



STP2202ABGA

June 1998

DSC

DATA SHEET

Dual Processor System Controller

DESCRIPTION

The STP2202BGA is the Dual Processor System Controller, also referred to as DSC, used in a low-cost high-performing two-processor system. DSC's primary functions are to provide data coherence control, memory control, datapaths control, flow control, transaction ordering, and address routing. It regulates the flow of requests and data on the system's "UPA" interconnect based on dual cache coherent tags for each of the two processors.

FEATURES

- Performs as a centralized system controller.
- Implements four ports on two UPA buses; two for the processors, one for the UPA to SBus interface (U2S) and one for the Fast Frame Buffer (FFB).
- Can also be configured with just one processor.
- Schedules the crossbar switch and controls the flow on the UPA data buses.
- It can support up to sixteen 60ns SPARCstation™ 20 type DRAM SIMMs, each with capacities of 16MB, 32MB, 64MB, or 128MB. This can support a total 2GB of system memory.
- Coordinates interrupt and reset inputs from Reset, Interrupt and Clock (RIC) and distributes them to the other system components.
- Provides an 8-bit EBus interface to allow read/write of the DSC's internal registers.
- Operates at a maximum frequency of 100 MHz (10 ns cycle time).
- Includes a JTAG interface for full chip scan during system tests.
- Contains a Phase-Locked-Loop (PLL) to remove skew introduced by the internal clock distribution network.

STP2202ABGA

DSC
Dual Processor System Controller

RELATED PRODUCTS

Name	Description	STP Part No.
APC	Audio Controller	STP2024QFP
CPU Module	UltraSPARC Module	STP5110
DTAG	Dual Tag Synchronous SRAM	N/A
Ecache	2nd Level High Speed Data and Tag Cache	N/A
FEPS	High Performance Master System I/O Controller	STP2002QFP
RIC	Reset/Interrupt/Clock Controller	STP2210QFP
SlavIO	Slave System I/O Controller	STP2001QFP
UDB	UltraSPARC-I Data Buffer	STP1080BGA
UltraSPARC-I	High Performance 64-Bit RISC Processor	STP1030BGA
U2S	UPA-to-SBus Interface	STP2220BGA
XB1	Crossbar Switch	STP2230SOP

FUNCTIONAL DESCRIPTION

System

The system units (see Typical System Configuration) typically interface with the DSC as follows:

UltraSPARC Modules (STP5110)

The processors are essentially isolated from the rest of the system except system memory, and communicate with the DSC through their ports on UPA Address Bus 0. The major functions the DSC provides for the processors are Port control, System Memory Path control, and issuance of necessary resets. Using the Snoop Bus, the DSC monitors a duplicate set of the UPA Address Bus 0 Port tags, and maintains order during coherent operations.

U2S (STP2220)

The U2S interfaces with the DSC through the I/O Data Bus and the UPA Address Bus 1. It is treated just like another client, and has no other special communication with the DSC.

FEPS (STP2002)

FEPS is Fast Ethernet Parallel port SCSI. It provides the following I/O devices: 10/100 Mb/sec Ethernet, 20 Mb/sec Fast SCSI and a standard parallel port.

SlavIO (STP2001)

SlavIO provides most of the SUNness I/O requirements. It contains serial ports, floppy, keyboard/mouse and EBus control. Since the DSC contains no data path, the 8-bit EBus, controlled by the SlavIO chip, is used by the processor(s) to read/write internal registers of the DSC.

XB1 (STP2230SOP)

The three port crossbar interconnects a 144-bit (128 + 16 ECC) UPA data bus accessed by two processors, a 72-bit (64 + 8 ECC) UPA data bus accessed by the U2S and the FFB, and a 288-bit wide memory bus. There is a 2 port switch (CBT) between 288-bit memory bus and 576-bit SIMM data. The crossbar and system memory access are controlled by the DSC.

Cross Bar Technology Sus Switch (CBT)

The CBT switch is a 2 port switch between a 576 bit memory bus (SIMM side) and a 288 bit data bus (XB1 side). To maintain a manageable pin count, the devices are sliced so that 18 parts are needed to form the complete switch function. The CBT switch part number is: TI SN74CBT16233.

Fast Frame Buffer (FFB)

On-board graphics interfaces with the system through an output only UPA64S graphics port. The FFB is always the slave, with the DSC the master. UPA Address Bus 1 is used to supply address information, The UPA I/O Data Bus is the output path for the graphics data.

RIC (STP2210)

The RIC's main function for the DSC is the import of reset status from system power on, pushbutton, or keyboard resets.

DTAG

Dual Tag SRAM attached to DSC's coherency controller, which keeps a copy of each processor's tags.

Note: The U2P and UIO could replace the U2S and SlavIO, respectively, if the system utilizes PCI buses.

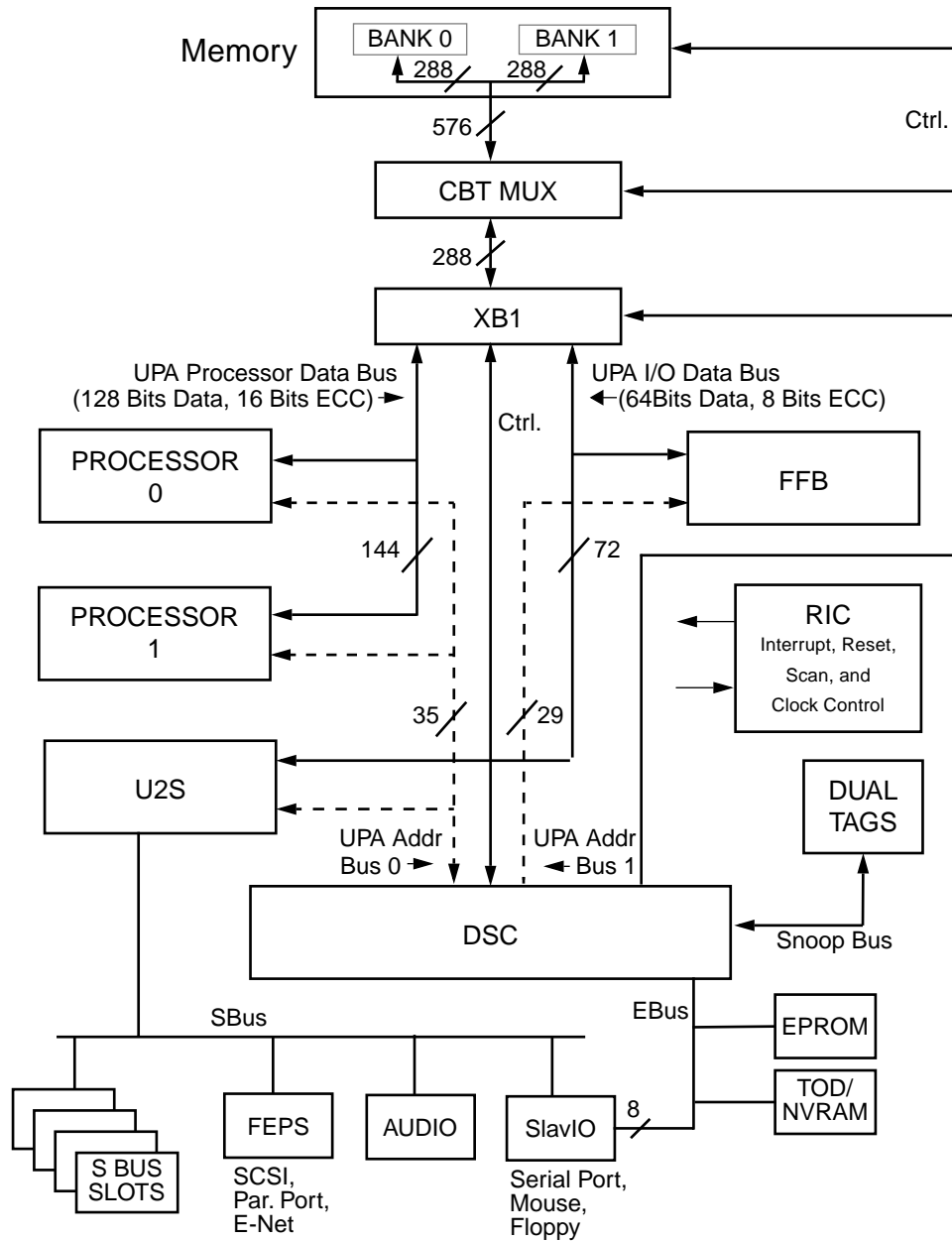


Figure 1. Typical System Configuration

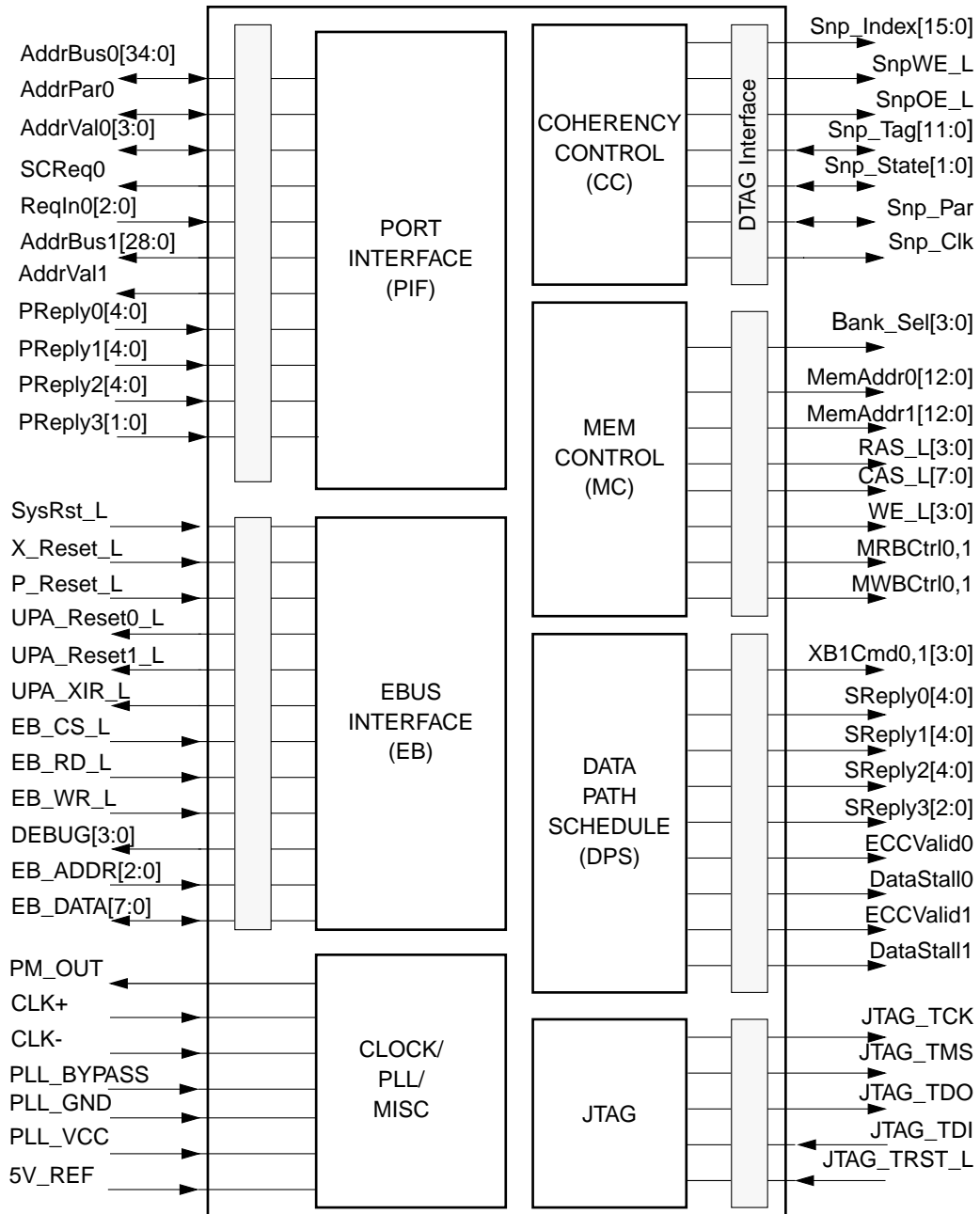


Figure 2. DSC Block Diagram

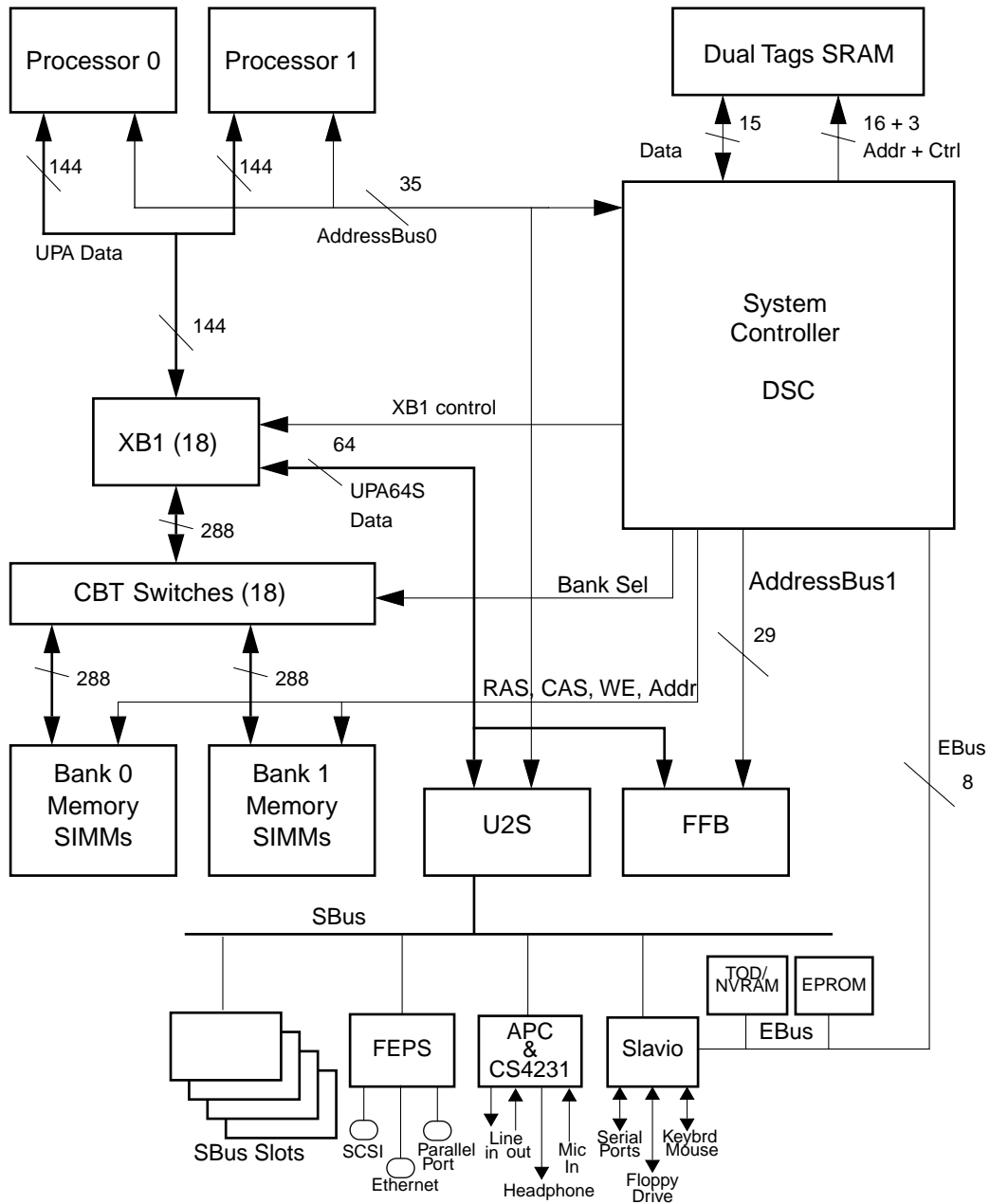


Figure 3. DSC in 2 Way MP System

FUNCTIONAL BLOCKS

DSC is divided into five major blocks:

1. Port Interface (PIF)
2. Datapath Scheduler (DPS)
3. Memory Controller (MC)
4. Coherency Controller(CC)
5. EBus Interface (EB)

Their functions are described in further detail in the following sections.

Port Interface (PIF)

The PIF supports two UPA busses. It is responsible for receiving packets, decoding their destinations, and forwarding packets to the proper destinations. Cached transactions are typically forwarded to the Memory Controller. Non-cached transactions are typically forwarded to the proper slave.

UPA address bus 0 has three UPA ports. Each Processor and the U2S can act as either a UPA master or a slave.

UPA address bus 1 implements the UPA64S subset only. It supports only a single graphics slave. This bus is output only, not bidirectional, and DSC is always the master of this bus. In addition, the graphics slave will only generate and receive truncated PReply and SReply signals.

PIF controls the arbitration on UPA address bus 0. There are three other masters on this bus, the two processors and U2S. PIF uses a distributed round robin algorithm as described in the "UPA Interconnect Architecture" document.

PIF also receives all PReplies from UPA clients.

PIF contains four sets of the following registers (one for each UPA port):

1. SC_Port_Config registers.
2. SC_Port_Status registers.

These registers are described in further detail in the "DSC User's Manual" document. Part No. 950-2117-01

Datapath Scheduler (DPS)

The DPS is responsible for regulating the flow of data throughout the system. It generates the following:

1. BMX commands for XB1 crossbar switch.
2. S_REPLYs for all clients.
3. UPA_DATASTALL signals.
4. UPA_ECCVALID signals.

DPS contains no software visible registers.

Memory Controller (MC)

MC is responsible for controlling the SIMMs. It performs the following functions.

1. Generates timing for read, write, and refresh.
2. Converts the physical address in the UPA packet into row and column addresses.
3. Maintains refresh timer.
4. Controls loading and unloading of data from the XB1 read and write buffers.
5. Controls the memory switch CBT (FET multiplexer) selects.

PIF forwards memory requests to the MC. MC communicates with the DPS to schedule delivery of data.

The operation of MC and the memory subsystem is described in further detail in the "DSC User's Manual" document, Part No. 950-2117-01.

Coherency Controller (CC)

The CC is responsible for maintaining cache coherency at the system level. A copy of each processors tags is kept in "Dual Tag" RAM that is connected to the CC. The CC checks the Dual tags or "snoops" on all of the cacheable transactions. From this snoop it can determine the appropriate response. The operation of the Coherency Controller is further described in the "DSC User's Manual" document.

EBus Interface (EB)

EB implements an interface to EBus, an asynchronous 8-bit interface controlled by Slavio. Since DSC contains no data path, all reading and writing of internal registers has to take place via EBus. Since all internal registers are 32 bits wide, EB has to perform packing and unpacking.

EB is the only block which can be used in both USC and DSC with minimal change.

The EB block implements reset logic.

The EB block contains a number of global registers.

1. SC_Control register for controlling resets and logging reset status.
2. SC_ID register, which contains DSC's JEDEC ID number, implementation and version numbers, and the number of UPA ports that this chip supports.
3. Performance counters: SC_Perf_Ctrl, SC_Perf1, and SC_Perf2. These counters can be configured to count various events for performance analysis.

The global registers are described in further detail in the "DSC User's Manual" document.

The operation of EB is described in further detail in the "DSC User's Manual" document.

Performance Monitors

The DSC has a small block that contains logic to monitor performance. Performance registers can be read after being set up by programming the SC_Perf_Ctrl register. These registers are defined in the "DSC User's Manual". These registers are accessed through the EBus.

JTAG Interface

The DSC has a JTAG interface. This interface block is common to the system ASICs and ports the signal set used for debugging purposes.

UPA Interface Signals

Signal Name	Pin Count	I/O	Buffer Type	Description
UPA_ADDRBUS0<34:0>	35	I/O	Holding amp.	Address bus 0, 2 processors and the U2S
UPA_ADDRBUS1<28:0>	29	O		Address bus 1, UPA64S (FFB), slave only
UPA_ADDRPAR0	1	I/O	Holding amp.	Parity (bit 35) for address bus 0
UPA_ADDRVAL0[2:0]	3	I/O	Holding amp.	[0] = processor 0, [1] = processor 1, [2] = U2S
UPA_ADDRVAL1	1	O		Address valid for UPA64S
UPA_DATASTALL0	1	O		Stall data to processors
UPA_DATASTALL1	1	O		Stall data to U2S
UPA_ECCVALID0	1	O		ECC valid for processors
UPA_ECCVALID1	1	O		ECC valid for U2S
UPA_PREPLY0<4:0>	5	I		Port replies from processor 0
UPA_PREPLY1<4:0>	5	I		Port replies from processor 1
UPA_PREPLY2<4:0>	5	I		Port replies from U2S
UPA_PREPLY3<1:0>	2	I		Port replies from UPA64S
UPA_REQIN0<2:0>	3	I		Client address bus 0 arbitration requests: [0] = processor 0, [1] = processor 1, [2] = U2S
UPA_RESET0_L	1	O		Reset for processors, tied to U2S's UPA_ARBRESET_L
UPA_RESET1_L	1	O		Reset for U2S and FFB
UPA_SCREQ0	1	O		DSC request for address bus 0
UPA_SREPLY0<4:0>	5	O		System replies for processor 0
UPA_SREPLY1<4:0>	5	O		System replies for processor 1
UPA_SREPLY2<4:0>	5	O		System replies for U2S
UPA_SREPLY3<2:0>	3	O		System replies for UPA64S
UPA_XIR_L	1	O		XIR reset for processor(s). Only processor(s) are disrupted.
Total UPA Outputs:	95			
Total UPA Port Interface signals:	115			

Dual Tag Interface Signals

Signal Name	Pin Count	I/O	Buffer Type	Description
SNPCLK	1	O		Snoop Clock
SNP_INDEX[15:0]	16	O		Snoop RAM address
SNPOE_L	1	O		Snoop RAM Output Enable
SNPPAR	1	I/O		Snoop RAM Parity
SNPSTATE[1:0]	2	I/O		Snoop Tag States
SNPTAG[11:0]	12	I/O		Snoop Tags
SNPWE_L	1	O		Snoop RAM Write Enable
Total Output Signals	34			

Memory Interface Signals

Signal Name	Pin Count	I/O	Buffer Type	Description
BANK_SEL[3:0]	4	O		Bank Select
CAS_L<7:0>	8	O		Column Address Strobe
MEMADDR0<12:0>	13	O		Row/Column Address
MEMADDR1<12:0>	13	O		Row/Column Address
RAS_L<3:0>	4	O		Row Address Strobe
WE_L[3:0]	4	O		Write Enable
Total Output Signals	46			
Total Memory Interface	46			

XB1 Interface Signals

Signal Name	Pin Count	I/O	Buffer Type	Description
BMXCMD0[3:0]	4	O		Command to XB1; bits 0-3 decode 16 command types
BMXCMD1[3:0]	4	O		Duplicate of BMXCMD0
MRBCTRL0	1	O		XB1 Read Buffer Control
MRBCTRL1	1	O		Duplicate of MRBCTRL0
MWBCTRL0	1	O		XB1 Write Buffer Control
MWBCTRL1	1	O		Duplicate of MWBCTRL0
Total Output Signals	12			
Total XB1 Interface	12			

EBus Interface Signals

Signal Name	Pin Count	I/O	Buffer Type	Description
EBUS_ADDR<2:0>	3	I	5V tolerant	EBus address
EBUS_CS_L	1	I	5V tolerant	Chip select for DSC on EBus
EBUS_DATA<7:0>	8	I/O	5V tolerant	Data in and out pins - TTL levels
EBUS_RD_L	1	I	5V tolerant	Read enable on EBus
EBUS_WR_L	1	I	5V tolerant	Write enable on EBus
Total, EBus Outputs	8			Low frequency outputs
Total, EBus Interface Signals	14			

Miscellaneous Signals

Signal Name	Pin Count	I/O	Buffer Type	Description
5V_REF	1	I		5V reference for 5V tolerant inputs
CLK	1	I	PECL	System Clock (differential)
CLK_L	1	I	PECL	System Clock (differential)
DEBUG<3:0>	4	O		External view of internal signals
JTAG_TCK	1	I	5V tolerant	Scan clock
JTAG_TDI	1	I	5V tolerant	Test data input
JTAG_TDO	1	O		Test data output
JTAG_TMS	1	I	5V tolerant	Test mode select
JTAG_TRST_L	1	I	5V tolerant	Reset TAP controller
PLL_BYPASS	1	I		Bypass internal Phase-Locked-Loop
PLL_GND	1	I		Ground for PLL
PLL_VCC	1	I		VDD for PLL
P_RESET_L	1	I	5V tolerant	POR Button
SYS_RESET_L	1	I	5V tolerant	Power on reset
X_RESET_L	1	I	5V tolerant	XIR Button Reset
PM_OUT	1	O		Process Monitor Output*
Total Misc. Outputs	6			
Total Misc. Signals	19			

* Note: Manufacturing Use Only

Power and Ground

Signal Name	Pin Count	I/O	Note	Description
VDD	38			+3.3V
VSS	38			Ground
Total Power and Ground	76			

Total Pin Count

Signal Group	Total Signals
UPA Port Interfaces	115
Dual Tag Interface	34
Memory Interface	46
BMX Interface	12
EBus Interface	14
Miscellaneous	19
Total SC Signals	240
Power & Gnd	76
Spares	4
SC Total	320

UPA BUS TIMING


All UPA transactions supported by DSC are described in Chapter 5 of the DSC User's Manual. The following diagrams show the timings of those transactions. The transactions can be divided into two groups: Non-cached transactions and Coherent transactions.

Noncached transactions include:

Interrupt from P0
Noncached Block Read, P1 to U2S
Non Cached Block Read, P0 to P1
Non Cached Block Read, P1 to FFB
Noncached Block Read, U2S to P0
Noncached Block Write, from P0
Noncached Read, P0 to U2S
Noncached Write, from P0.

Coherent transactions include:

Read to Discard, from U2S
Read to Discard, with Copy Back to Discard, from P0
Read to Own, with Copy Back Invalidate, from P0, P1
Read to Own, with Copy Back Invalidate, from U2S



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Read to Share, with Copy Back, from P1

Read to Share from P0, DTAG in Invalid State

Read to Share from P0, DTAG in Modified State

Read to Share from P0, DTAG in Owned State

Read to Share from P0, DTAG in Shared State

Read to Share from P0, With cancelled memory read

Four consecutive Read to Share from P0, DTAGS in I, S, O and M States

Write Back from P1

Write Back Invalidate from P1.

Figure 4. P_INT from P0

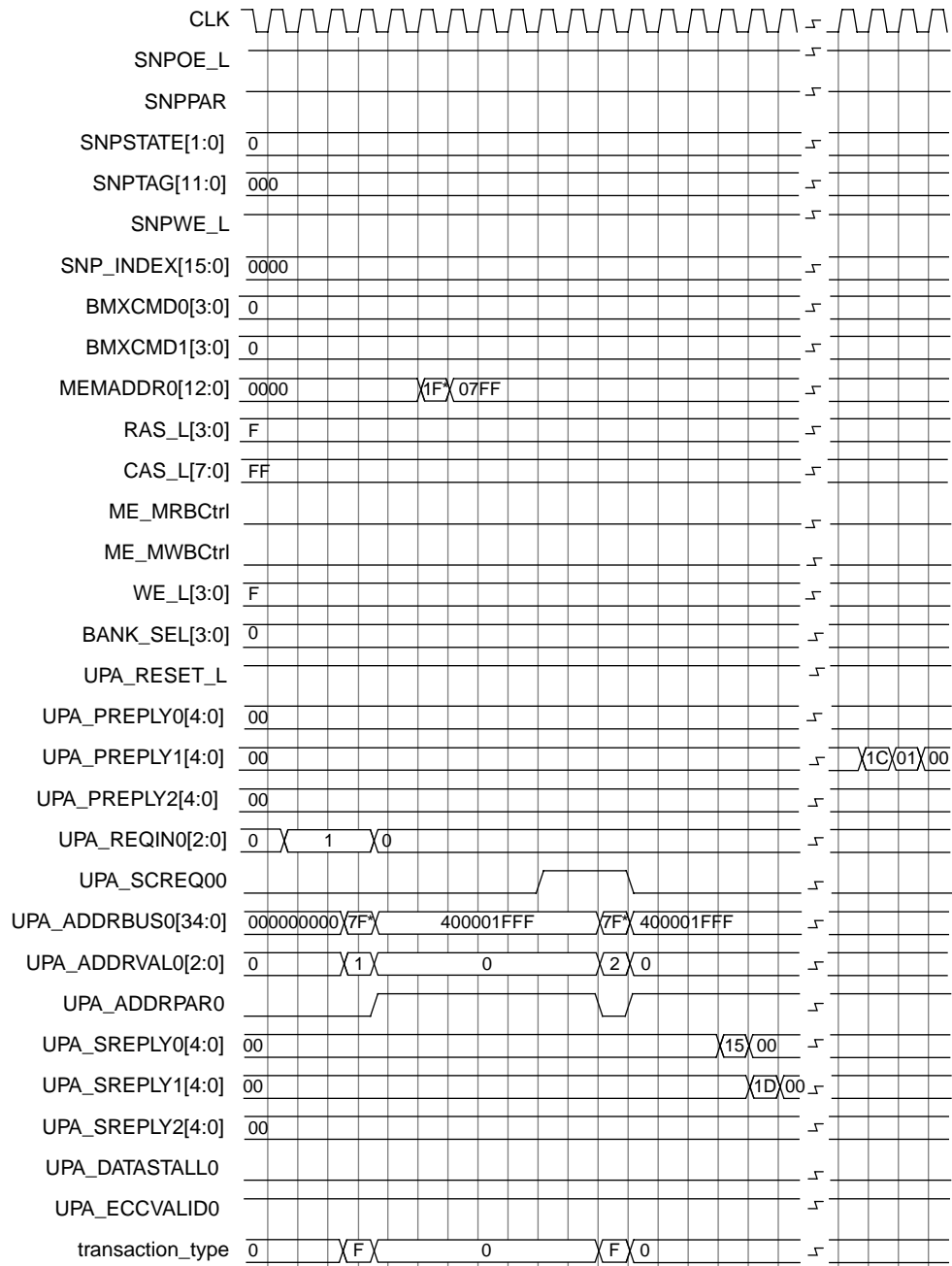


Figure 5. P_NCBRD, P1 to U2S

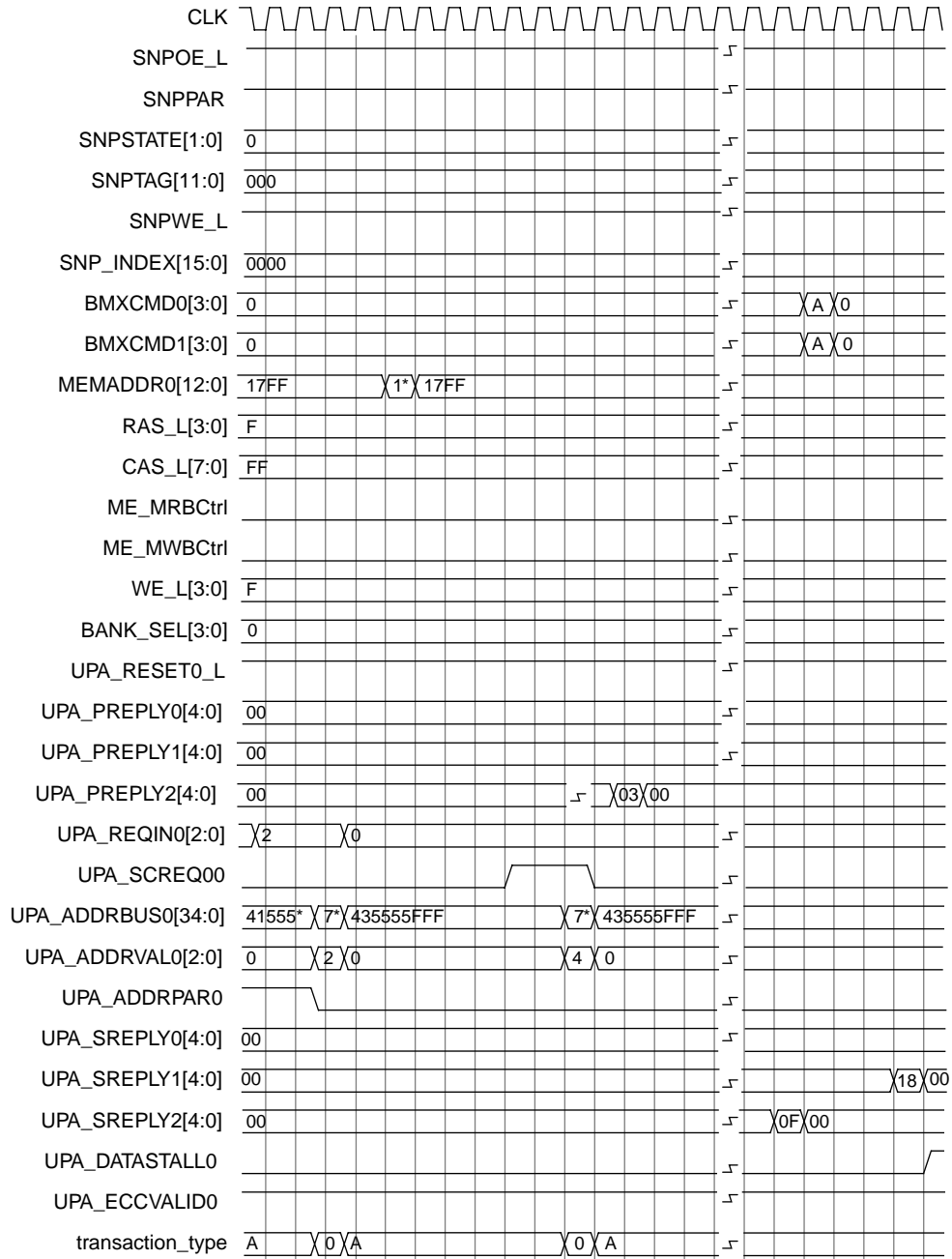


Figure 6. P_NCBRD, P0 to P1

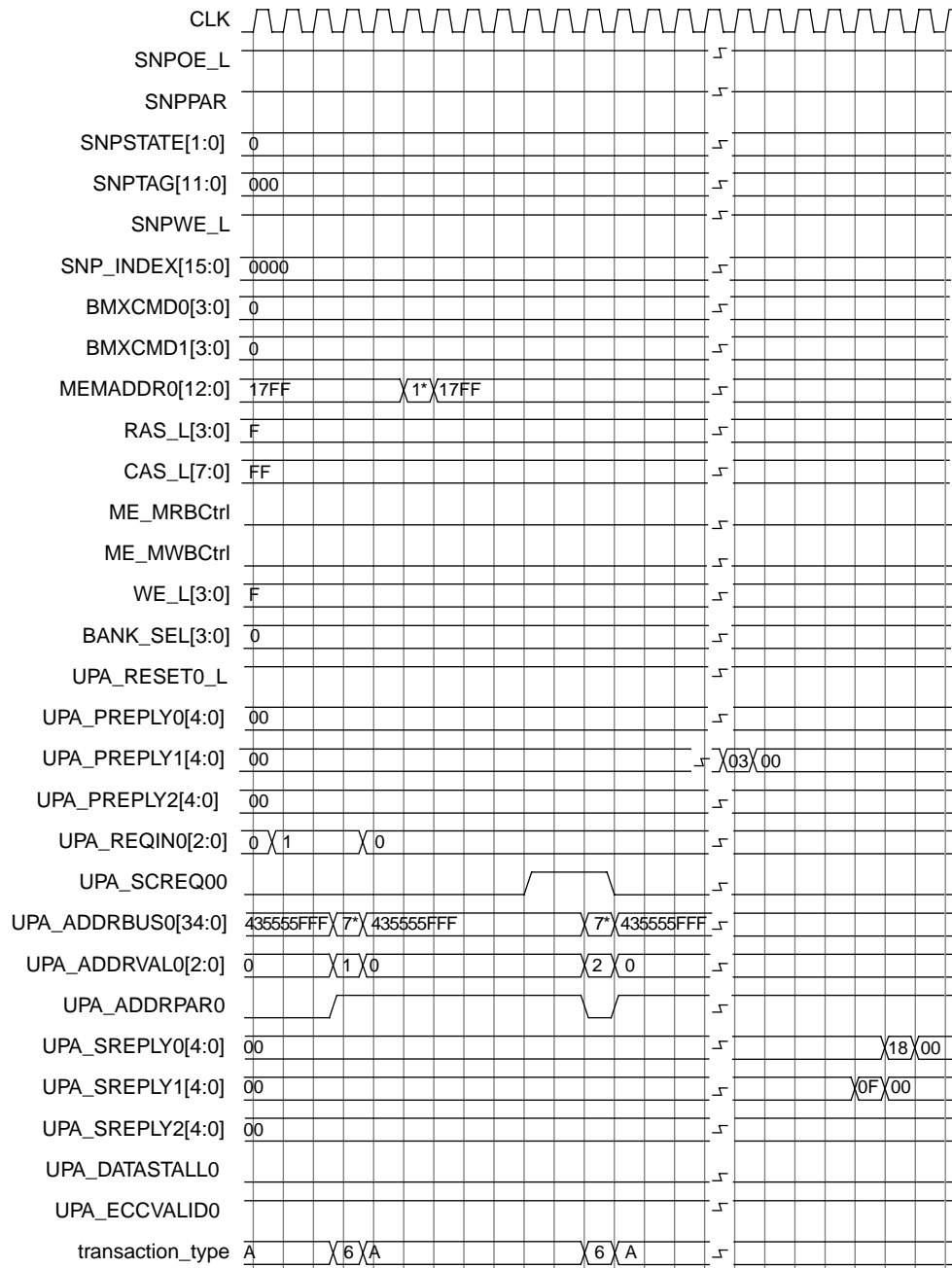


Figure 7. P_NCBRD, P1 to FFB

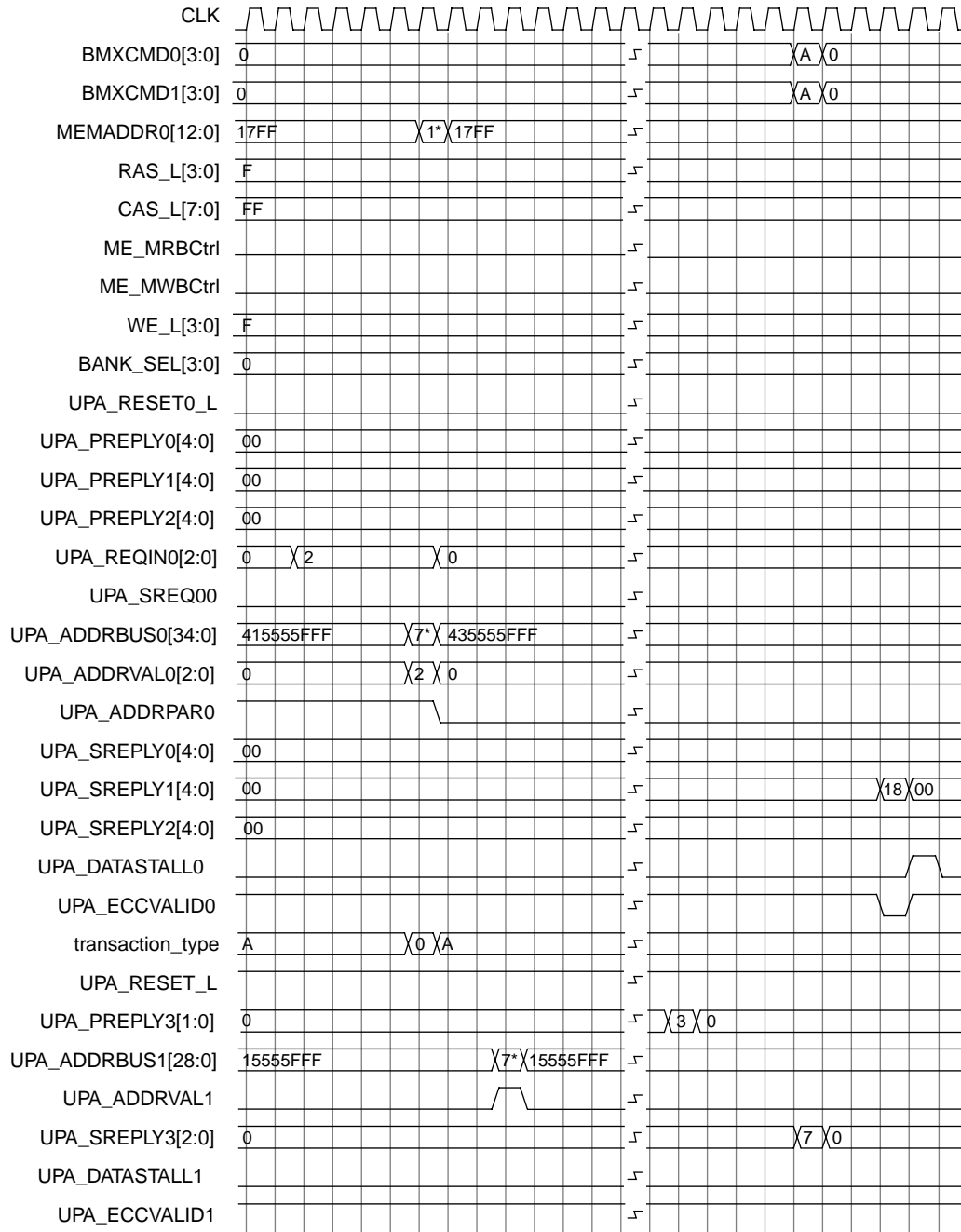


Figure 8. P_NCBRD, U2S to P0

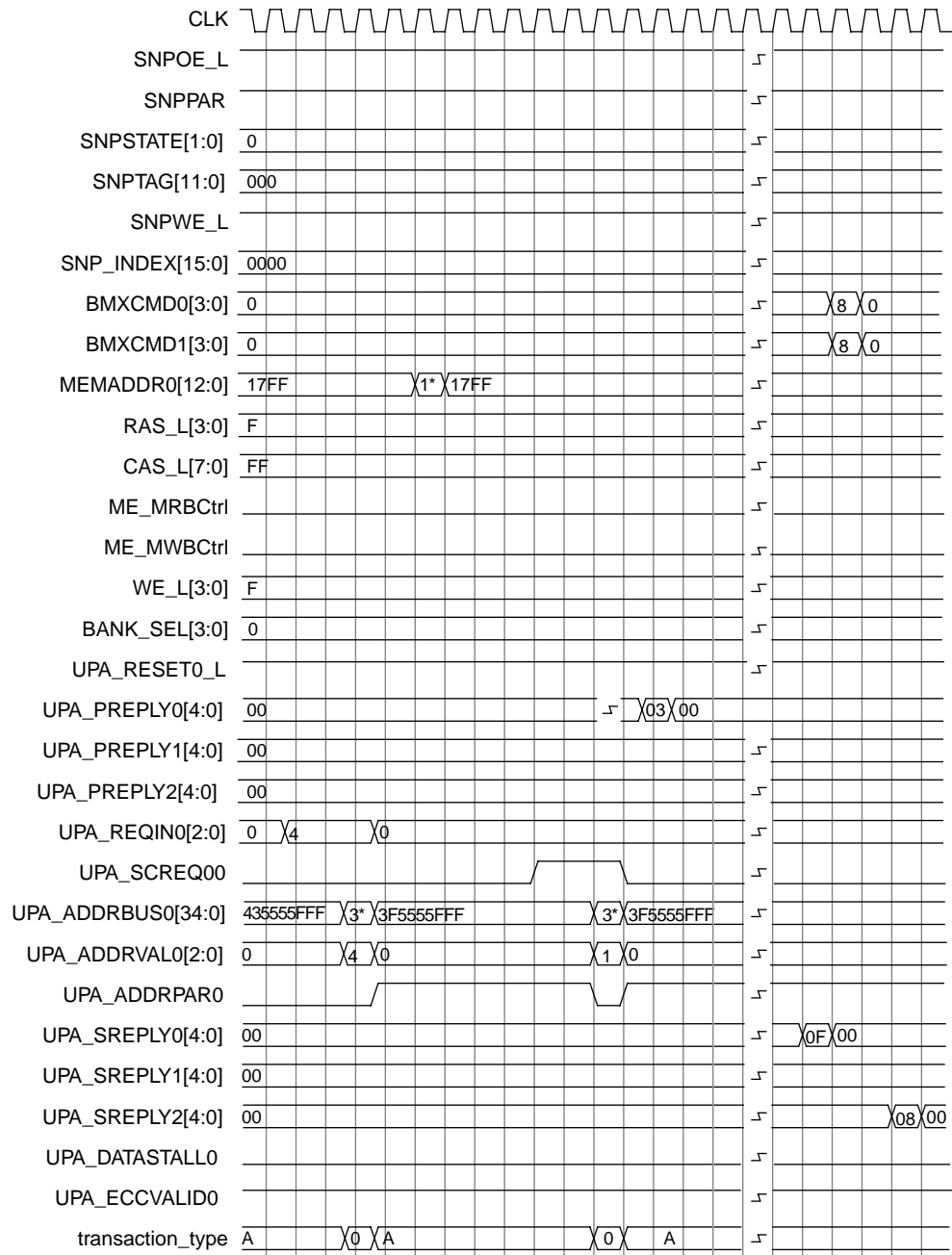


Figure 9. P_NCBWR from P0

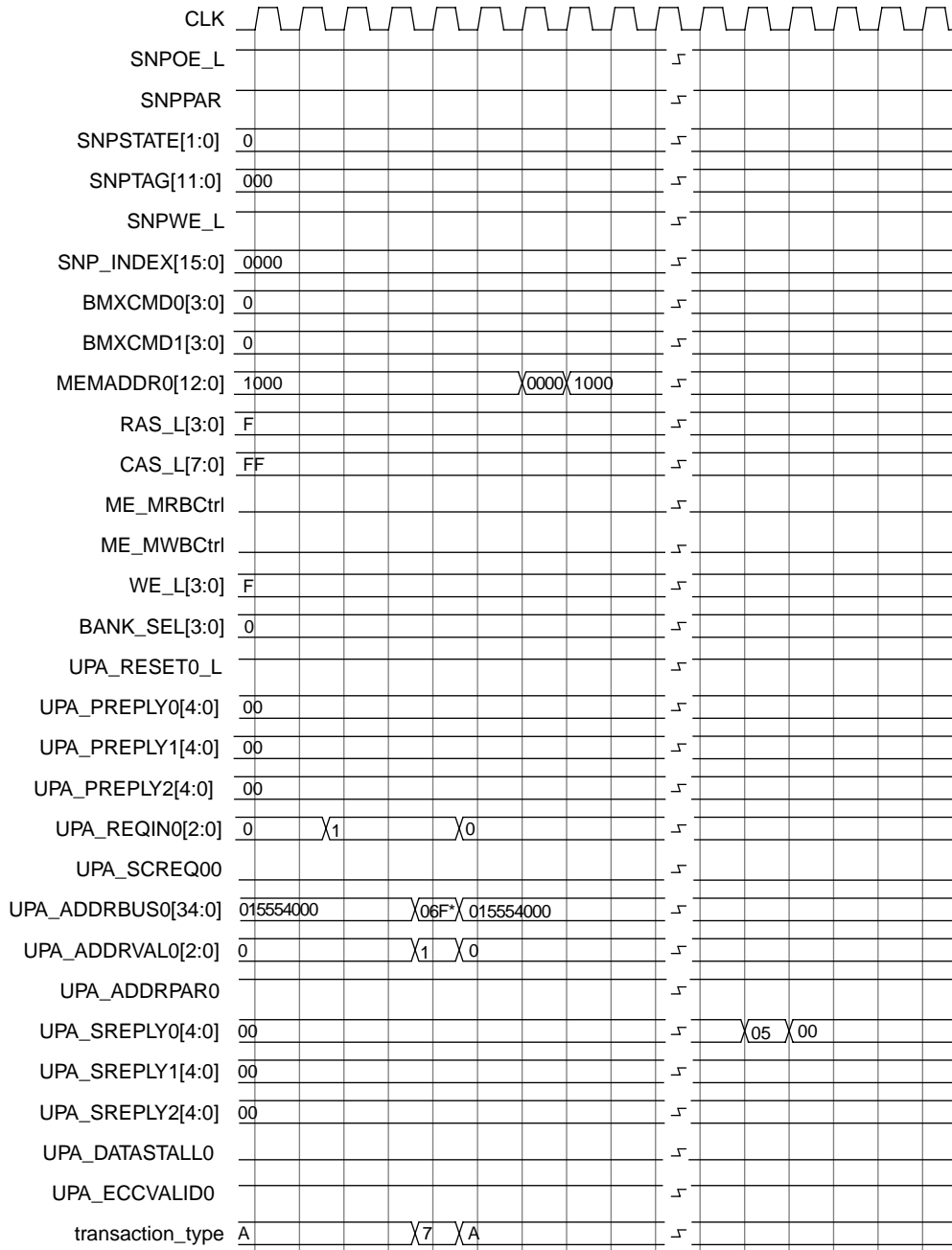


Figure 10. P_NCRD, P0 to U2S

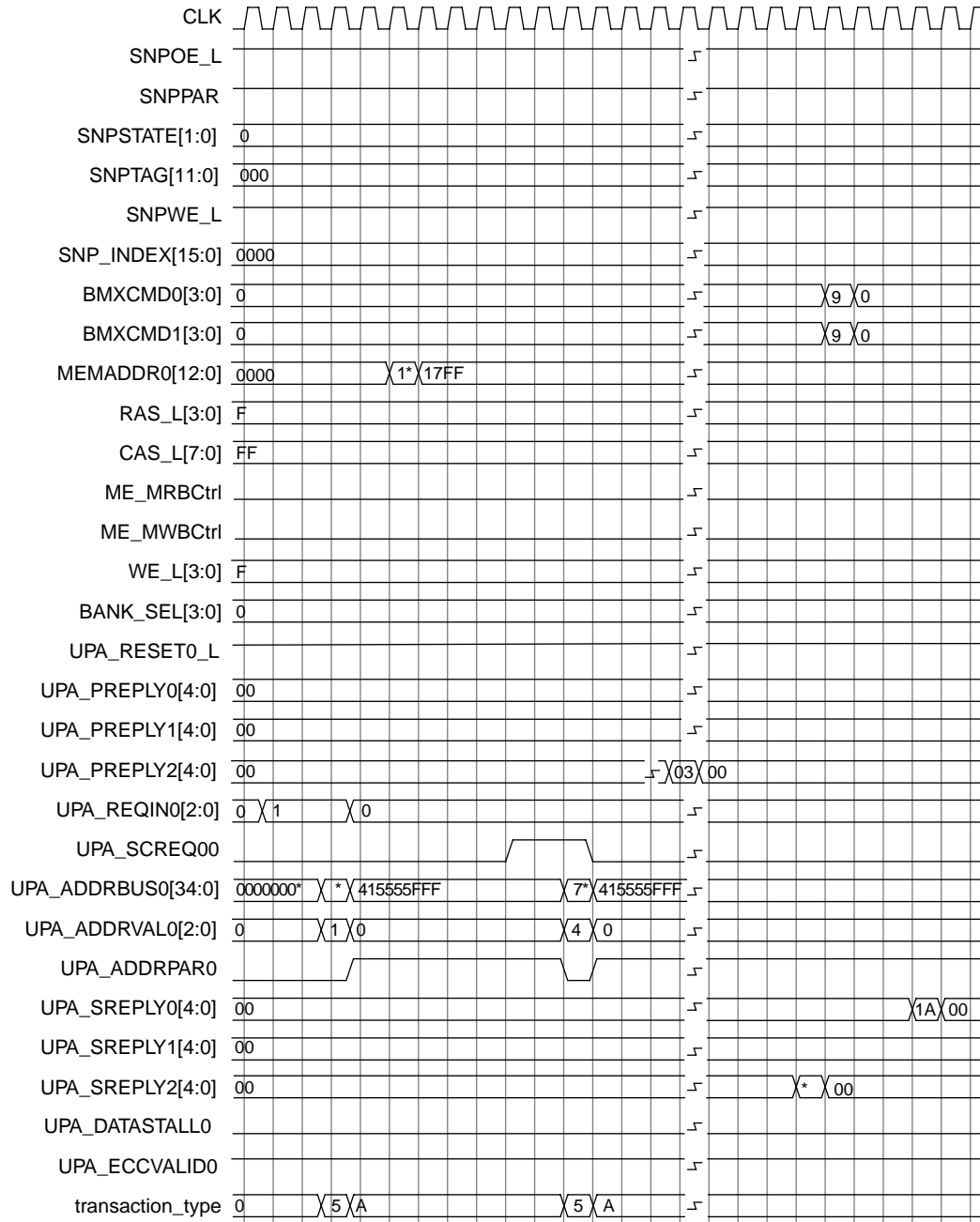


Figure 11. P_NCWR from P0

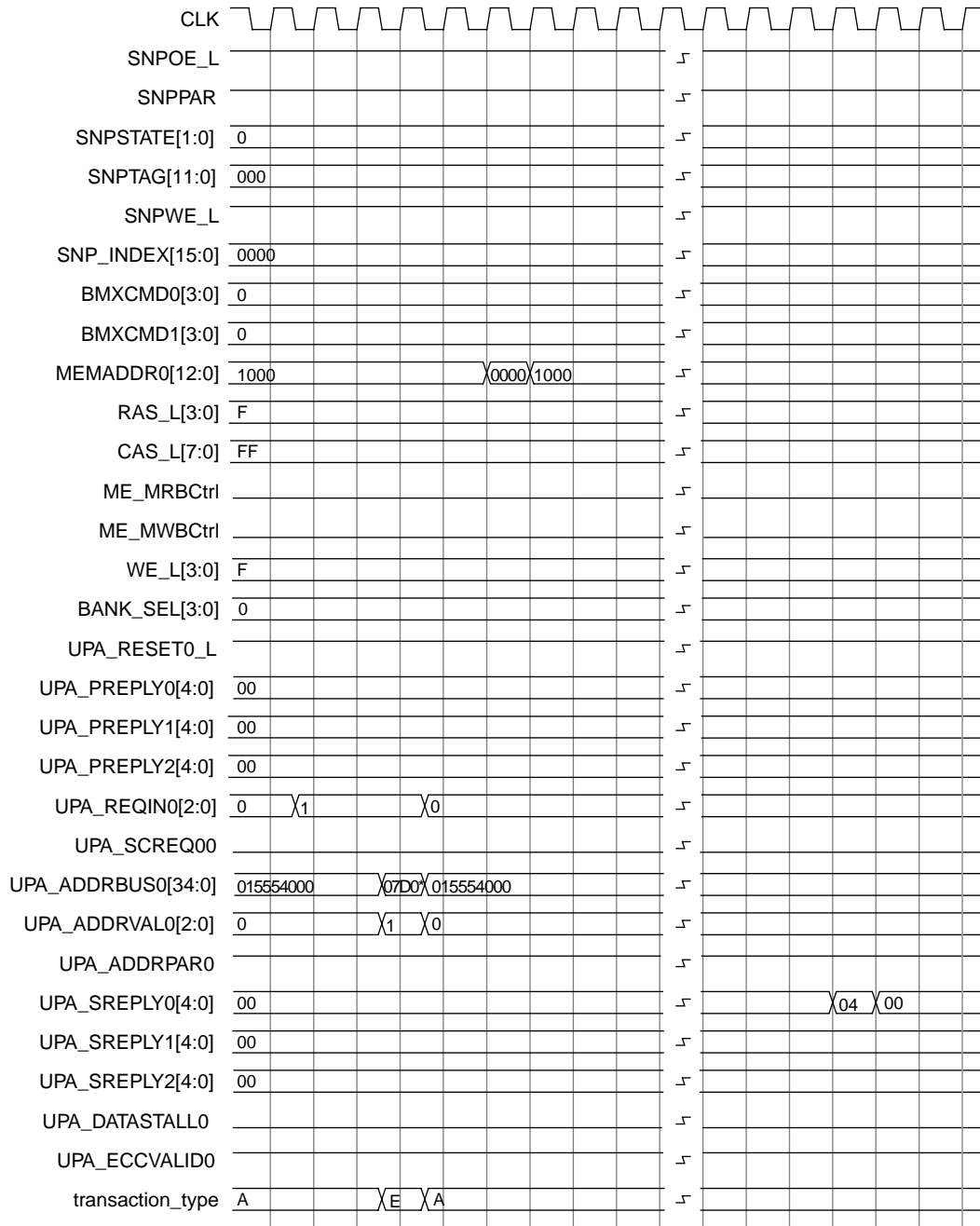


Figure 12. P_RDD from U2S

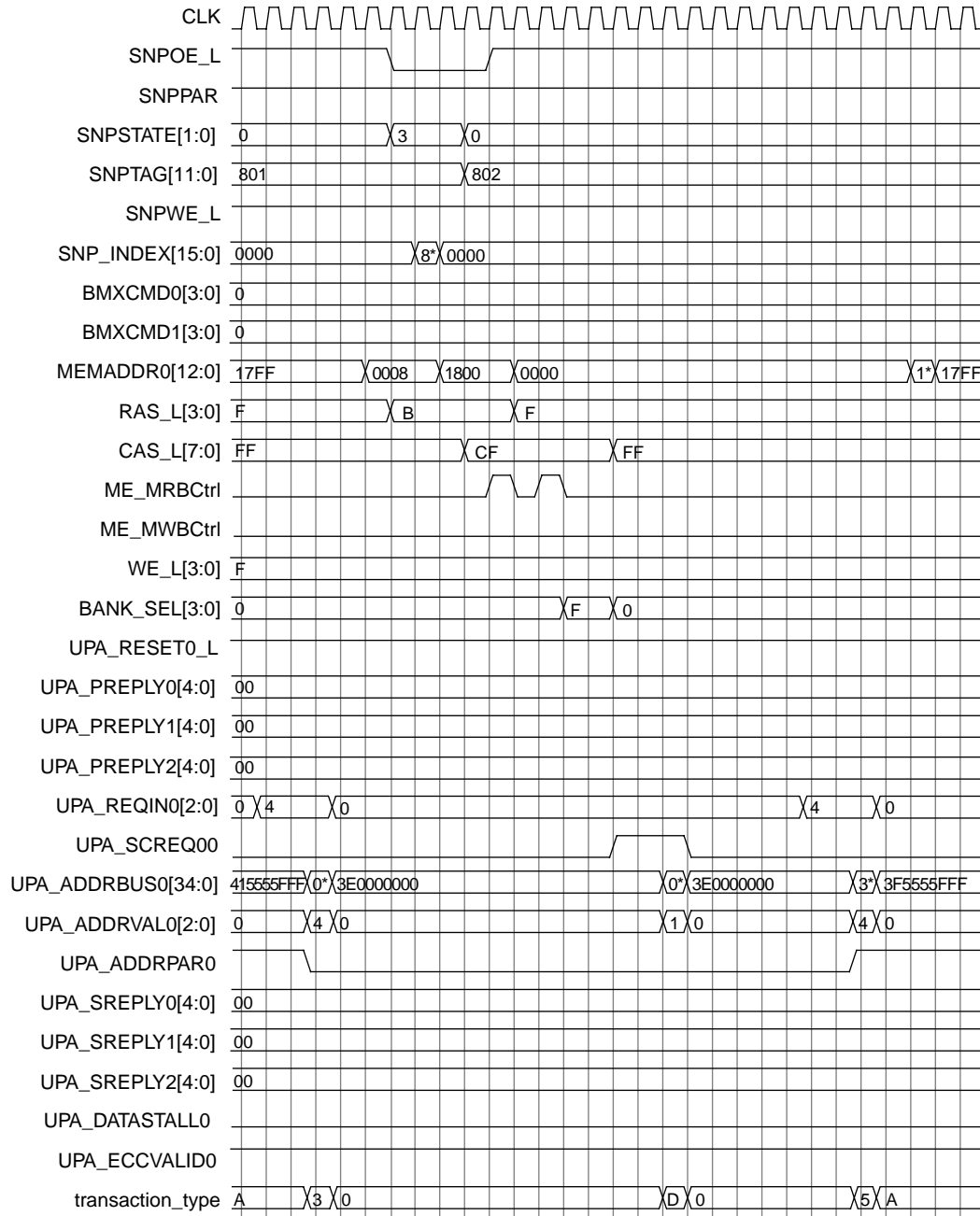


Figure 13. P_RDD from P0

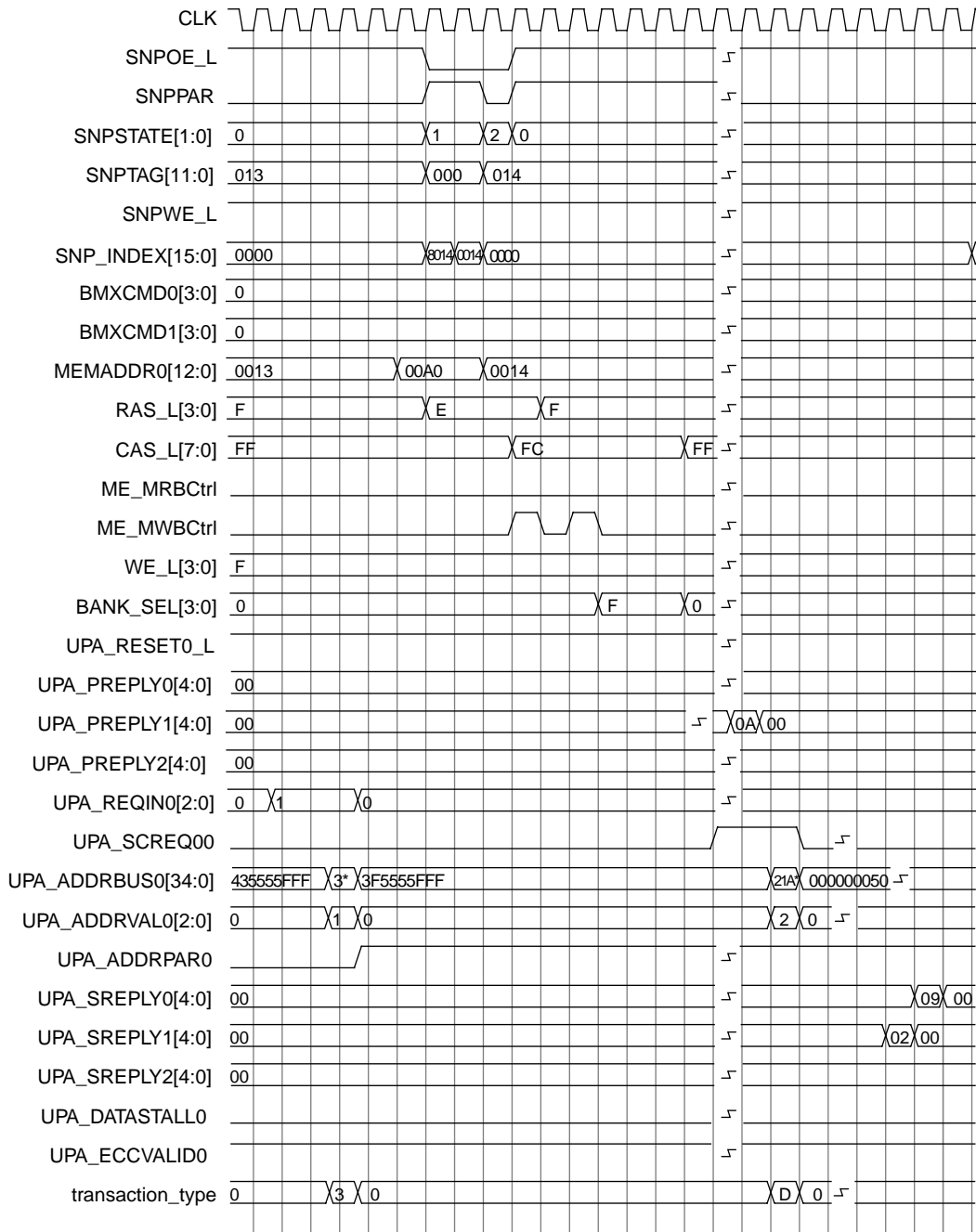


Figure 14. P_RDO from P0, P1

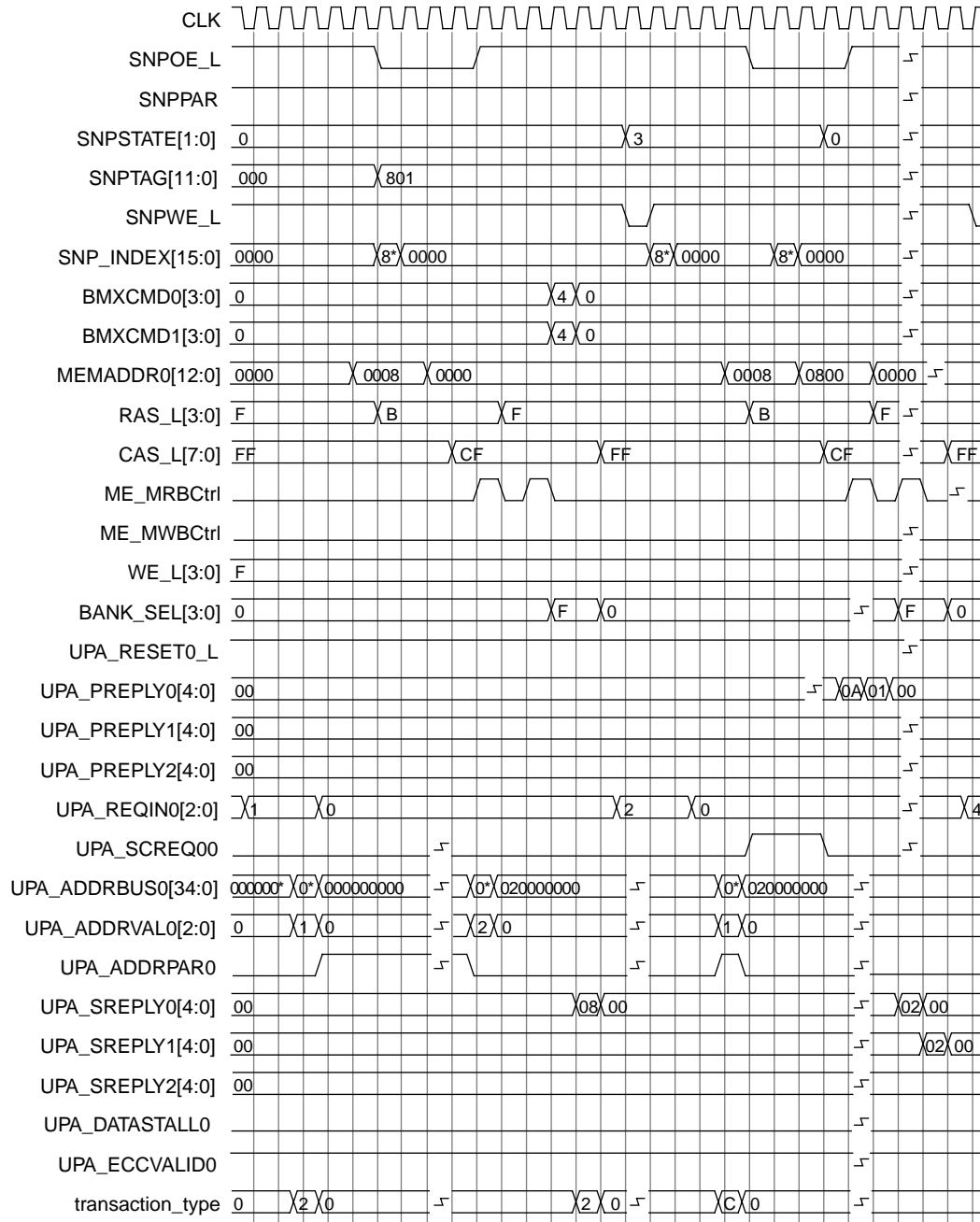


Figure 15. P_RDO from U2S

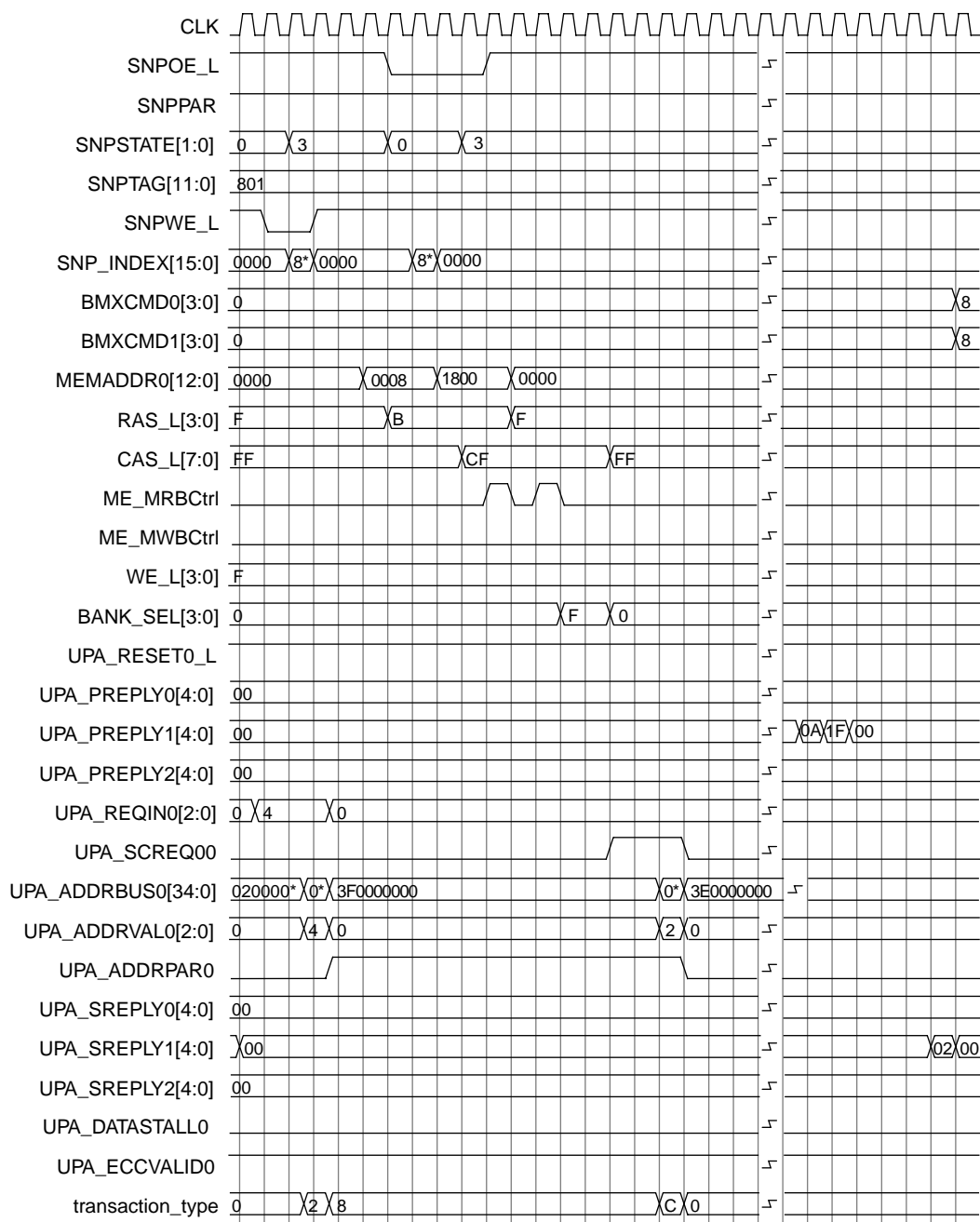


Figure 16. P_RDS from P1

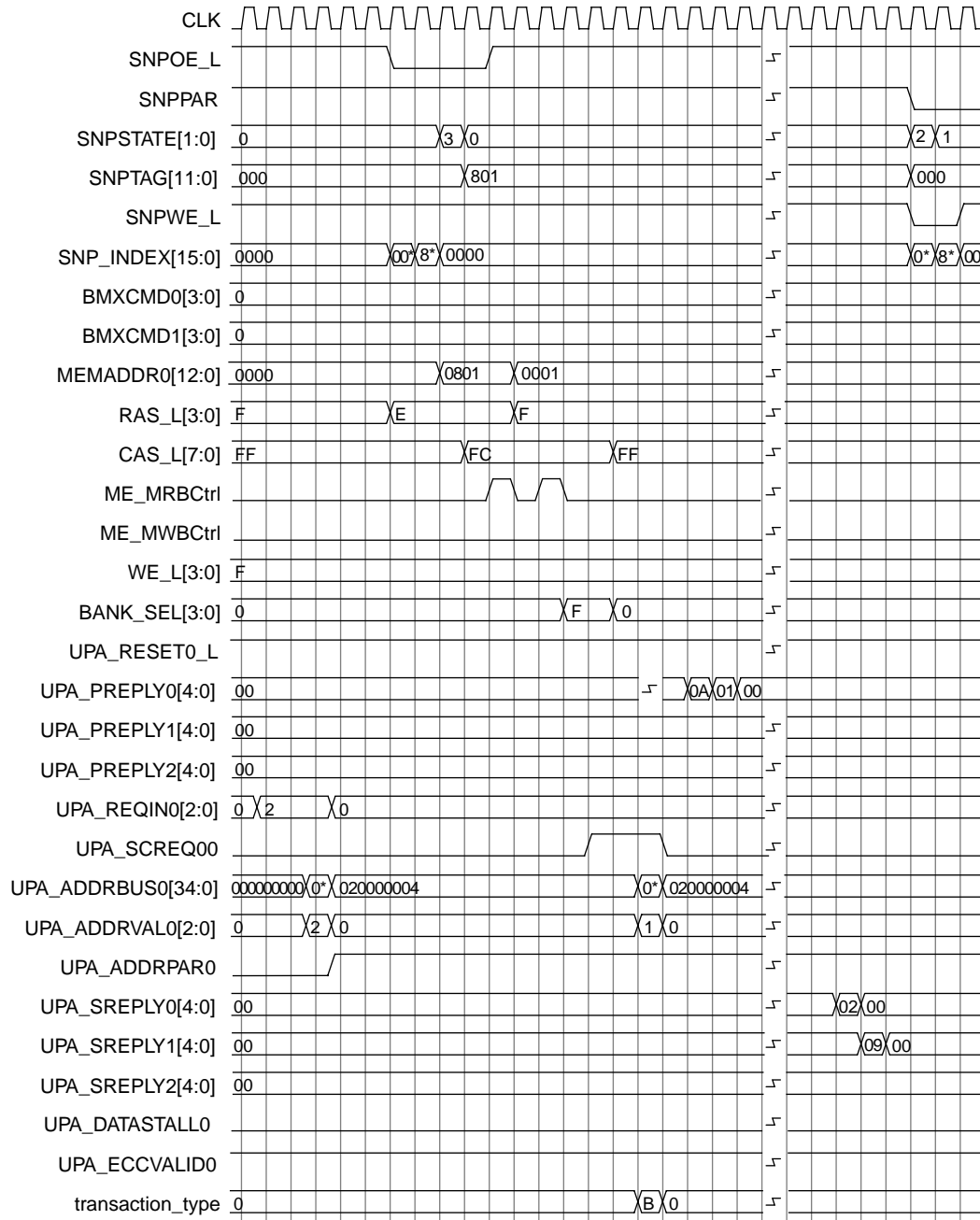


Figure 17. P_RDS from P0

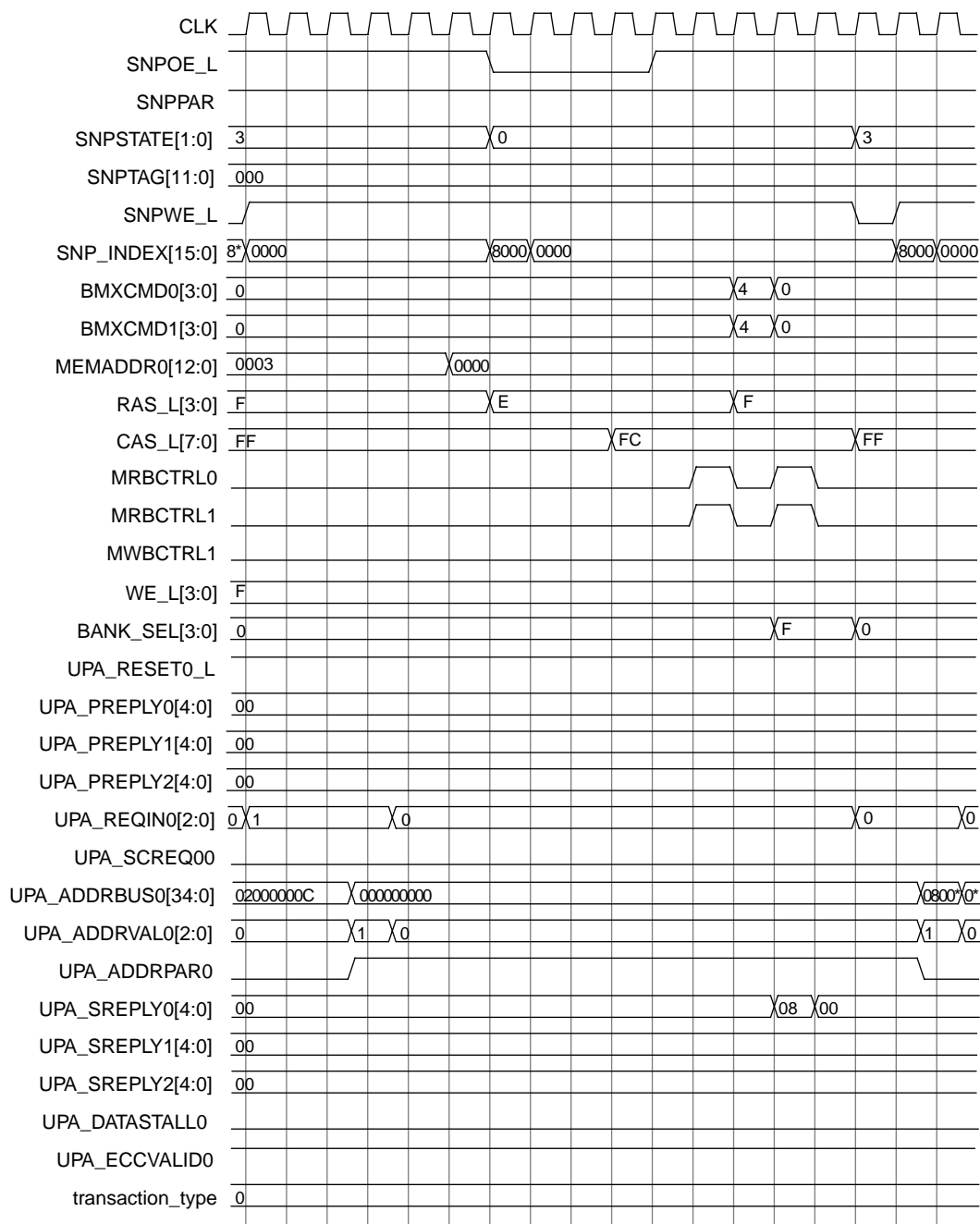


Figure 18. P_RDS from P0

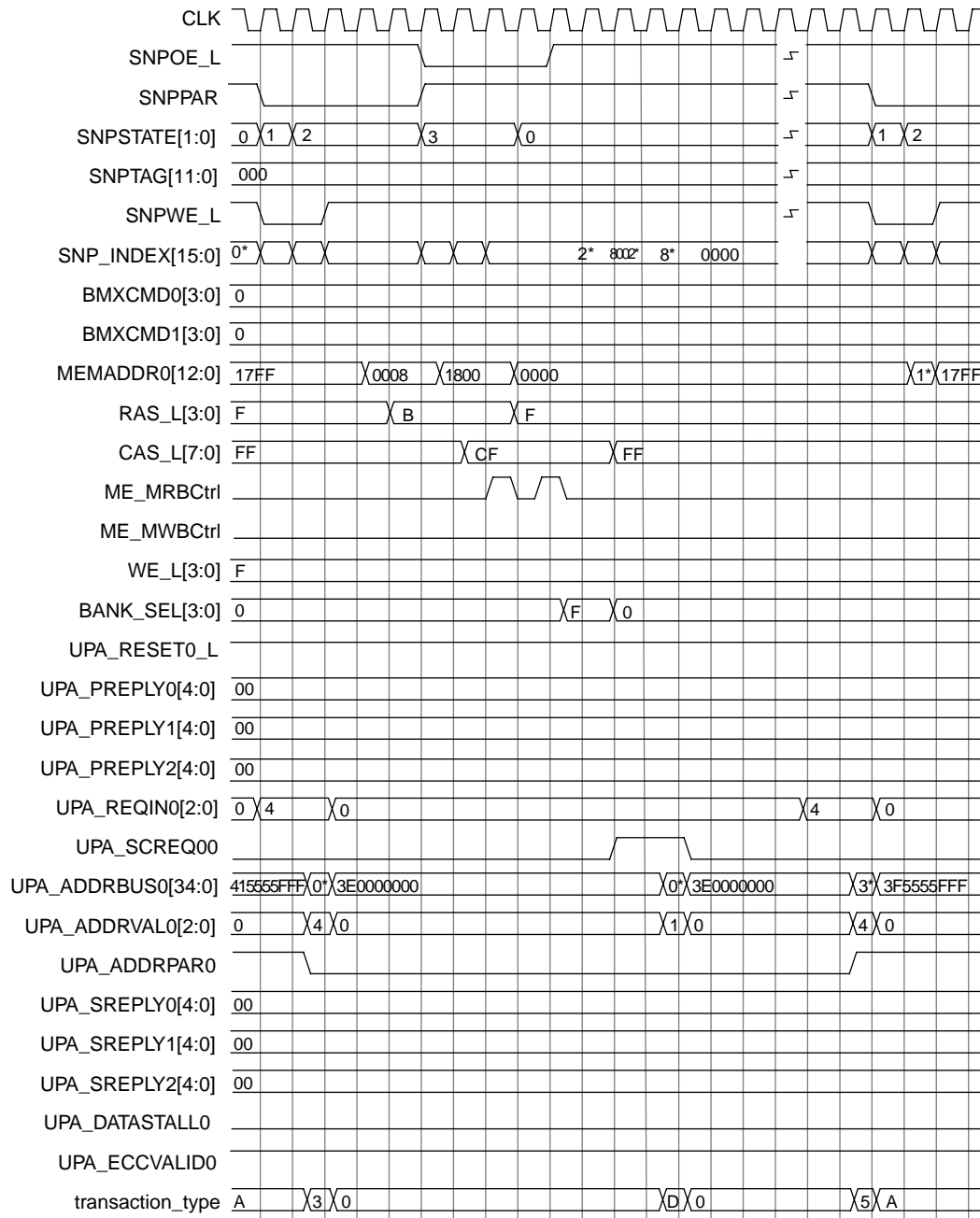


Figure 19. P_RDS from P0

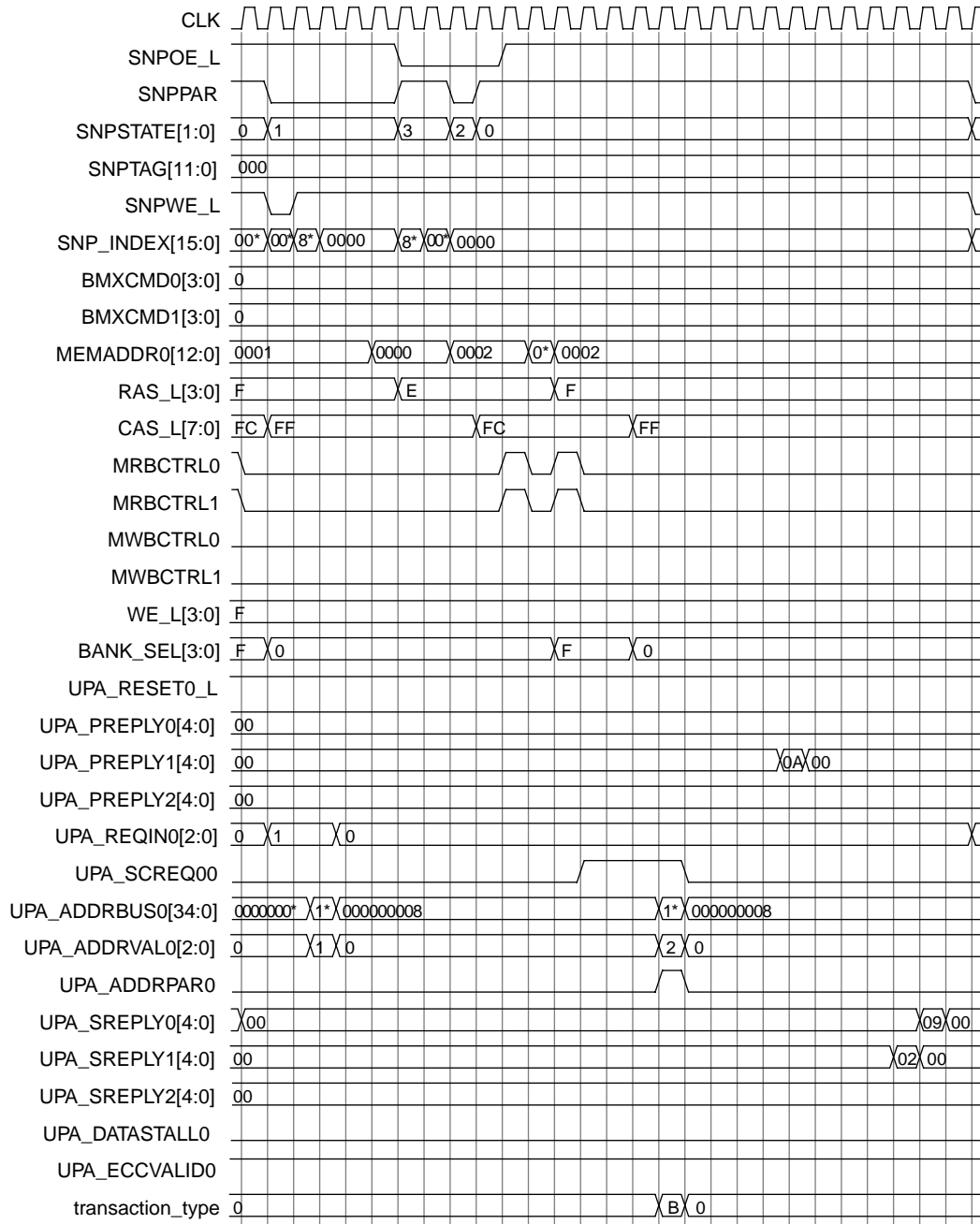


Figure 20. P_RDS from P0

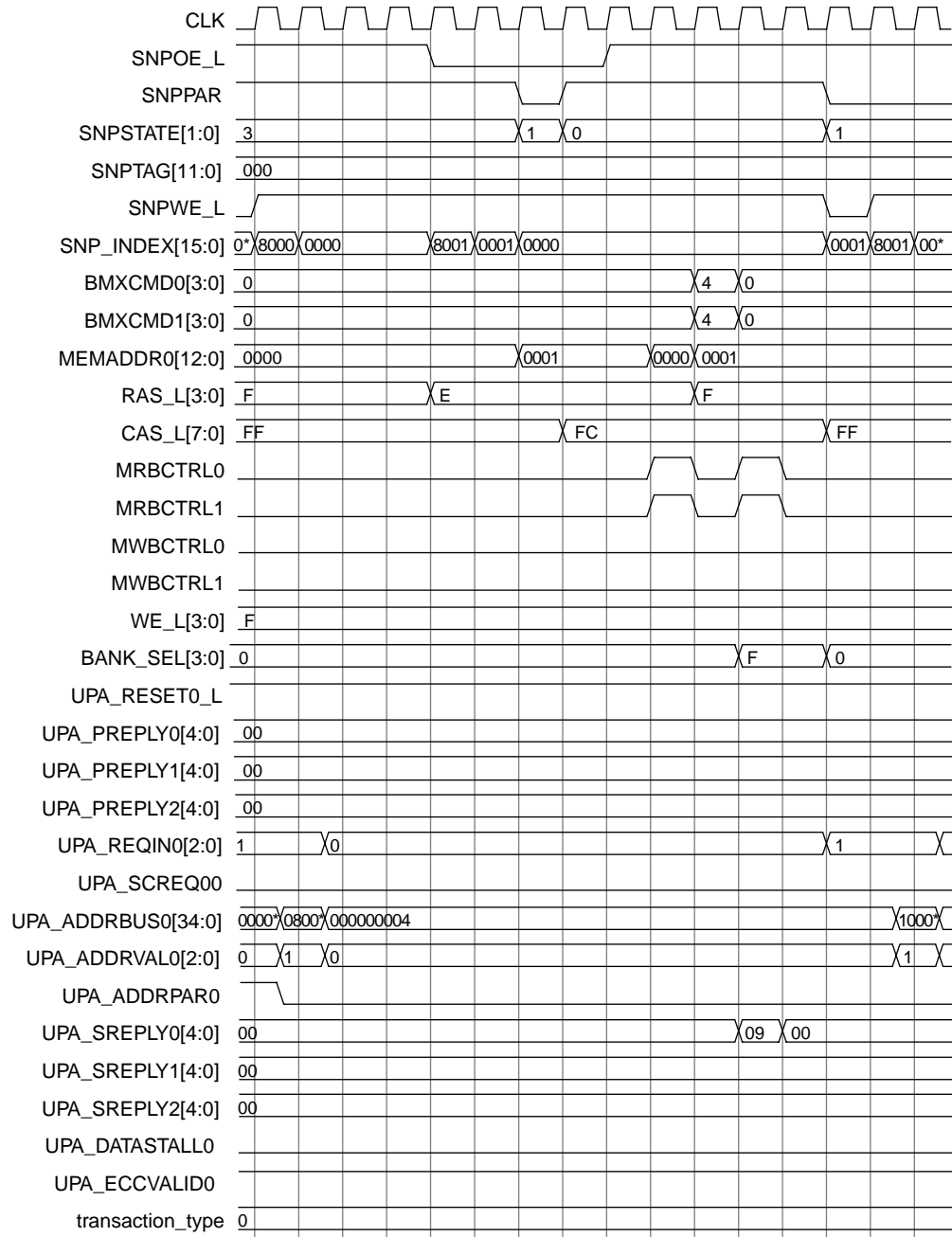


Figure 21. P_RDS from P0 with Cancelled Memory Read

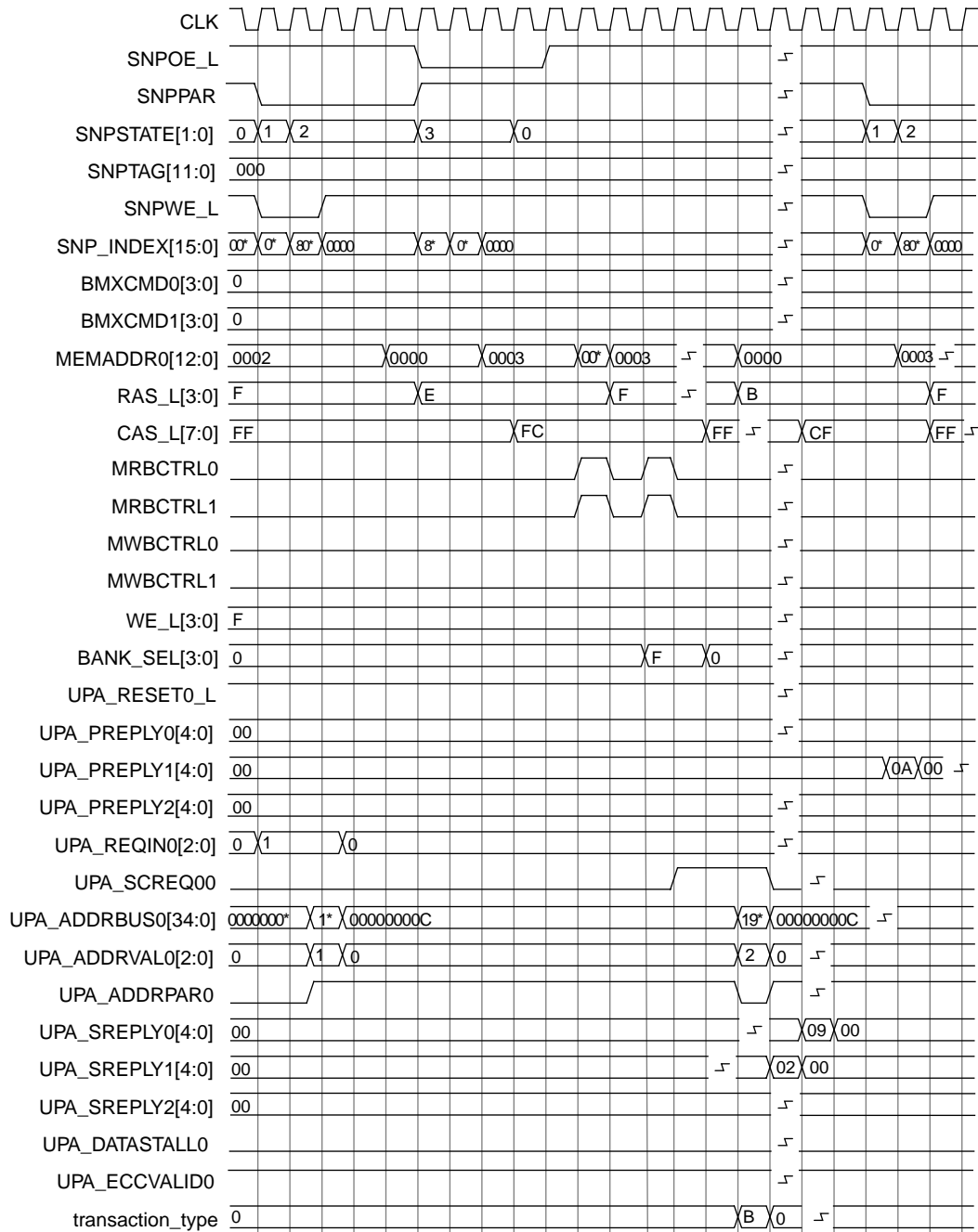


Figure 22. Four Consecutive P_RDS from P0

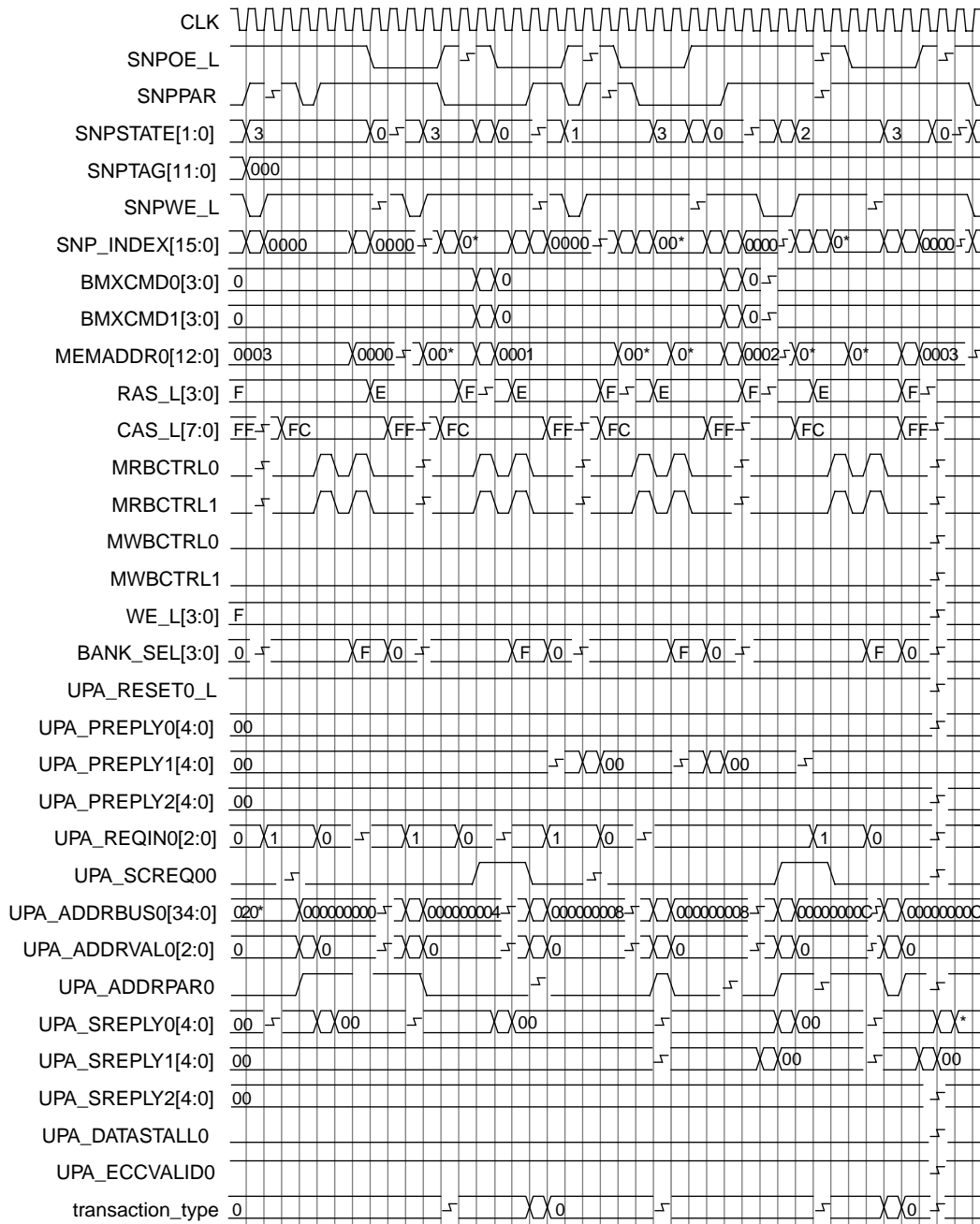


Figure 23. P_WRB from P1

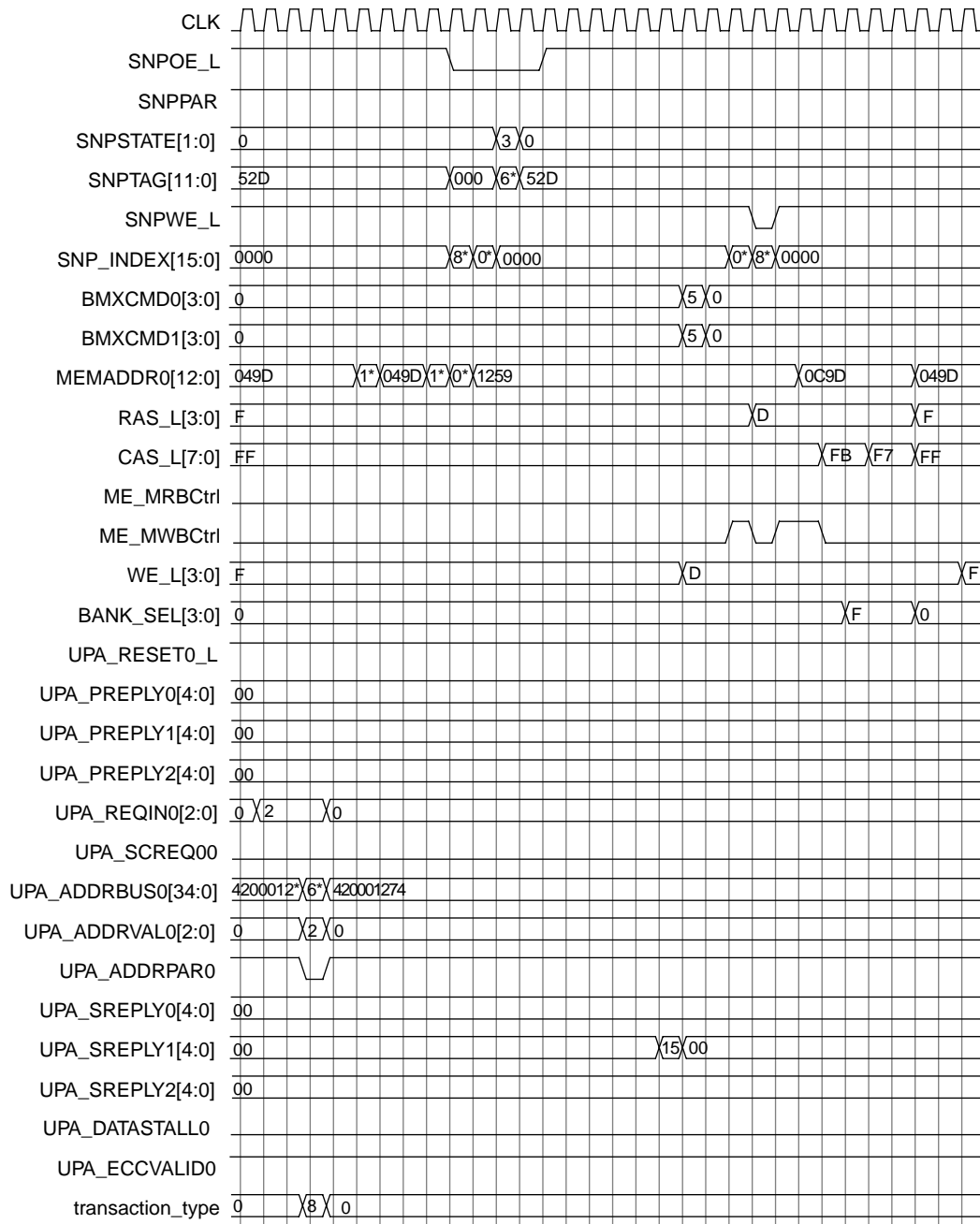
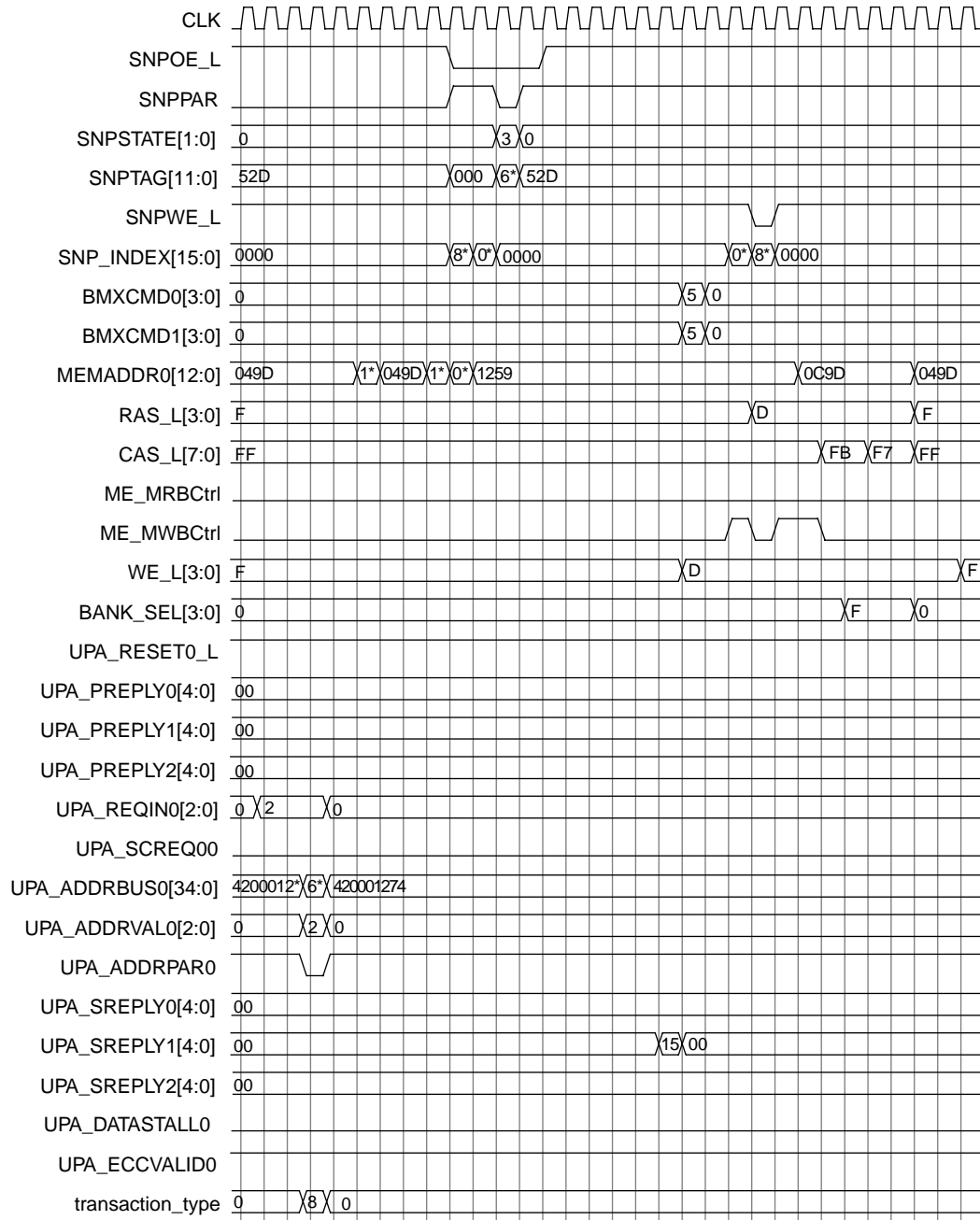


Figure 24. P_WRI from P1



Basic Memory Timing

Because the DSC is expected to operate under a wide range of clock frequencies, Memory Controller (MC) timing is programmable so that memory timing can be optimized for any given frequency. Memory refresh and access timing have been divided into a number of segments. Memory Control and Status Register 1 (MCSR1) contains seven fields which allow custom tailoring of any particular segment: WPC1, RCD, PC0, CP, PC1, RP, and $\overline{\text{RAS}}$. For a detailed description of these fields, refer to the programming model in the “DSC User’s Manual.”

The timing diagram in *Figure 25* shows a generic template for a read or write transaction, how it is broken down into segments, and the corresponding fields in MCSR1 which control that particular segment. Each individual segment is programmable to certain values.

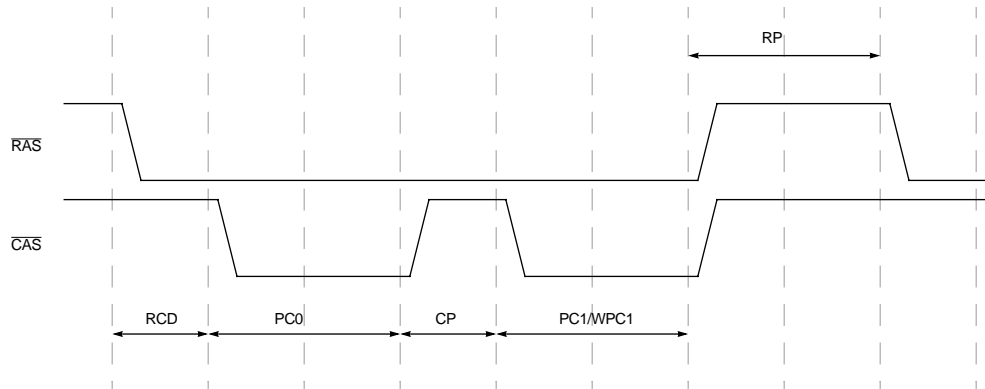


Figure 25. Basic Read/Write Timing

1. RCD is the $\overline{\text{RAS}}$ -to- $\overline{\text{CAS}}$ delay.
2. PC0 is the page cycle 0 time.
3. CP is the $\overline{\text{CAS}}$ -precharge time.
4. PC1 is the page cycle 1 time for a read operation.
5. WPC1 is the page cycle 1 time for a write operation.
6. RP is the $\overline{\text{RAS}}$ -precharge time.

Reads use RCD, PC0, CP, PC1, and RP. Writes only use RCD, CP, WPC1, and RP; PC0 is fixed.

The Timing in *Figure 26* shows a generic template for a refresh operation.

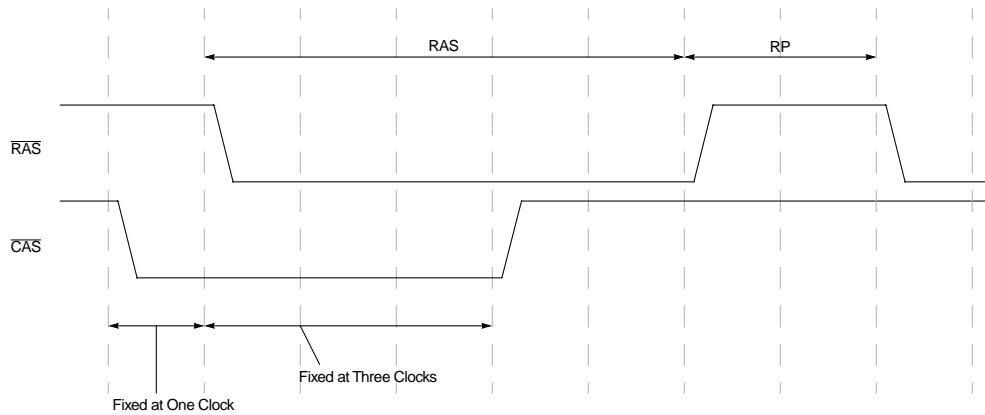


Figure 26. Basic Refresh Timing

1. $\overline{\text{RAS}}$ is the minimum $\overline{\text{RAS}}$ timing.
2. RP is the $\overline{\text{RAS}}$ -precharge timing.
3. CSR is the CAS to RAS assertion time.

UPA-to-Memory Timing

Figure 27 and Figure 28 show the minimum time for a UPA memory request packet issued on the UPA address bus pins to traverse the USC and appear on the USC's memory outputs, assuming that the USC is idle. RAS and MEMADDR have similar logic and board paths. This allows one clock of address setup times for Row Address.

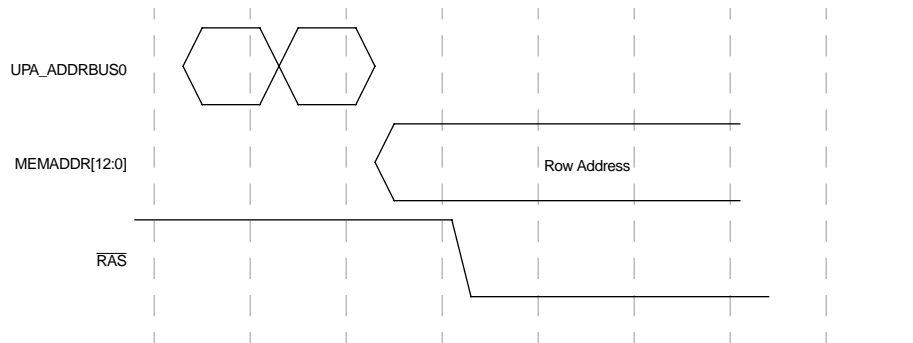
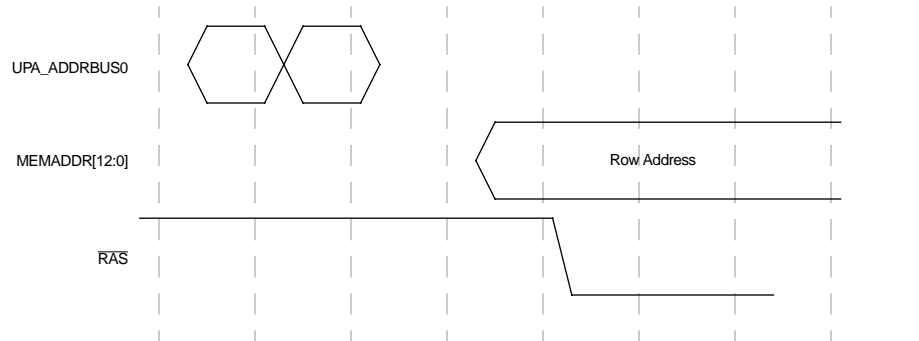


Figure 27. Best Case UPA-to-Memory Timing (Fast Path)

Figure 28. Best-Case UPA-to-Memory Timing (Normal Path)



Fast path timing is only applicable for memory reads issued from the processor. All other memory accesses use the normal path.

MEMORY ACCESS TIMINGS AND DESIGNER NOTES

This section shows read, write, and refresh timings for the default frequency of 83.3 MHz (12 ns) for accesses from both CPU and U2S. The main difference between the CPU and U2S accesses is that the CPU resides on a 128 bit wide data bus and U2S resides on a 64 bit wide data bus, so the data transfer timing is different.

The timing diagrams show best case idle timing. Care must be taken in interpreting these diagrams, since the timings shown here may not match exactly what might be seen during system operation. The reason is that the movement of data on the UPA busses and the movement of data on the memory bus is somewhat decoupled by the read and write buffers in the XB1 chips.

The signals can be divided into two groups. The first group consists of MEMADDR, RAS_L, CAS_L, WE_L, MRBCTRL, and MWBCTRL, which are all generated by the Memory Controller. Their timing relationships are invariant and will match what is shown in these diagrams except for those instances where a stretch might occur. The stretch points have been indicated. The second group consists of UPA_SREPLY, XB1CMD, and UPA_DATASTALL, which are all generated by the Datapath Scheduler. Their timing relationships are invariant and will match what is shown in these diagrams. However, the relationships between the two groups are not invariant; they will vary depending on whether the datapaths and DSC are idle or not, and whether it is a read or write transaction. The diagrams here only show what happens when everything is completely idle.

A precharge operation is performed between every memory access, regardless of whether the two accesses go to the same SIMM or to different SIMMs. The DSC MC does not leave SIMMs in page mode, however, it does overlap successive memory operations going to different SIMMs, hiding some of the precharge time in some cases. Back to back reads or back to back writes are separated only by the time which the different SIMM Groups share their common data bus, assuming that the requests can be issued quickly enough at the address bus, and the MC is not stalled with the Stretch Counter.

The DRAM cycle begins on the first programmed cycle and ends the cycle after the longest cycle programmed. For example, if the RAS generator is programmed to last 10 cycles, but the CAS generator is programmed for 14 cycles, then the DRAM cycle for that SIMM ends on the 15th cycle. The exact point at which the cycle actually starts is not possible to document. If the system is completely idle, and there are no refreshes occurring, then the cycle starts the next cycle after the PIF sends its request which could be imme-

diately after the UPA request or not. If there is a refresh occurring, then the refresh must finish before the request starts. If there are other transactions in progress, then there may be some dependencies as to when the operation can start depending on whether the request is for the same group of SIMMs or if the request is for a different group of SIMMs.

A question arises as to when cycles actually start and end. This is not an easy question to answer if you can only look at UPA transactions and DRAM array outputs. If you use the debug pins and output the internal Start signal in the MC then that defines the actual beginning of a cycle, but there is no reasonable way to document all the possibilities of when the DRAM cycle starts by only observing the UPA requests and DRAM outputs.

Another question arises as to how cancelled reads affect DRAM timing. They really do not affect reads. In the case of a cancel (due to the cc deciding to provide the data from the other processor's cache) the read from memory continues and is simply not used. The case seen in the lab, where the timing appeared to be a function of cancels was a bug which should be corrected as of this writing.

Notes on the following timing diagrams regarding stretch points, ping pong points and timer information.

1. The address must be asserted until cycle 5. As described in Chapter 4, Programming Model Section 4.3.5, "Memory Controller Registers," on page 4-45 of the DSC User's manual. The correct value to program PPRdCnt would be $5 - 2 = 3$ for this behavior.
2. StretchRd: As described in Section 4.3.5, "Memory Controller Registers," on page 4-45, there are five cycles before MRB_Ctrl needs to pulse, therefore the correct stretch point is just before the first pulse. The value which StretchRd needs to be programmed to is $5 - 2 = 3$.
3. Regarding the timer values: As an example, we will look at SameBusyRdRd. This value specifies the earliest time at which the next read to the same group of SIMMs can start. All these values depend on the specifics of the system clock speed, the DRAM timing information, and the specific way the waveforms are programmed. There is an initial cycle at the beginning of the read (which the subsequent read to the same SIMM will also have). The system clock speed is 12 ns per cycle. The DRAMs are standard 60 ns DRAMs. Therefore t_{RAS} is 60 ns, t_{RP} is 40 ns, and t_{RC} is 110 ns. We have 5 cycles where RAS is low thus satisfying t_{RAS} , we could have RAS high for 4 cycles giving us 48 ns, thus satisfying t_{RP} , but then t_{RC} is only 108 ns. Therefore, t_{RP} also needs to be 5 cycles. This means that the earliest the next cycle to the same group can begin is in 10 cycles. As described in Section 4.3.5, "Memory Controller Registers," on page 4-45, we subtract two from this and get 8. SameBusy RdRd needs to be programmed to 8 for the tightest allowable read to read spacing to the same group. When looking at timer values for different groups, the worst case timing for the address bus and data bus must be accounted for, to get the tightest spacing for those.

SIMULATED MC TIMING EXAMPLES AND NOTES

This section contains a set of examples that shows both internal and external waveforms. These samples are extracted from the simulation tool and are used for illustration only. By reviewing the CSR values, the timing diagrams, and the descriptions, it is hoped that a better understanding of the MC will be obtained.

A non-optimized set of Memory CSR's that work with the simulation environment is shown below. The clock in this case is 50 MHz (20ns).

TABLE 1: CSR values for timing examples

Address	Value (Hex)	Function
80	a0c10f18	Mem_Control0
84	263725b3	RAS_Control
88	00004da3	CAS_RD_Control
8c	29362692	BankSel_Control
90	2c98249a	XB1_Buffer_Control
94	24cb24c7	CAS_WR_Control
98	14ac0279	Phase_Level_Control
9c	02952549	SIMM_Busy_Rd_Control
a0	06020543	Count_Control
a4	249324b7	Refresh_Control
a8	29b52493	Row_Control
b0	14952549	SIMM_Busy_Wr_Control
b4	12952549	SIMM_Busy_Refr_Control

These CSR values were used when generating the following waveforms.

Writes to Different Groups

Figure 29 illustrates two consecutive writes going to two different groups from different CPUs. The general sequence is as follows:

1. The PM_ReqVal signal starts the MC FSM.
2. The mc_fsm sends out the start signal to Group 0 generators on the next clock.
3. The DPS tell the CPU to write to the XB1 write buffers on the next clock.
4. The Timers start counting.
5. The DPS tells the XB1 to accept the Write Data on the next clock.
6. WE_L is activated and remains so throughout the write cycle.
7. Another PM_ReqVal signal arrives, requesting group 1. Since SIMMBusyDiff is active, the next Write cannot be started and the FSM goes into a Pending state.
8. SIMMBusyDiff is inactive on the next clock cycle and the start to group 1 is initiated.
9. And so on...

It may be possible to eliminate the "Pending" cycle by reducing the Diff_Busy_Wr_Wr count from a to 9 if the memory address hold time does not get violated in the process. The memory address appears to be the limiting factor in this case. Note that the DiffWr counter is held for one cycle in state 09. This is because the DM_WBAck signal has not yet arrived and the state machines are held. See also *Figure 35*.

Reads to Different Groups

Figure 30 shows consecutive reads from two groups from CPU 1 and then CPU 0. There appears to be some optimization that can be made here with the Diff_Busy_RD_RD counter. The limiting factors include the Memory Address and the RB_Busy signal. It may be necessary to move out the StretchTimerRd by two cycles so that the MC samples RB_Busy at a more appropriate time. Right before you need to start filling the XB1 buffer is the suggested time. This would be a cycle before the internal mrb_ctrl signals are activated. It appears that the Diff_Busy_RD_RD counter could be reduced by as many as 5 cycles if the StretchTimer Rd is increased by 2 cycles.

Reads to the Same Group

Figure 31 shows consecutive reads to the same SIMM group. The CAS generator is currently taking 10 cycles. Since it must be in idle before accepting another start signal, only by reducing the CAS generator state machine sequence can we reduce the SIMMBusy count. Since the cycle count in the last phase of CAS_RD is 2, the state machine effectively cycles for 2 counts during that stage. Reducing the last phase to 1 will have no effect on the waveform, yet will let the state machine go to the idle state 1 cycle earlier. Hence, a start pulse can be received 1 cycle earlier.

Write followed by a read

In this example, shown in Figure 32, a write is followed by a read in the same group. This example shows the internal Hold0 signal, which keeps the cycles in the timer "timer0Wr" from decrementing. This hold signal is the result of WB_Busy being active when the StretchTimerWr0 counter has expired and polls WB_Busy to see if the XB1 buffer has acquired its data. The next cycle, XB1 has acquired the data, the DPS sends DM_WBAck and the WB_Busy goes inactive and allows the timer0Wr counter to proceed.

The limiting factor in starting the Read in this case is the rising edge of CAS. It does not appear that any additional cycles can be gained from this sequence.


Waveform generators

Figure 33. shows various waveform generator state machine sequences for both a write and a read.

Stretch Write counters

Figure 34. shows the stretch write counters. It a sequence of two writes, one from CPU1 and the next from U2S. When the stretch write counters expire, they check the WB_Busy signal to see if the XB1 buffer is loaded. From the figure, we can see that the CPU data is loaded very quickly and there is only 1 hold state before the both SIMM pairs can be written. However, the second write is from U2S and the waveform generators are held for both the first and second datums. The important thing to watch for is that the StretchWr1 must be long enough so that it samples WB_Busy after the second DM_WBAck arrives. If StretchWr1 is too small, it will sample WB_Busy during after the first DM_WBAck and think that data has arrived and inappropriately write the data to memory. Thankfully, the DPS block will always place DM_WBAck 4 cycles apart on Writes from U2S and the StretchWr1 counter is held when the hold signal is active.

For performance, it's best to minimize the StretchWr counters.

A solid black rectangular box with rounded corners.

STP2202ABGA

DSC
Dual Processor System Controller

Ping-Pong buffers

Figure 35. shows the ping-pong buffers on 2 consecutive reads. When the PP timer expires it sends out the PingNow signal. That, in turn, causes the memory addresses to be originated from the other buffer. For performance optimization, you want the next address to appear as soon as it can while not causing address hold time violations for the current operation.

Timing diagram showing the relationship between various system signals and a 100ns time scale. The signals are:

- sc_subsys.sc.UPA_ADDRBUS0: 00000000
- sc_subsys.sc.UPA_ADDRVAL0: 0
- sc_subsys.sc.Xscmp_top.PC_SnpReqVal: 0
- sc_subsys.sc.Xscmp_top.CP_WrDnPC0C1: 0
- sc_subsys.sc.Xscmp_top.CP_WrDnPC1C1: 0
- sc_subsys.sc.Xscmp_top.CP_WaitPC0C1: 0
- sc_subsys.sc.Xscmp_top.CP_WaitPC1C1: 0
- sc_subsys.sc.Xscmp_top.PM_ReqVal: 0
- sc_subsys.sc.Xscmp_top.mc.Start: 0
- sc_subsys.sc.Xscmp_top.mc.MC_fsm.pres_state: 0
- sc_subsys.sc.Xscmp_top.mc.MC_simm_eng.timeOffWt.count: 0
- sc_subsys.sc.Xscmp_top.mc.SIMMBusyDiff: 0
- sc_subsys.sc.BMXCMD0: 0
- sc_subsys.MEM_ADDR0: 0000
- sc_subsys.RAS_L: ff
- sc_subsys.CAS_L: ff
- sc_subsys.WE_L: ff
- sc_subsys.BANK_SEL: 0
- sc_subsys.MWBCTRL0: 0
- sc_subsys.MRBCTRL0: 0
- sc_subsys.UPA_SREPLY0: 00
- sc_subsys.UPA_SREPLY1: 00
- sc_subsys.sc.CLK: 00

The time scale is marked from 0 to 100ns.

Figure 30. P1_RDD_P0_RDD

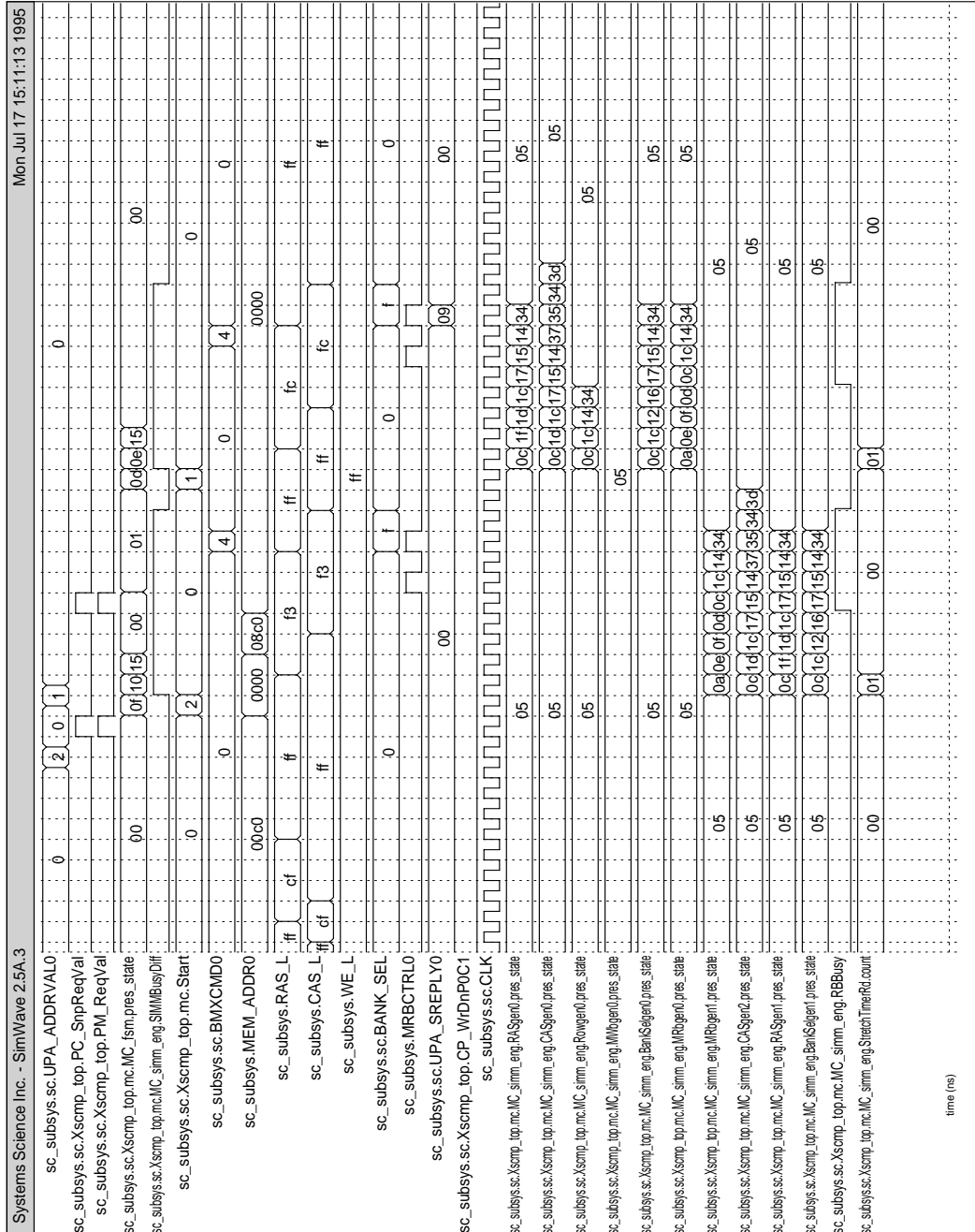


Figure 31. Same Group P1_RDD_P0_RDD

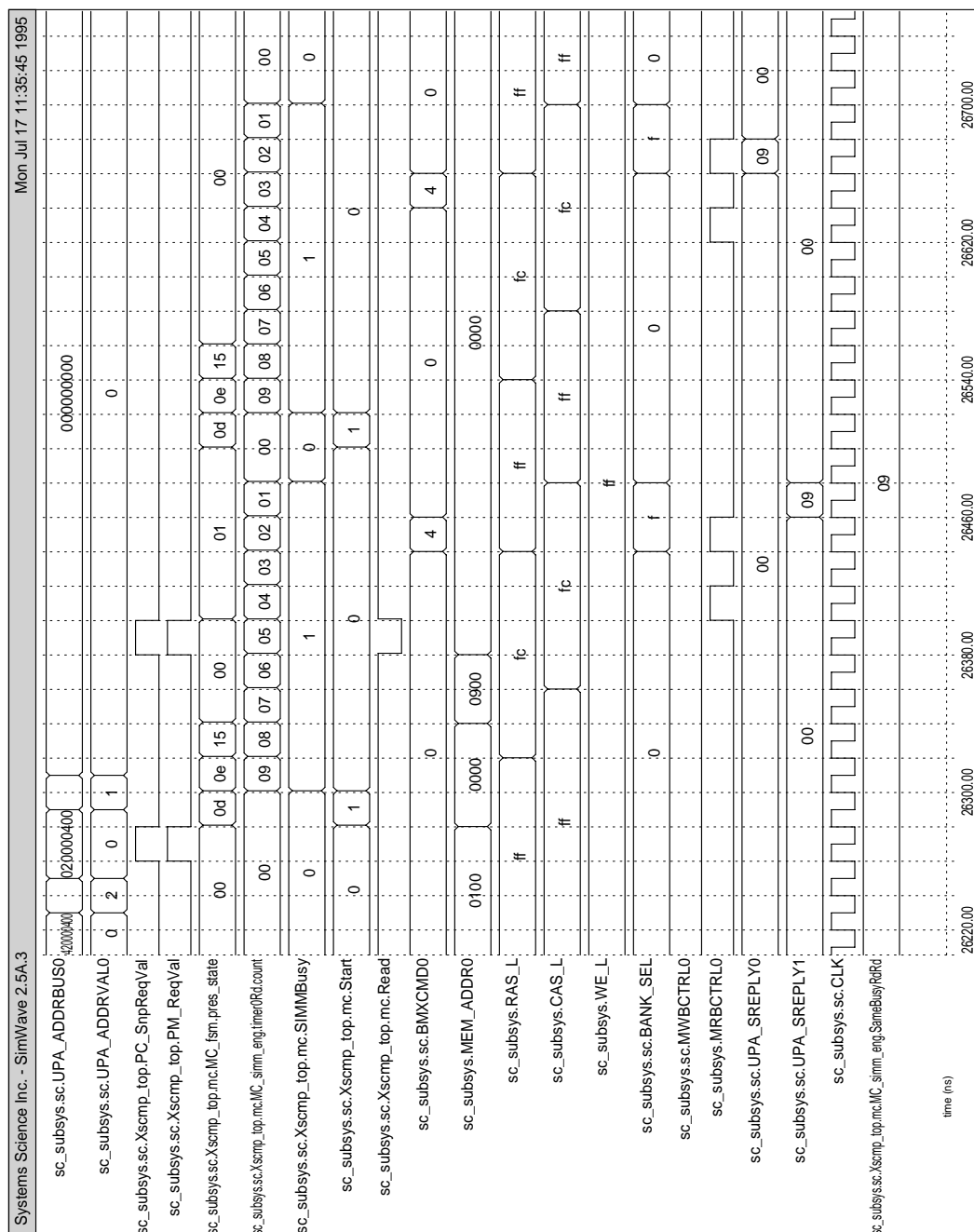


Figure 32. P0_WRI_RDD Same Group

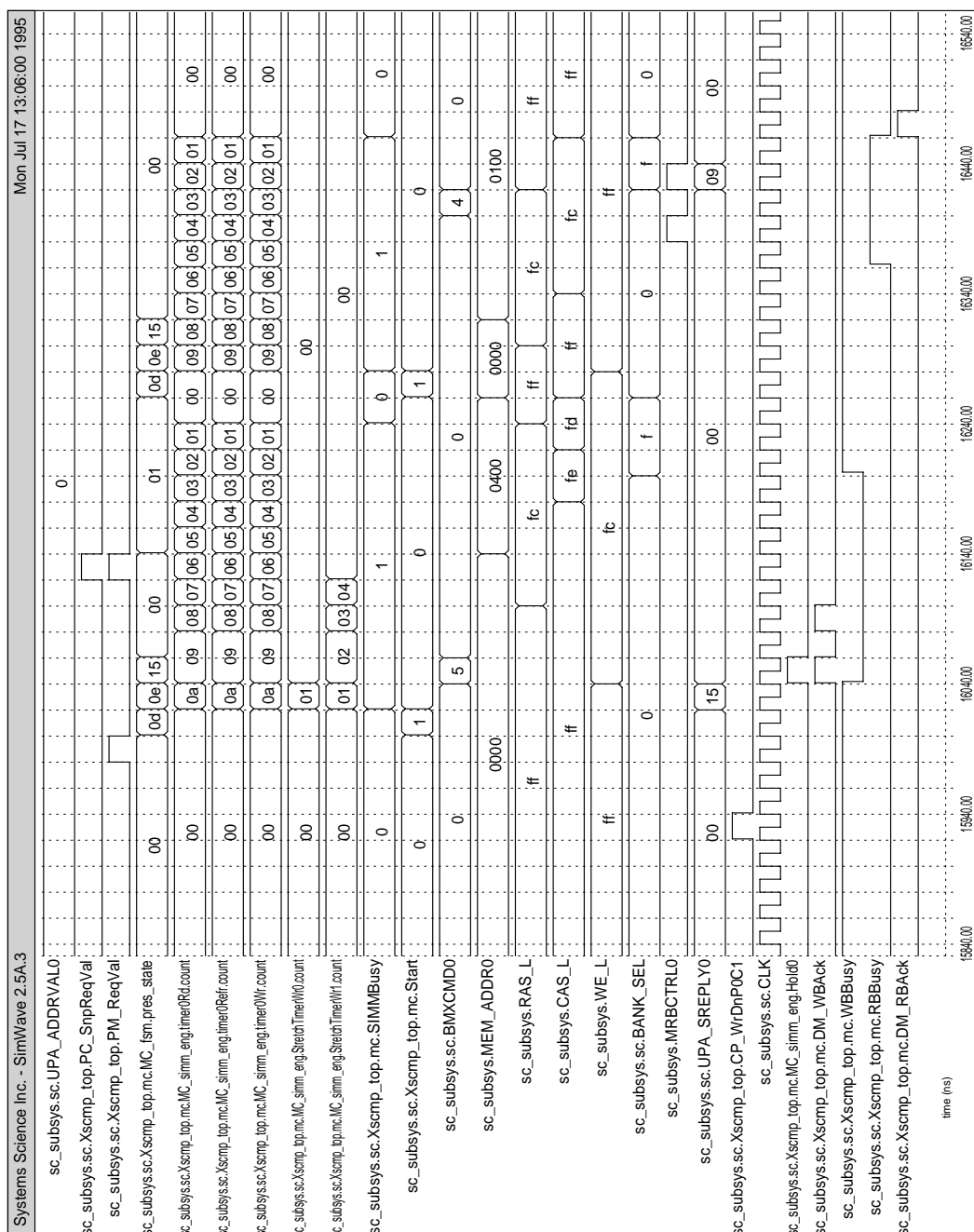


Figure 33. Waveform Generators

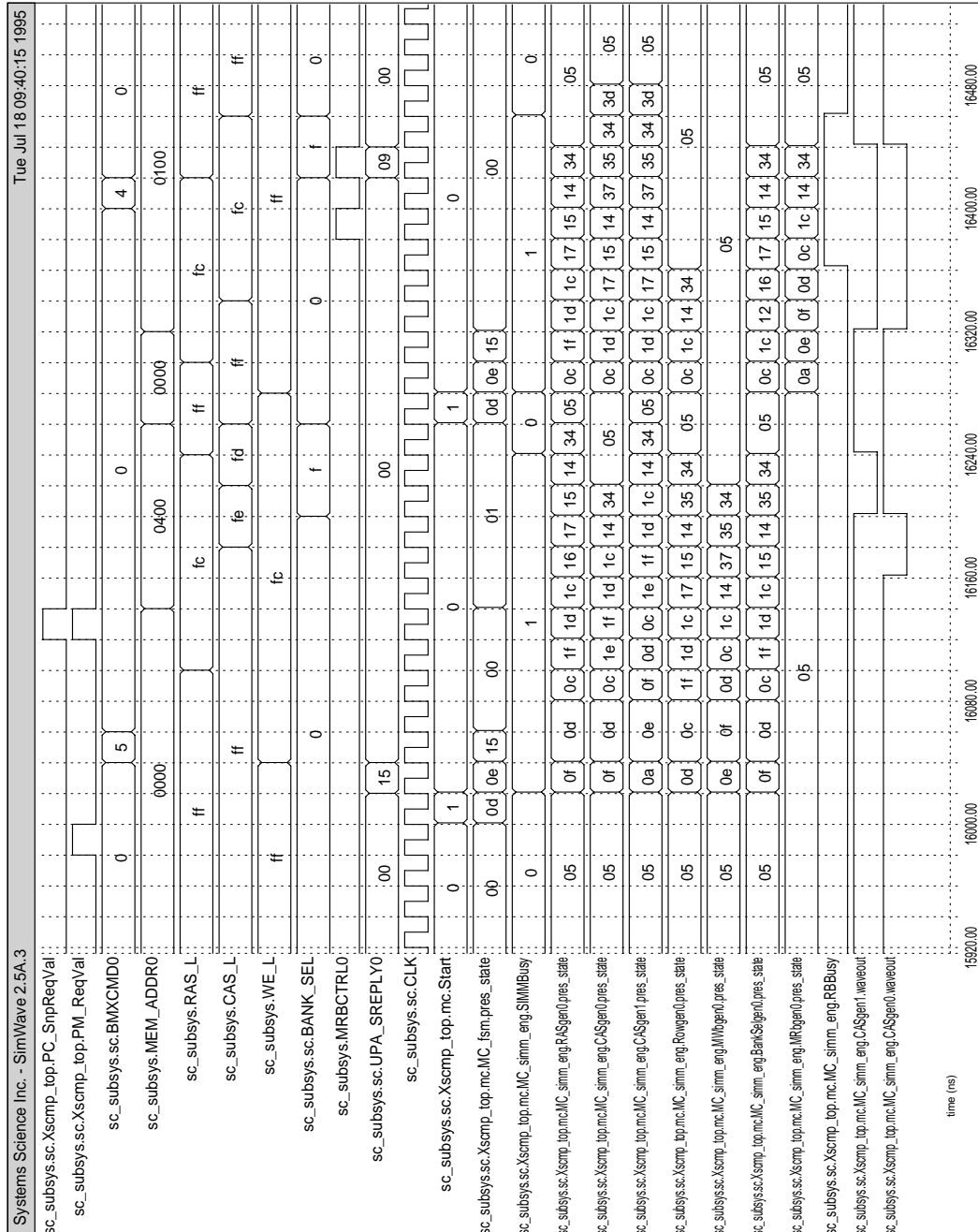


Figure 34. Stretch write counters

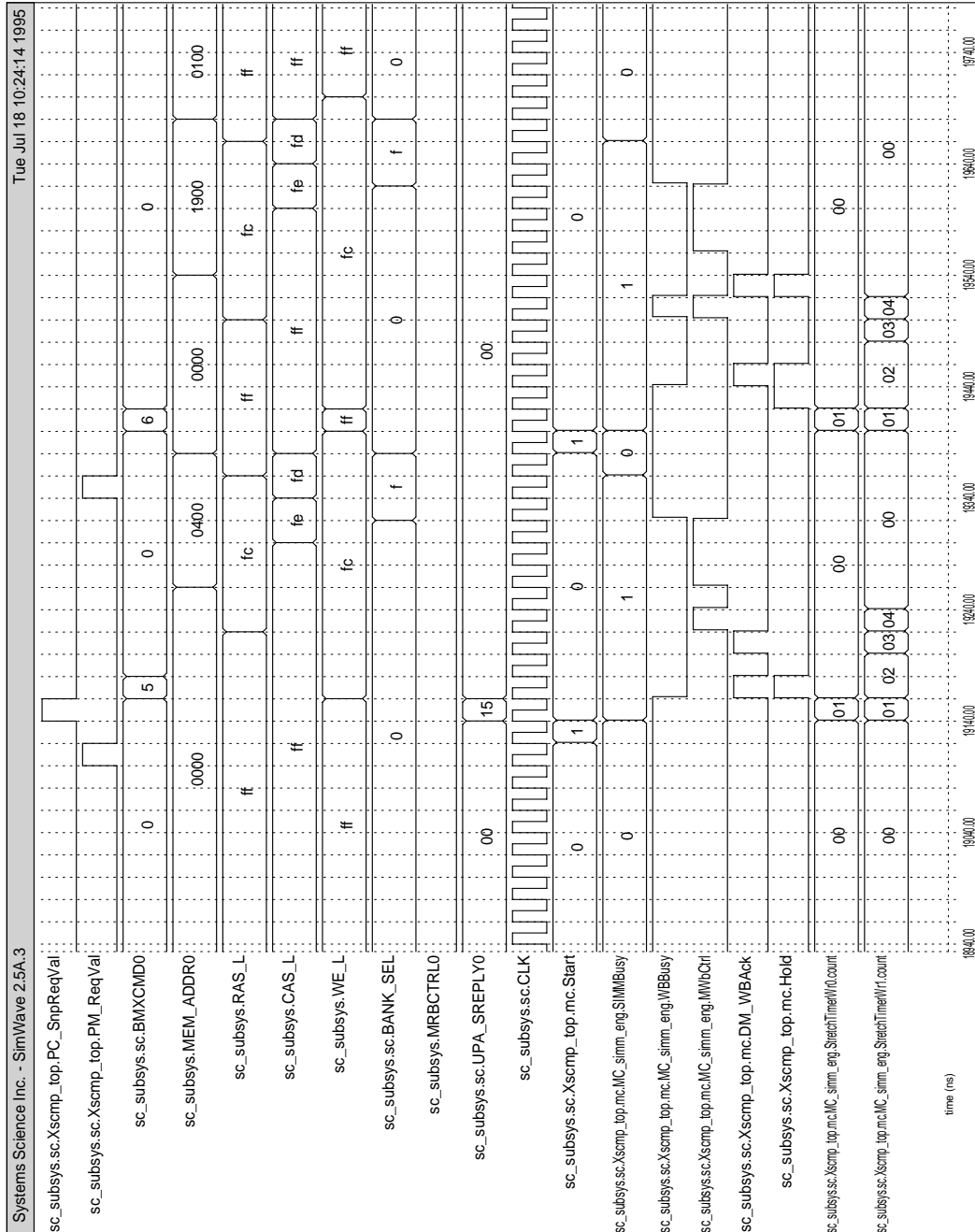
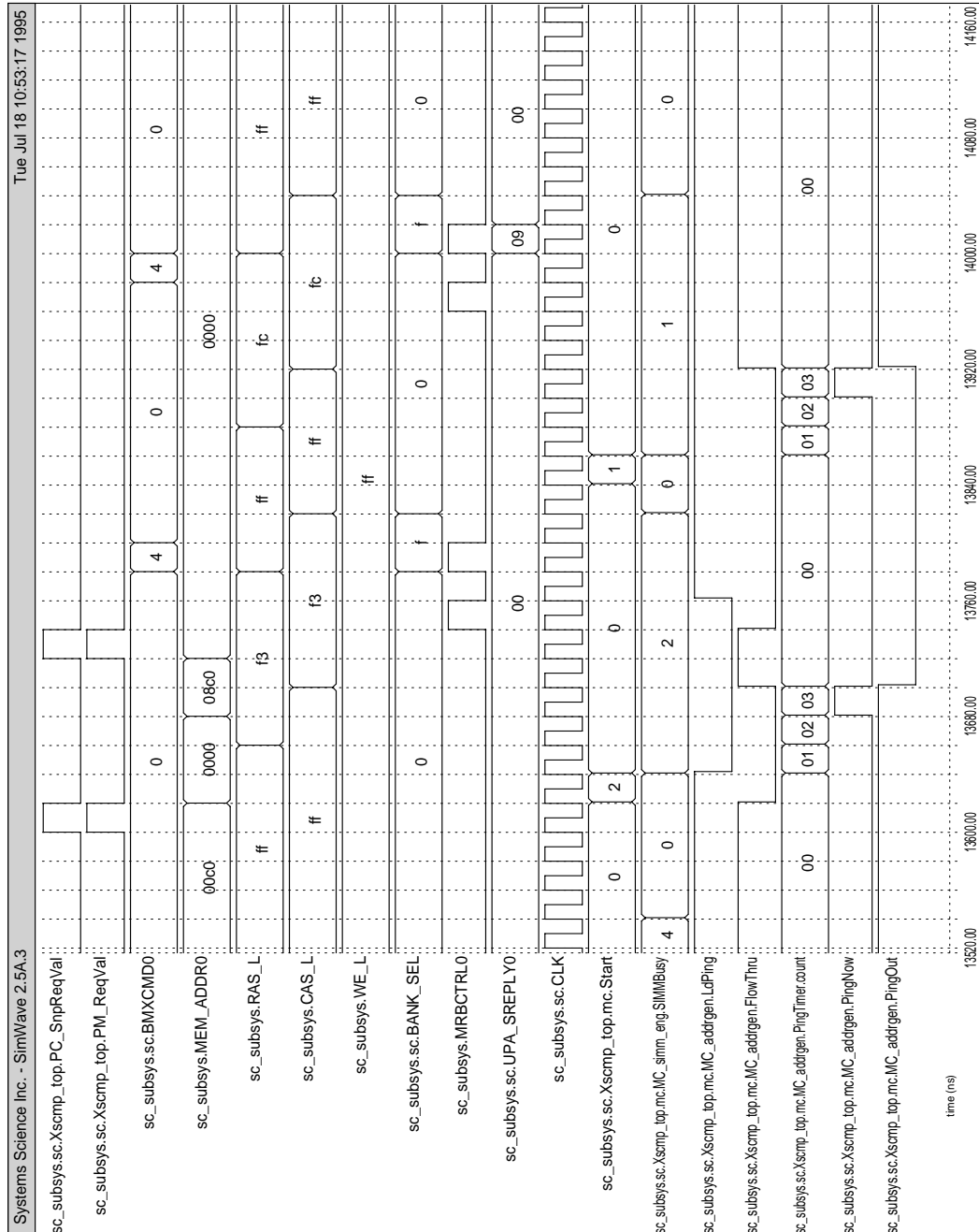


Figure 35. Ping-Pong timers if Wr-Wr



83.3 MHz DSC TIMING EXAMPLES AND NOTES

CSR Programming Notes

This section includes empirical knowledge about programming CSRs. Generating a functional CSR set is a difficult process. Everything has to be perfect for the set to work in actual hardware which makes debug ugly. There are 384 bits to program, each has an effect on the DRAM waveforms generated, or the DRAM cycle to cycle timing, or the DRAM to UPA interface. To assist future DSC CSR programmers the following notes are provided to guide the process and answer some of the difficult questions that came up during generation of the CSRs presented in this document.

Programming Same Group Timing:

The most important point for programming same group timing is to wait to start the following group until all the timers from the first group have finished. No overlapping signals are allowed because reloading a counting timer with a new countdown value is not supported by this design. An example of a failure created by violating this rule is overlapping a refresh cycle behind a write cycle. If the write CAS timer is not finished when the refresh cycle starts then the refresh cycle will have CAS high for the entire cycle - a missing CAS refresh cycle.

A special case that requires overlapping into the previous cycle is a DRAM read cycle. Optimized timing has been implemented to allow minimum latency for reads. The DRAM RAS signal is dropped immediately (clock 0) in a read cycle. This requires that the ROW address is available one clock previously. To accomplish this the Ping Pong point of the previous cycle is used as a switch time to output the next read ROW address. For this case the Ping Pong point is used for the same group addressing, not just for switching to a different group address.

Finally the DRAM timing parameters must be met. The DRAM cycle time, RAS and CAS precharge time between cycles must be met.

For all cases except one the DSC concatenates DRAM cycles based on the minimum value of the timers. That case is a read followed by write. One dead clock is necessary because of the requirement for one clock of float time between data masters on the UPA bus. However two more dead clocks appear partially because the memory controller must wait until the read data is removed from the XB1 to allow the write data to be latched on the UPA side and partially because of the internal handshakes required by the coherency control, the port interface and the memory controller. The dead clocks show up at the first stretch point of the write cycle.

Also note that if a one timer finishes before the others in the DRAM cycle, the signal either stays in the final state or goes to the initial programmed state. Overlapping signals is allowed if the overlapping signal timer is finished however no practical application was found for this.

Note: Factors for same group DRAM cycle concatenation:

- DRAM control signal requirements (RAS and CAS precharge, address and data setup and hold time, signal minimum width, minimum cycle time, and everything else in the DRAM specification).
- UPA and XB1 timing for data transactions. (data float time, correct data latch for writes and reads)
- DSC control points (Setting Ping Pong points for address switching to the next cycle, setting stretch points for holding cycles at the correct point for late data, starting and ending cycles at the right points).
- Taking into account the special performance features of the SCMP (read cycles starting one clock early by

setting up ROW address one clock before the cycle starts, ORing the bank select signal to allow tighter overlap on different group reads and writes, Ping Pong point controls the next address switch time for both same and different groups)

Note: Factors for different group DRAM cycle concatenation:

- All the above except the first because the control signals are separate. Note that the DRAM write signal is included as a separate signal even though it is not controlled by CSR timers

Programming Different Group Timing:

Programming the different group timing is more complicated than same group, even though the control signals are separate, because the address bus and data bus are shared. The simplest case for different group timing is to just use the same group timer values. This of course does not take advantage of the overlapping cycles the DSC design allows and the performance increase possible with overlapping cycles.

The DSC allows 100% utilization of the DRAM data bus and 50% utilization of the UPA data bus during back to back reads. The overlapping ROW address special case, as described above, is used to achieve this throughput. Two clocks of DRAM data float time and one clock of UPA data float time are included. The limiting factor for overlapping reads is simply the DRAM data bus.

For overlapping writes the limiting factor is the DRAM address bus. One clock of overlap is allowed. The address bus must remain stable for the second CAS until one clock before the end of the first write. This implies that a different group write can not start earlier because the second write ROW timer would switch from the first write CAS address to the RAS address. This is a design limitation of the DSC because the ROW address for the next write is not needed for one more clock.

For overlapping different group reads and writes two cases must be examined; read followed by write and write followed by read. For write followed by read DRAM cycles limiting factor is the DRAM address bus. This case is actually identical to the same group write to read timing. No optimization is possible because the address bus is used until one clock before the end of the write cycle. The following read requires one clock of address setup time before RAS. Again this is the same overlapping ROW address special case, as described above. The write ping pong point is set at the end of the second CAS, one clock before the end of the cycle, to allow a same or different group read to start immediately at the end of the write, without a dead clock.

For the read followed by write case the limiting factor is the UPA data bus. One dead clock is necessary because of the requirement for one clock of float time between data masters on the UPA bus. However as described above, two more dead clocks appear and are related to the internal DSC control handshakes and XB1 scheduling. The dead clocks show up at the first stretch point of the write cycle and the resulting timing is the same as for the same group timing. No different group optimization is possible.

Special Programming Rules.

1. All same and different timers are programmed with a value two less than the desired end count.
2. The Ping Pong point is programmed for a value one less than the address switch time desired.
3. The Ping Pong point and the ROW timer (selects between RAS and CAS address) are independent. If the Ping Pong point is set correctly the ROW timer can still select the wrong address.

4. The Bank Select signal is an OR of the individual group bank select signals.
5. The Bank Select signal does not switch for the first few clocks of a cycle to allow more overlap of DRAM cycles.
6. The RAS signal of write and read cycles is inverted from the programmed value for the first time interval. This is to allow RAS to drop immediately for read cycles.
7. In most cases write cycles stretch for one or more clock at the first stretch point waiting for data. One case without stretch cycles is back to back writes. Read followed by write cases have 3 stretch clocks.

CSRs for 83.3 MHz DSC

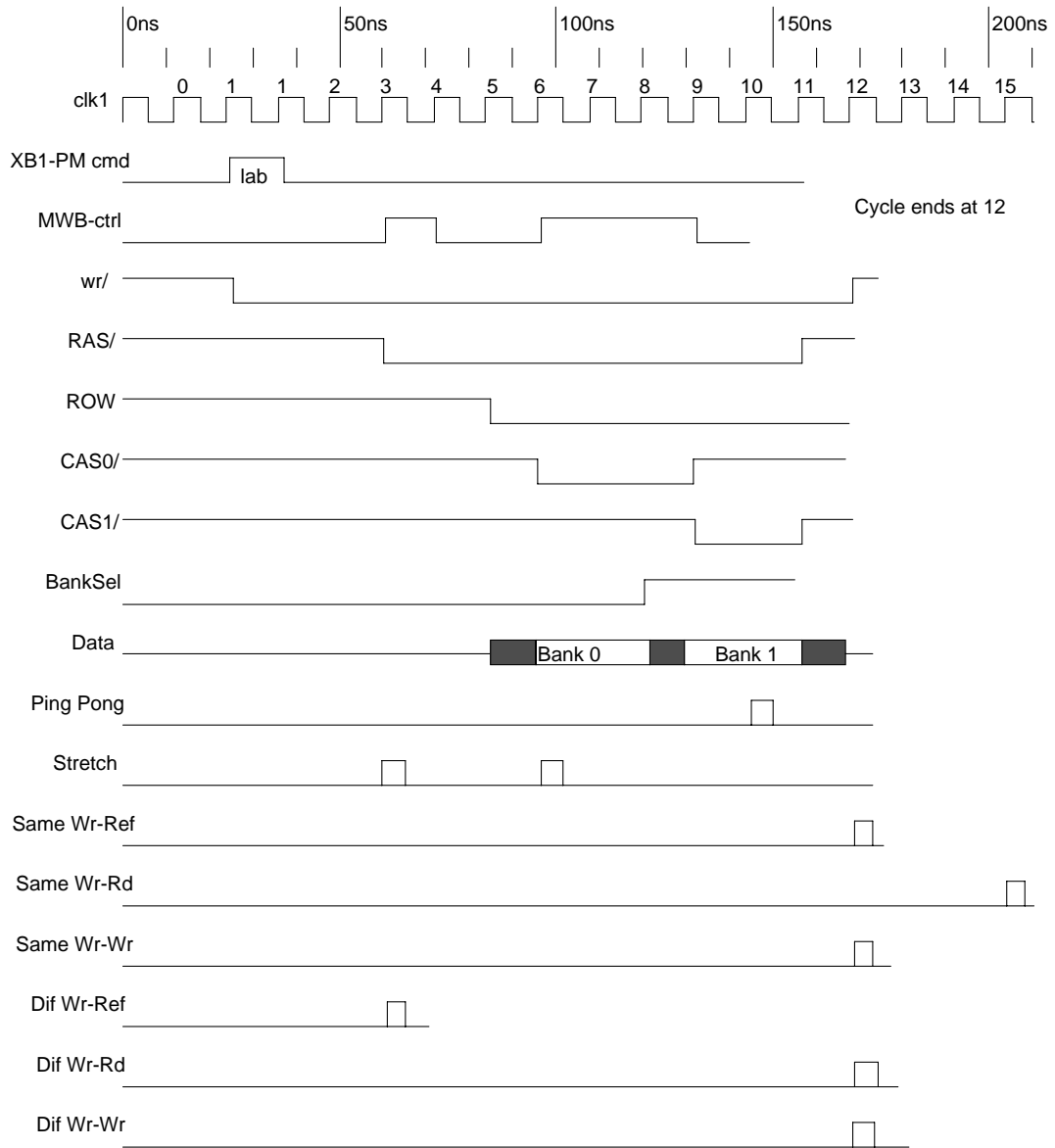
The optimized set of Memory CSRs for 83.3 MHz DSC is shown below.

CSR values for the 83.5 MHz UPA case

Address	Value (Hex)	Function
80	a0c1 0f18	Mem_Control0
84	29b7 24a5	RAS_Control
88	0000 2d95	CAS_RD_Control
8c	2936 2692	BankSel_Control
90	2d16 249a	XB1_Buffer_Control
94	24cb 6537	CAS_WR_Control
98	14ac 0270	Phase_Level_Control
9c	02c5 19a8	SIMM_Busy_Rd_Control
a0	0602 0d45	Count_Control
a4	a913 2929	Refresh_Control
a8	29b5 2493	Row_Control
b0	0294 a549	SIMM_Busy_Wr_Control
b4	1290 8548	SIMM_Busy_Refr_Control

These CSR values were used when generating Figure 36. to Figure 44.

Figure 36. 12 NSec Write Timing

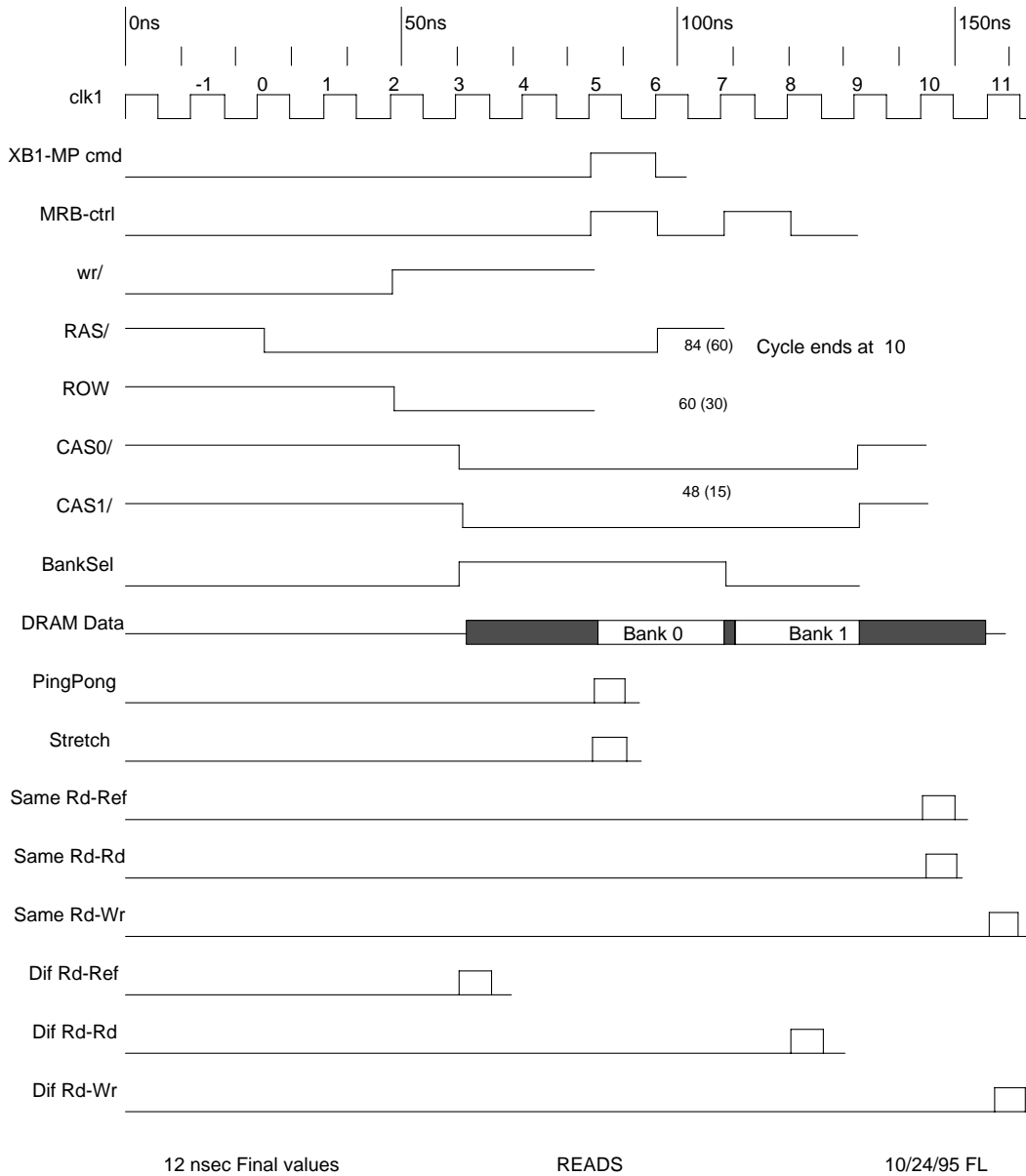


Idle -> write cycles have one clock of first write stretch
Stretch points are internally 2 clocks before they are shown above
12 nsec Final values

11/8/95 FL

WRITES

Figure 37. 12 NSec Read Timing



Critical timing: RAS to data has 24 nsec margin

Figure 38. 12 NSec Refresh Timing

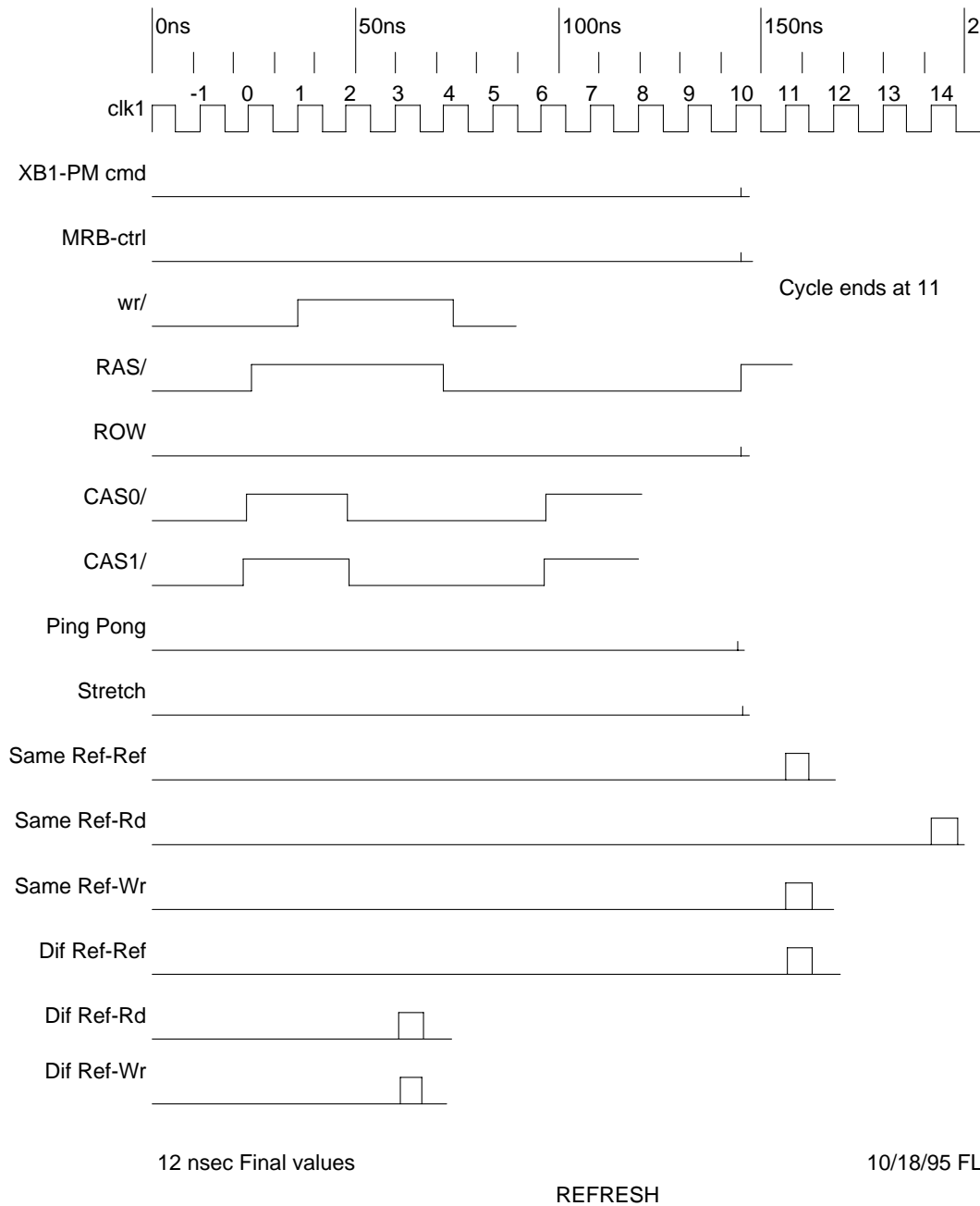
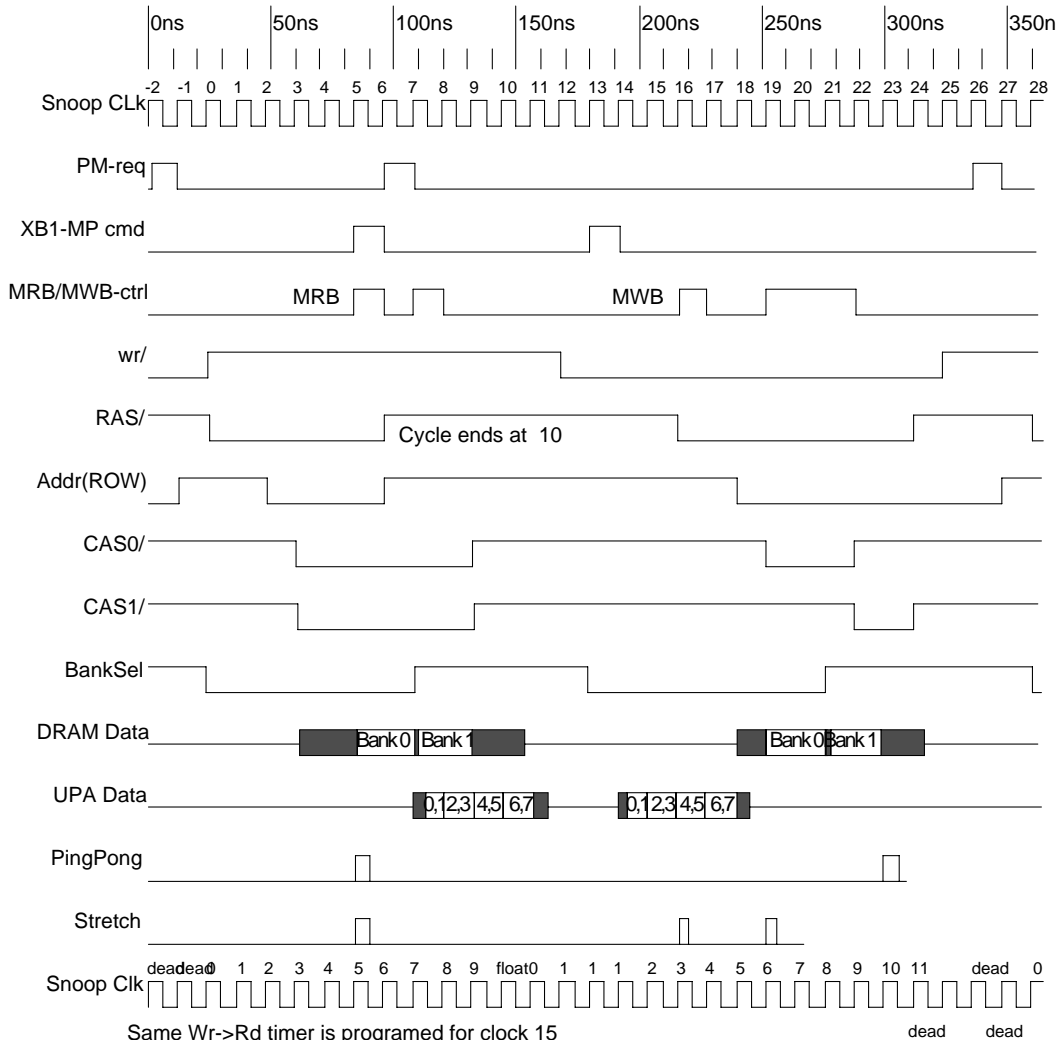


Figure 39. 12NSec Same SIMM Group Read<->Write Timing



Same Wr->Rd timer is programed for clock 15

Limiting factor is RAS precharge for 4 clocks between write and following read.

Same Rd->Wr timer is programed for clock 11

Limiting factor is that UPA data bus requires one clock of float between masters

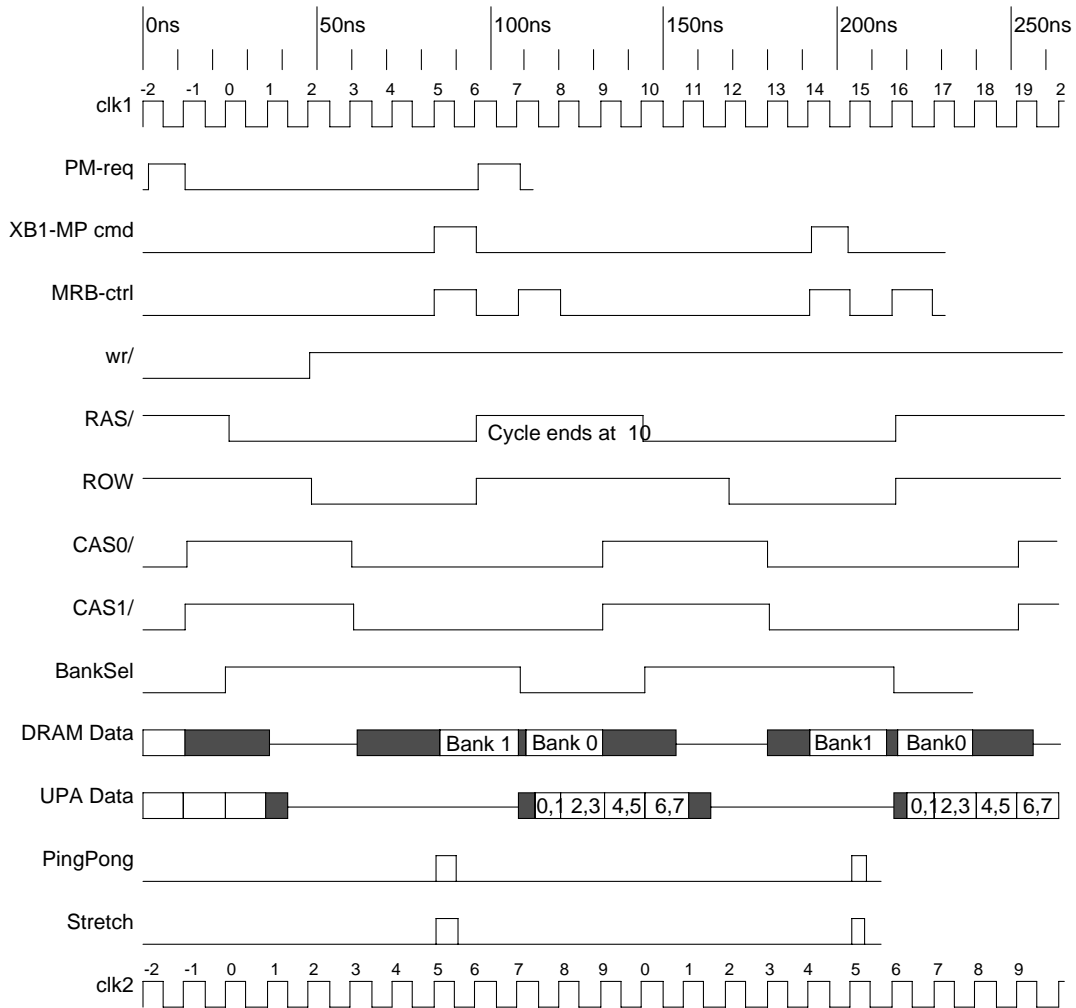
Lab measurements show that the first write stretch point holds for data for 3 clocks

because the read data must be unloaded from the XB1 before the write can start.

When write follows read XB1 comand is delayed by one clock

Same Read -> Write time is 28 clocks at 83 MHz or 381 MBytes/Sec

Figure 40. 12 NSec Same SIMM Group Read <-> Read Timing



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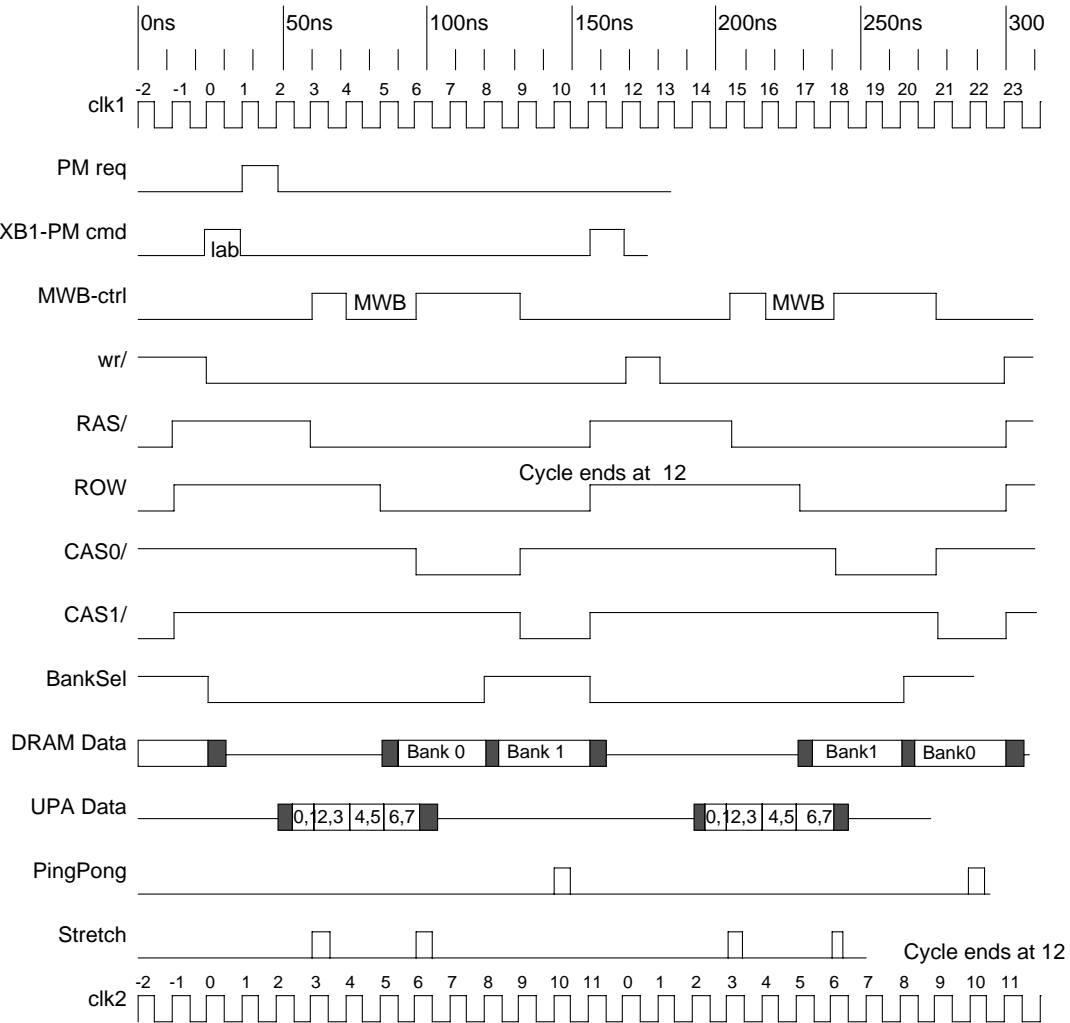
Limiting factors are, first cycle RAS and CAS timers must zero, and RAS precharge for 4 clocks.

Same Rd -> Rd timer is programmed for clock 10

Lab measurements show that ROW controlled address switch for same group is also controlled by ping pong point

Same Read -> Read time is 20 clocks at 83 MHz or 533 MBytes/Sec

Figure 41. 12 NSec Same SIMM Group Write <-> Write Timing



11/22/95 FL

Limiting factors are, first cycle RAS and CAS timer must zero out, and RAS precharge for 4 clocks.

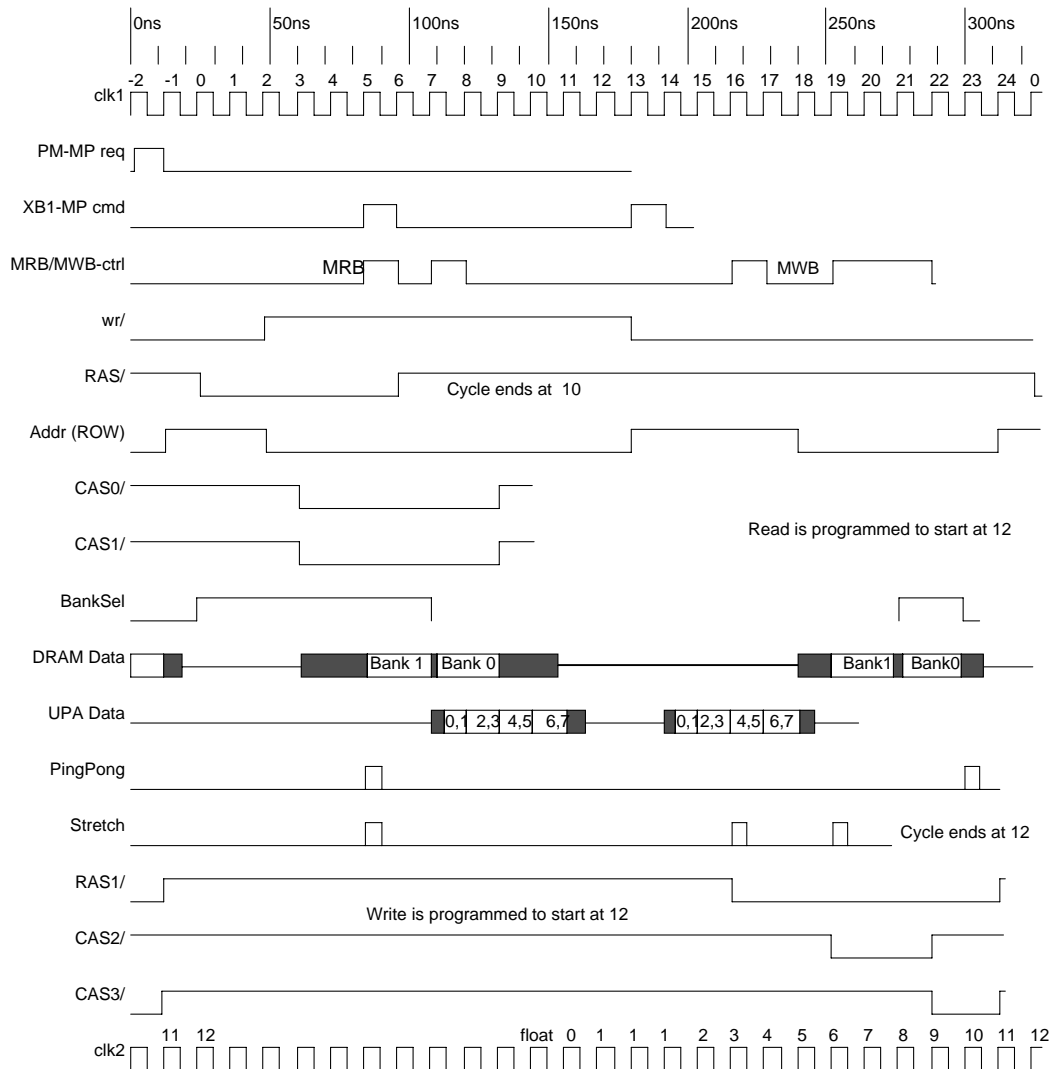
Same Wr -> Wr timer is programmed for clock 12

Lab experiments confirm this timing

Unlike read -> write timing there are no 1st write stretch points here because the XB1s are not holding data.

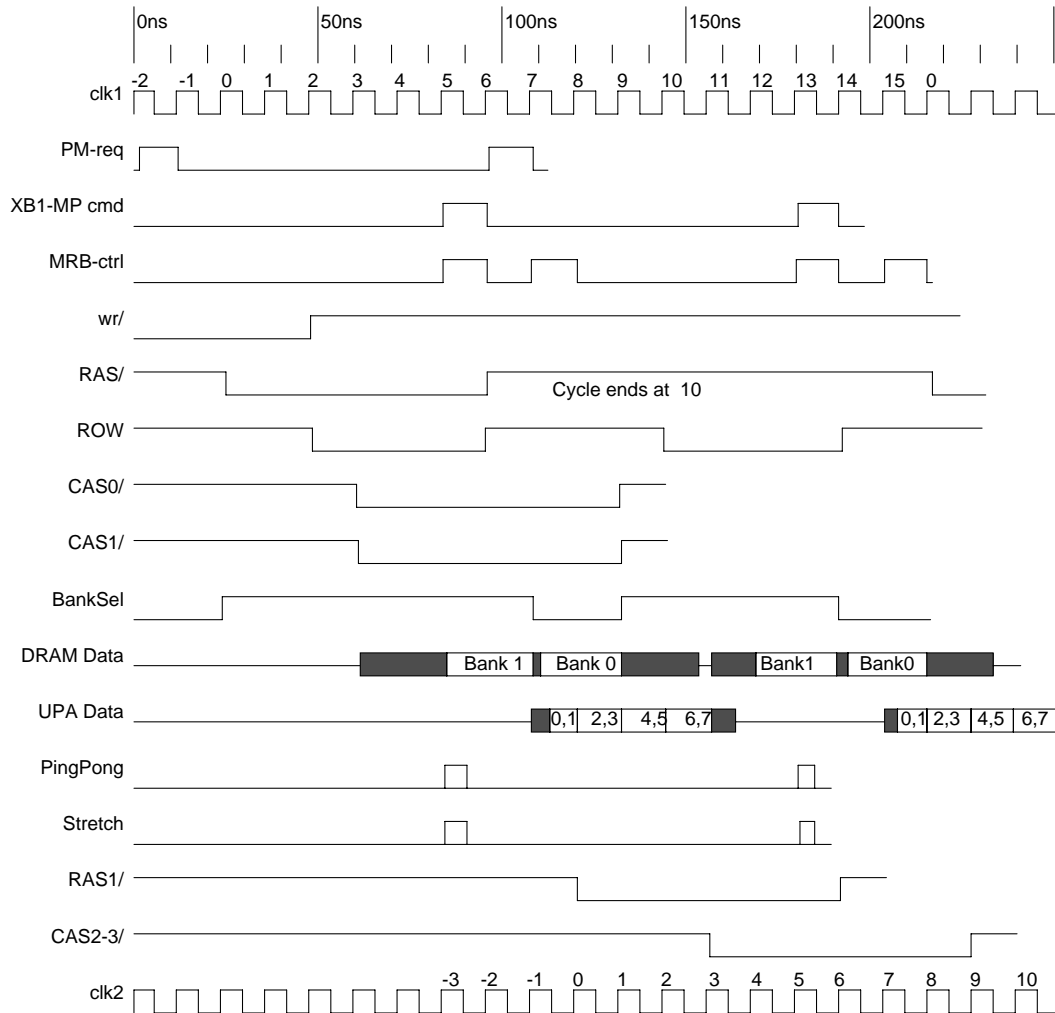
Same Write -> Write Cycle Time is 24 Clocks at 83 MHz or 444 MBytes/Sec

Figure 42. 12 NSec Different SIMM Group Read <-> Write Timing



Diff Wr->Rd timer is programmed for 12; Limiting factor is CAS address hold to RAS address setup
 Diff Rd->Wr timer is programmed for 12; Limiting factor is that UPA data bus requires one clock of float
 Also, lab experiments show that first write stretch point holds for 3 clocks
 because the read data must be unloaded from the XB1 before the write can start

Different Read -> Write Time is 25 clocks at 83 MHz or 427 MBytes/Sec

Figure 43. 12 NSec Different SIMM Group Read <-> Read Timing

Diff Rd -> Rd timer is programmed for 8 for two clocks of overlap

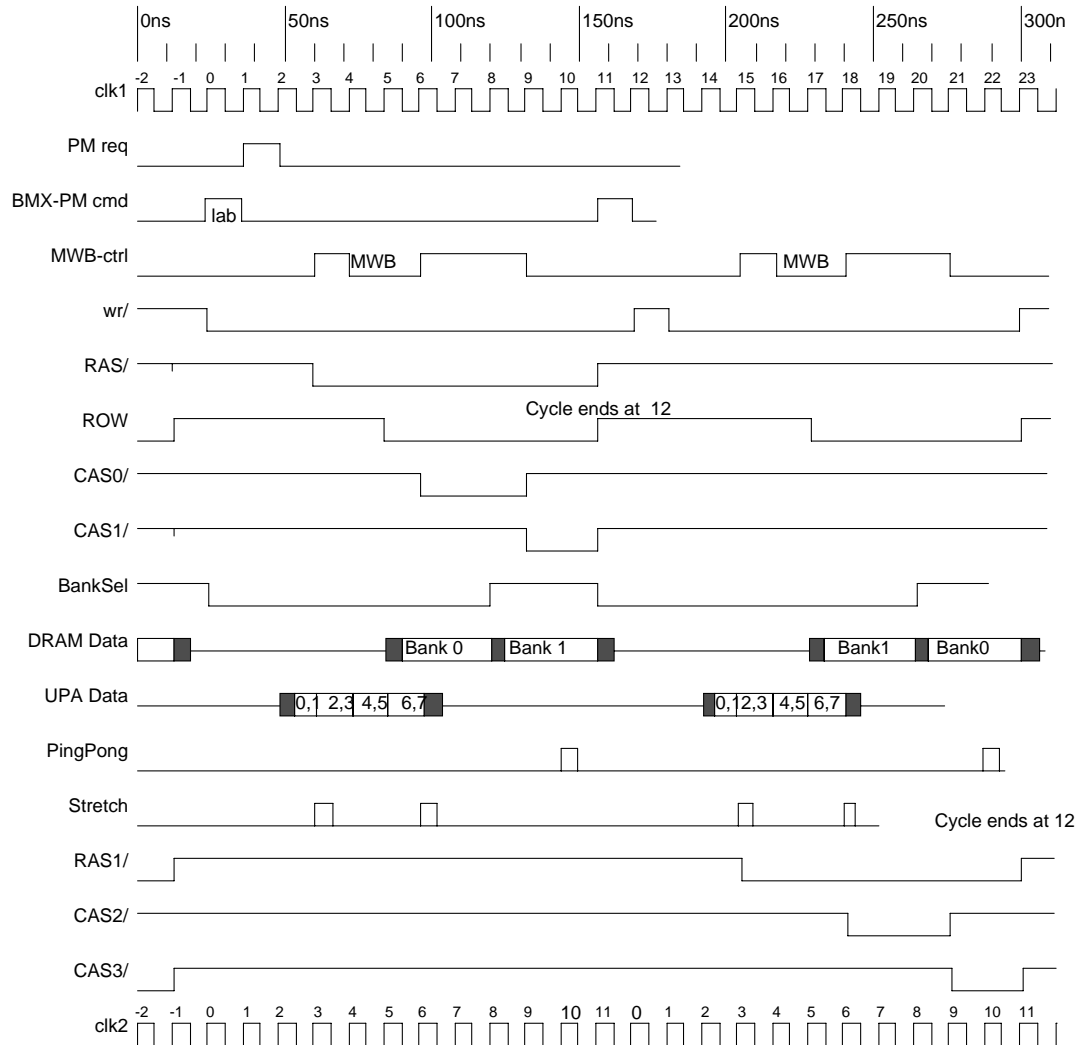
10/18/95 FL

Limiting factor is the DRAM data bus - two clocks of float required ROW is controlled at ping pong point

Also, lab experiments show that one more clock of overlap fails with "data missaligned" in UNIX

Different Read -> Read time is 16 clocks at 83 MHz or 667 MBytes/Sec

Figure 44. 12 NSec Different SIMM Group Write <-> Write Timing



Limiting factor is first write cycle finish signal to second data available.

11/22/95 FL

Same Wr -> Wr timer is programmed for clock 12. Programming for < 12 does not result in closer cycles.

Lab experiments confirm this timing

Unlike read -> write timing there are no 1st write stretch points here because the BMXs are not holding data.

Different Write -> Write Cycle Time is 24 Clocks at 83 MHz or 444 MBytes/Sec

66.7 MHz DSC TIMING EXAMPLES AND NOTES

This CSR timing set is for the Ultra 2 “Hot Box”. The CPU modules run at 200 MHz in 3:1 mode producing a UPA frequency of 66.7 MHz.

CSRs for 66.7 MHz DSC

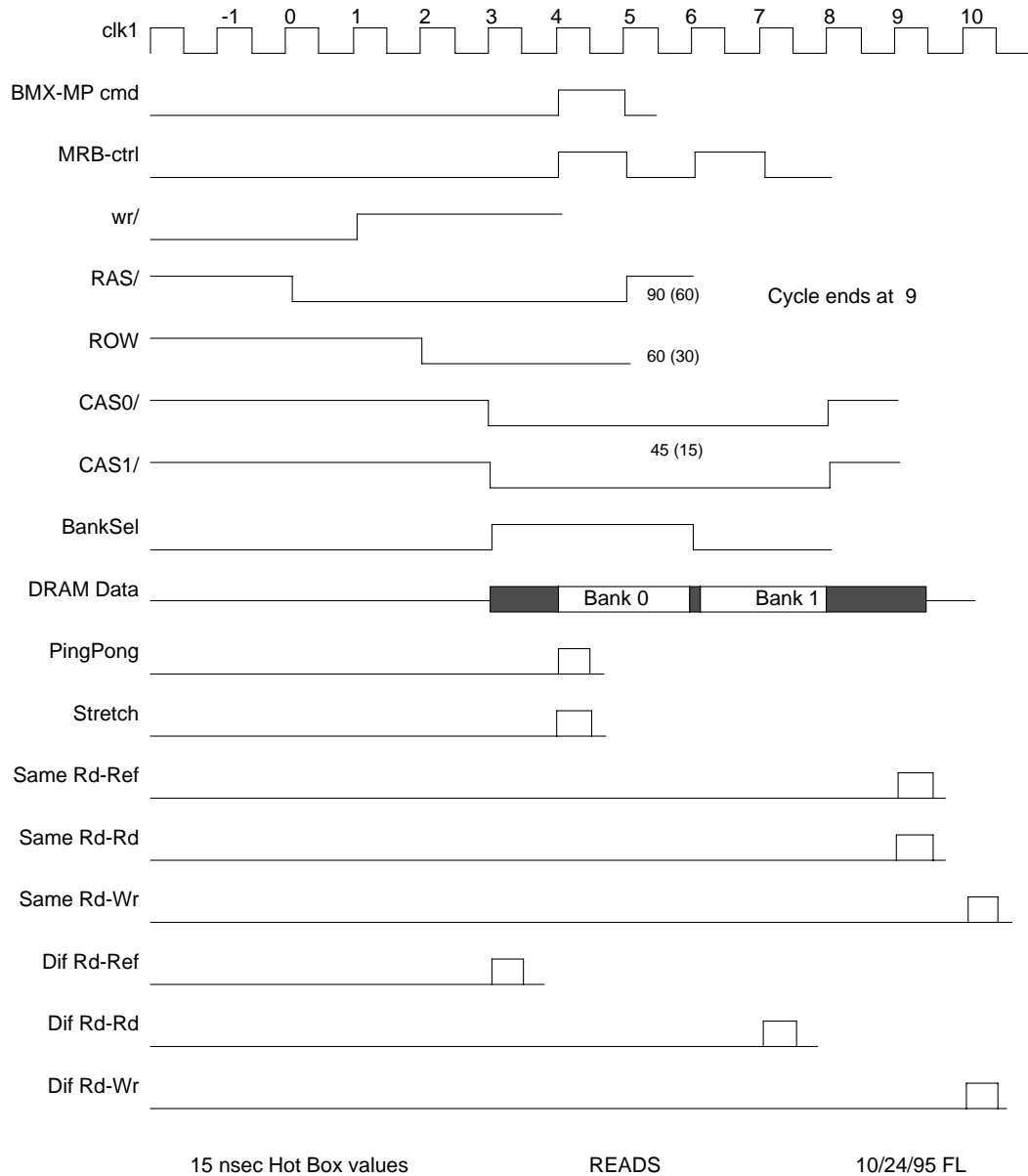
The optimized set of Memory CSRs for DSC at a UPA speed of 66.7 MHz is shown below.

CSR values for DSC Rev 1 at 66.7 MHz UPA

Address	Value (Hex)	Function
80	a0c1 0f18	Mem_Control0
84	29b7 2495	RAS_Control
88	0000 2d23	CAS_RD_Control
8c	2936 2612	BankSel_Control
90	2d16 2498	XB1_Buffer_Control
94	24cb 84b7	CAS_WR_Control
98	14ac 0270	Phase_Level_Control
9c	0295 1587	SIMM_Busy_Rd_Control
a0	0202 0944	Count_Control
a4	2893 2527	Refresh_Control
a8	252b 2495	Row_Control
b0	0274 a148	SIMM_Busy_Wr_Control
b4	0e70 8547	SIMM_Busy_Refr_Control

These CSR values were used when generating Figure 45. to Figure 47.

Figure 45. 15 NSec Read Timing



DRAM data access time from RAS, CAS addr, CAS all have 30 ns margin

Figure 46. 15 NSec Write Timing

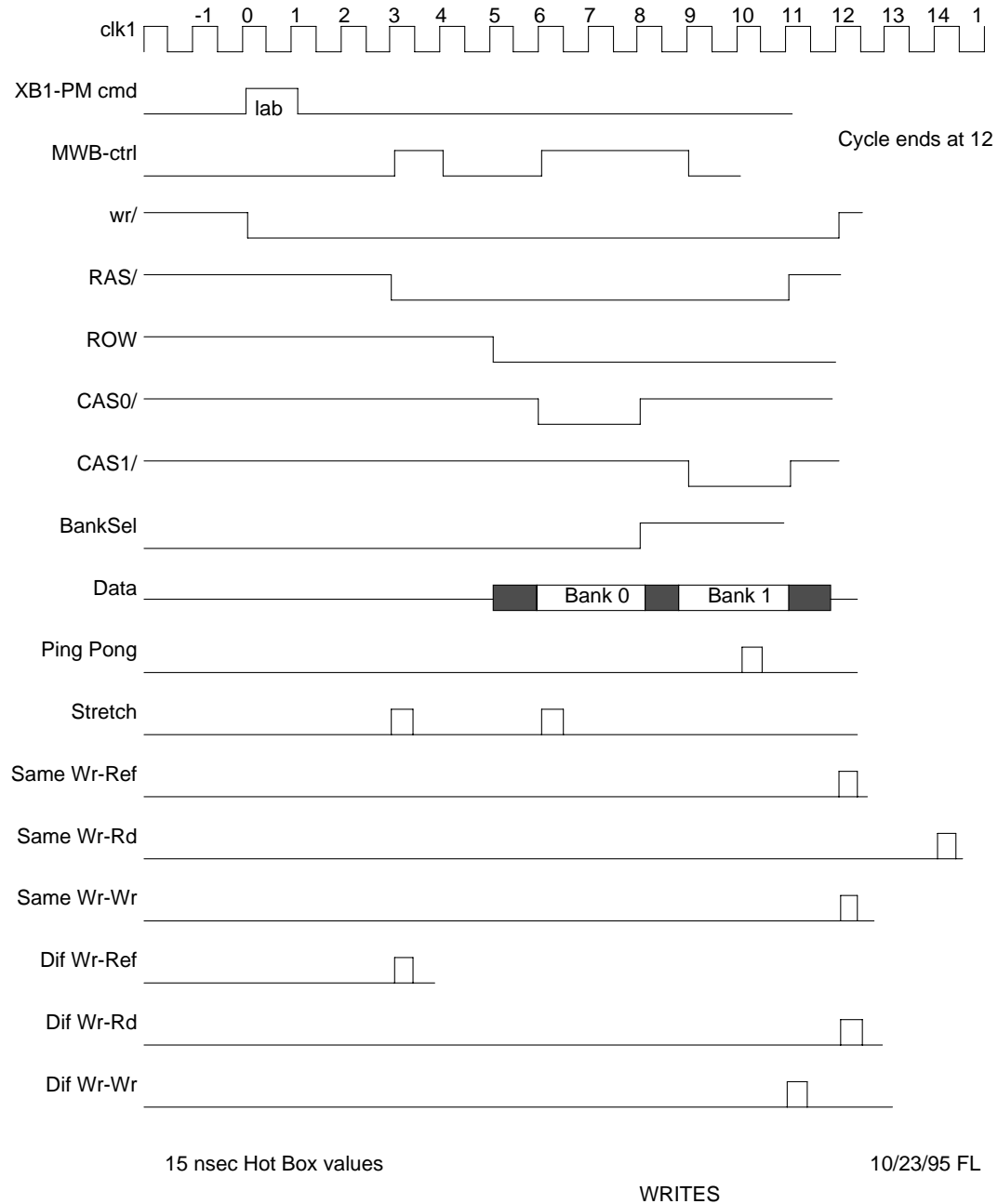
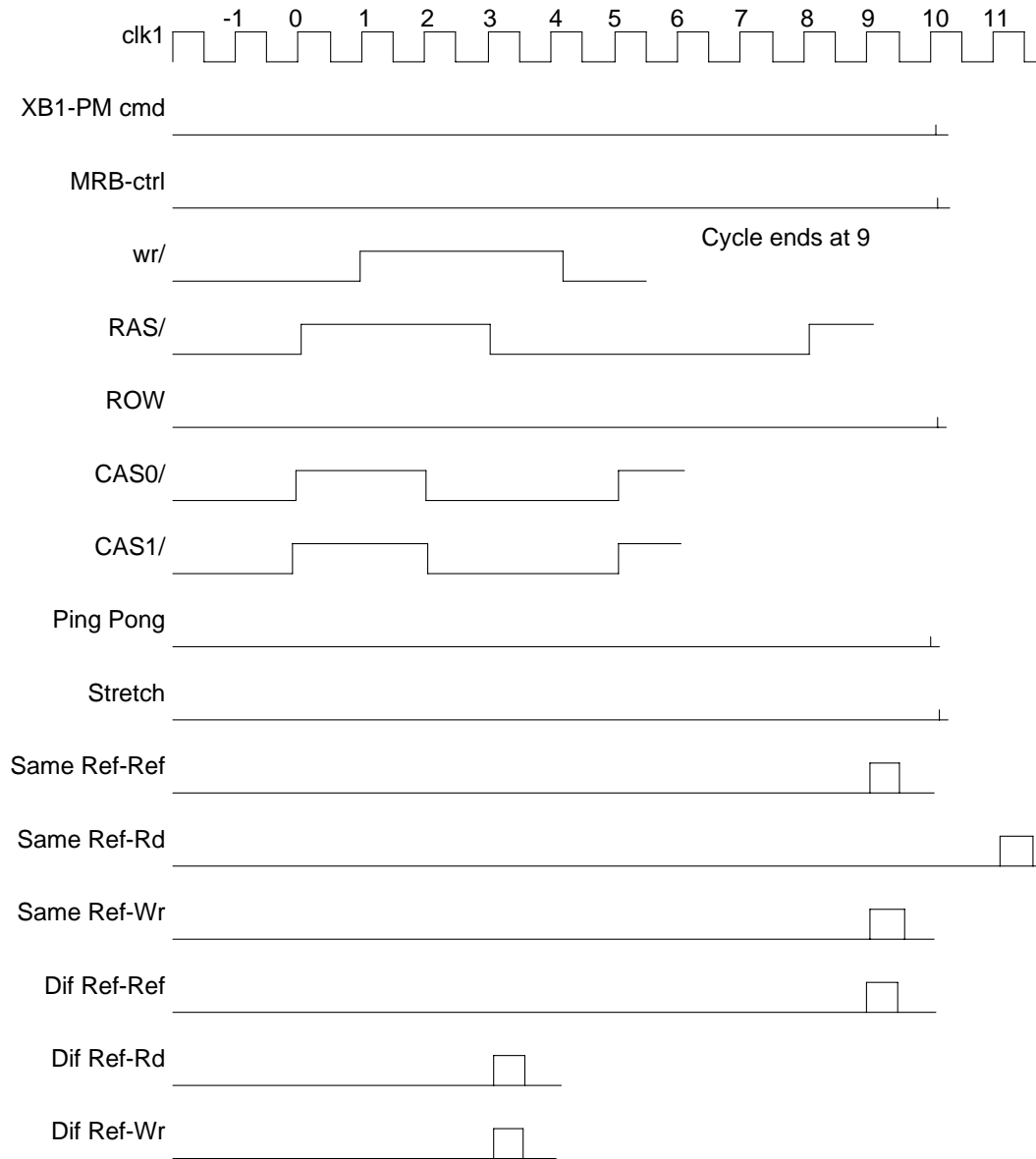


Figure 47. 15 NSec Refresh Timing



15 nsec Hot Box values

REFRESH

10/23/95 FL

100 MHz DSC TIMING EXAMPLES AND NOTES

This CSR timing set is for the Ultra 2 “Hot Box”. The CPU modules run at 200 MHz in 2:1 mode producing a UPA frequency of 100 MHz.

CSRs for 100 MHz DSC

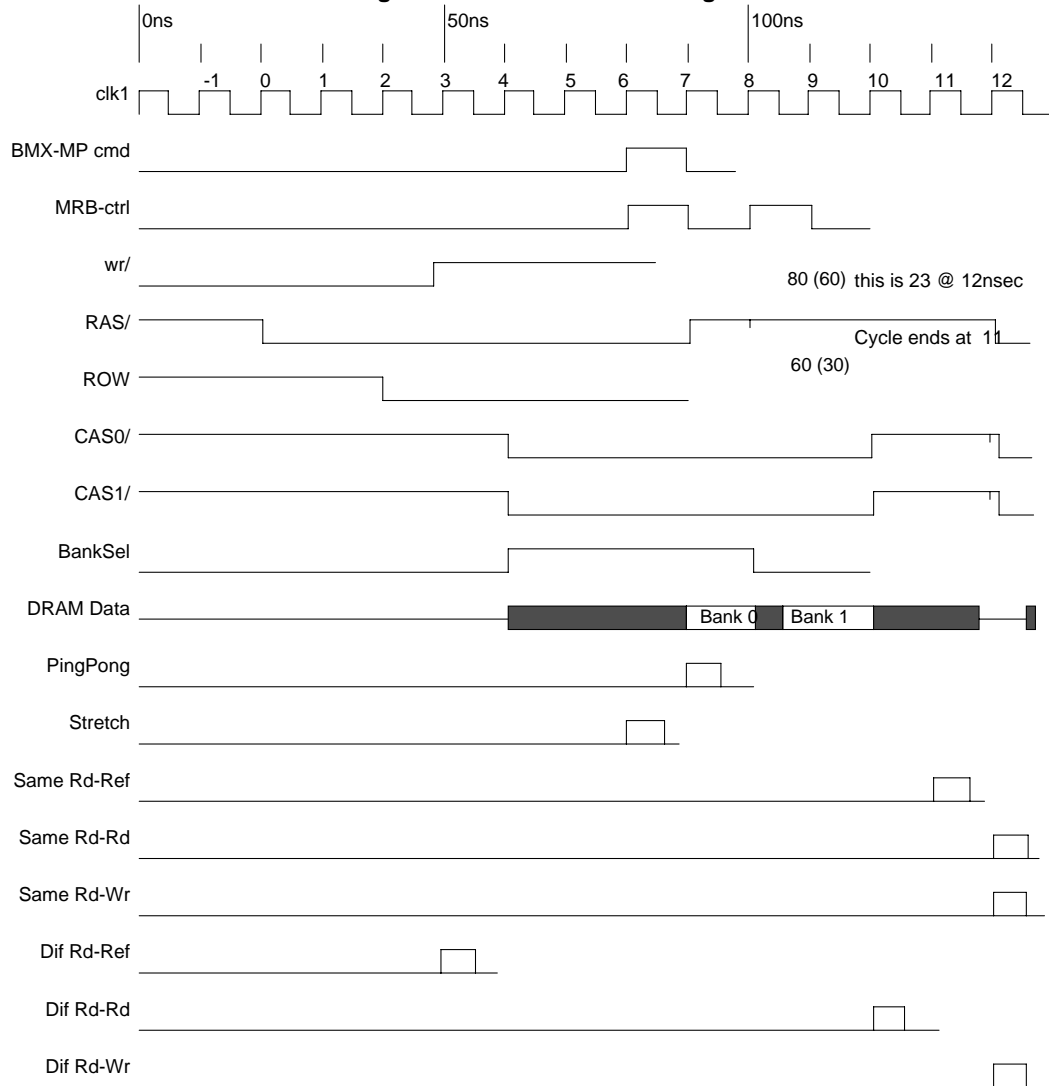
The optimized set of Memory CSRs for DSC at a UPA speed of 100 MHz is shown below. Note that these CSRs will not work with earlier DSC Rev 0 or 1.

TABLE 2: CSR values for DSC Rev 3 at 100 MHz UPA

Address	Value (Hex)	Function
80	a0c1 0f18	Mem_Control0
84	51b7 2525	RAS_Control
88	0000 2da5	CAS_RD_Control
8c	4a36 26a2	BankSel_Control
90	3128 249c	XB1_Buffer_Control
94	255d a547	CAS_WR_Control
98	14ac 0270	Phase_Level_Control
9c	02d6 220a	SIMM_Busy_Rd_Control
a0	0603 1187	Count_Control
a4	c913 2d29	Refresh_Control
a8	4db5 6493	Row_Control
b0	02a6 29aa	SIMM_Busy_Wr_Control
b4	14a0 85a9	SIMM_Busy_Refr_Control

These CSR values were used when generating Figure 48. to Figure 50.

Figure 48. 10 NSec Read Timing



RAS path: SCMP clk to out = 6 ; measured wire and SIMM buffer delay (resistor to DRAM) = 9; total = 15ns

Data path: measured wire and CBT delay (DRAM to BMX) = 4 ; BMX setup = 4ns; total = 8ns

GRAND TOTAL: add 19 ns to all DRAM access times.

Limiting factor is RAS to data: 1 ns margin

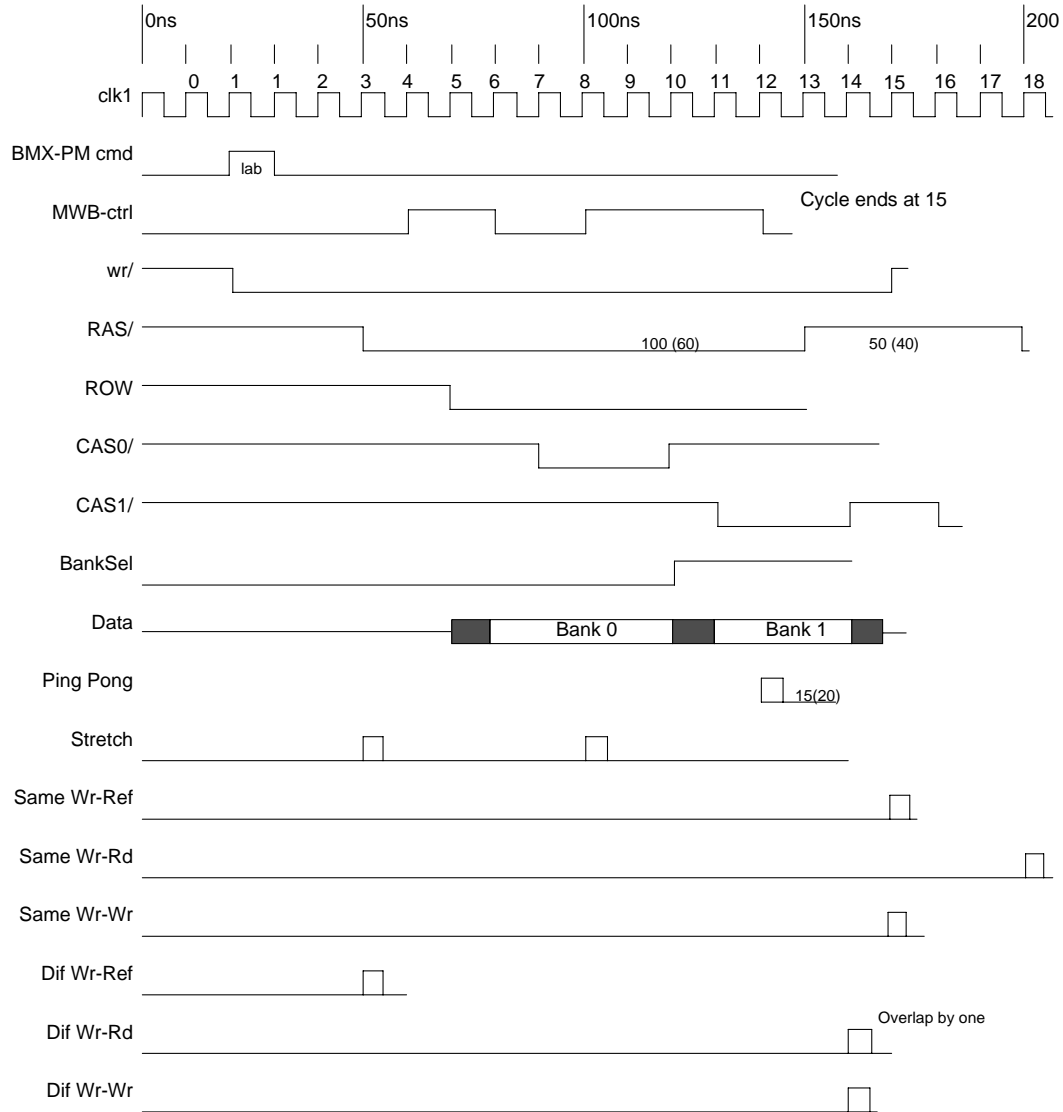
Measured 12/20; RAS: SCMP UPA Clk+ to DRAM = 7.8; ADDR: 8.65; DATA: BMX UPA Clk+ to DRAM = 7.

100 MHz screen on SCMP and BMX give + 4 Nsec margin on above path; 2 on SCMP clk to out, 2 on BMX

10 nsec UPA values

READS

Figure 49. 10 NSec Write Timing



Stretch points are internally 2 clocks before they are shown here

Idle -> write cycles have one clock of first write stretch

Limiting factor is data hold from CAS; speeded at 15, but need 10 margin

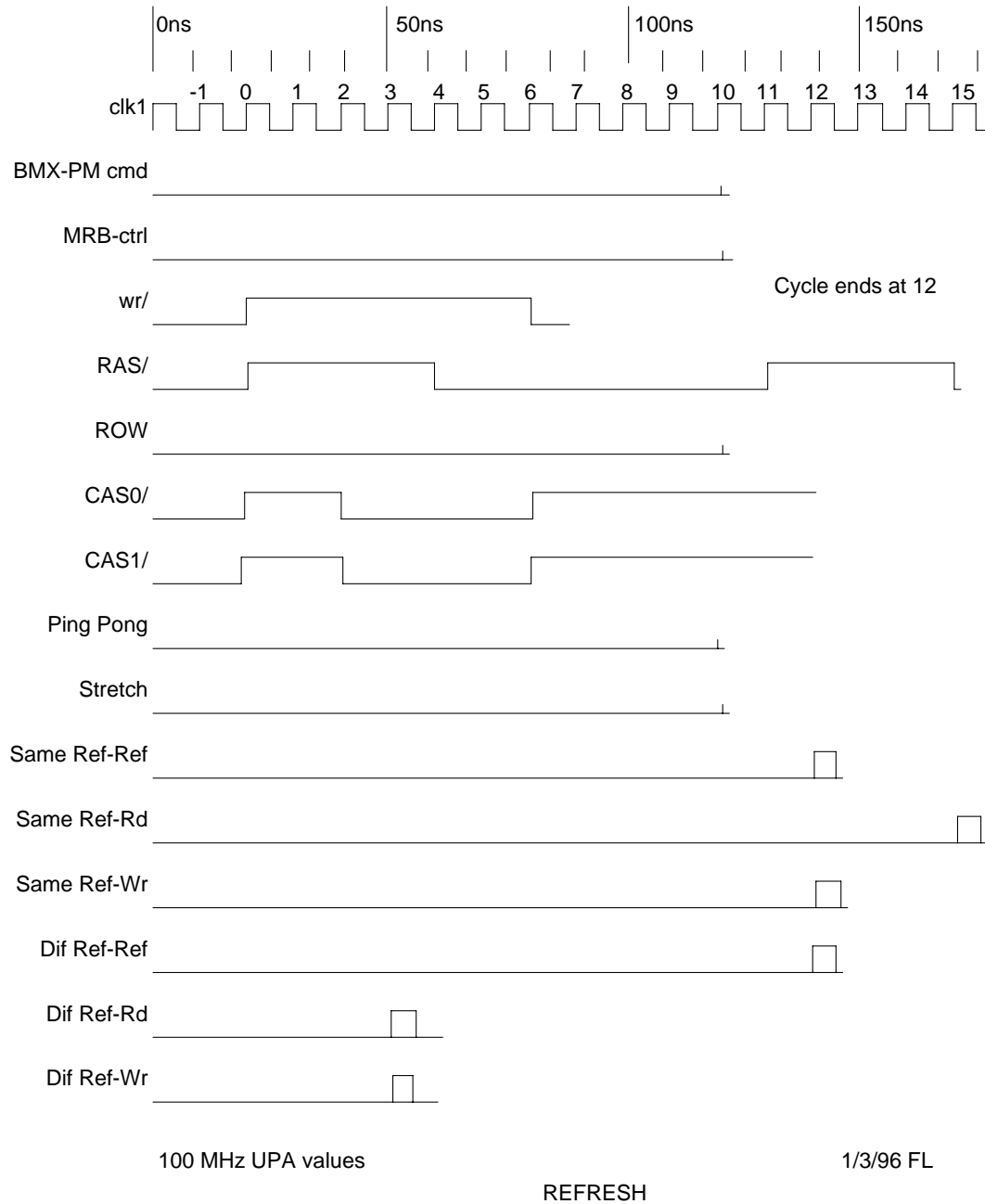
Limiting factor is CAS high from RAS low; speeded at 60

100 Mhz UPA 10 ns values

WRITES

3/12/96 FL

Figure 50. 10 NSec Refresh Timing



MEMORY PEAK PERFORMANCE

The following tables show the peak bandwidths the DRAM memory system is capable of with the final released SCR set. Note that these are true instantaneous values taken from logic analyzer traces using two processors and picking times when the memory was driven to peaks by overlapping requests. Refresh cycles are completely overlapped and thus are not included in these values. Actual program measured Bcopy statistics will be less.

Cases of different group overlapping read and write and a concurrent refresh in a third group were observed proving the SIMM group independence of the DSC memory controller.

2 processor Pulsar at 167 MHz 2:1 mode:

Sustained Peak Bandwidth, 12ns cycle

Transaction	Same group of SIMMs	Different group of SIMMs
Memory Read	533MB/s	667 MB/s
Memory Write	444 MB/s	444 MB/s
Bcopy	381 MB/s	427 MB/s

2 processor Pulsar at 200 MHz 3:1 mode:

Sustained Peak Bandwidth, 15ns cycle

Transaction	Same group of SIMMs	Different group of SIMMs
Memory Read	474 MB/s	610 MB/s
Memory Write	356 MB/s	356 MB/s
Bcopy	328 MB/s	356 MB/s

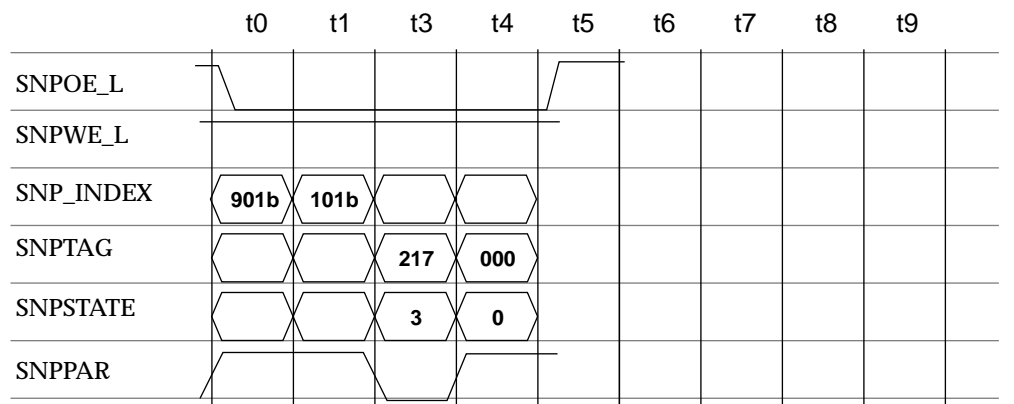
DTAG TIMING DIAGRAMS

The UPA cache coherence protocol is point-to-point write-invalidate. The unit of cache coherence is a block size of 64 bytes. Coherent read/write transactions transfer data in 64-byte blocks only, using 4 quadwords. In order to avoid snoop interference with a processor's cache Dual set of tags (Dtags) is maintained by SC_MP. The Dtags contain the 4 MOSI cache states (E & M states are merged) and Dtags support direct mapped cache.

A single 18-bit wide SRAM contains the Dtags for both processors. Since the tag and status bits are 15 bits wide, only one Dtag can be accessed each cycle. It will take two consecutive clock cycles to snoop the Dtags of both processors. For timing of the Dtag accesses, please see figures below.

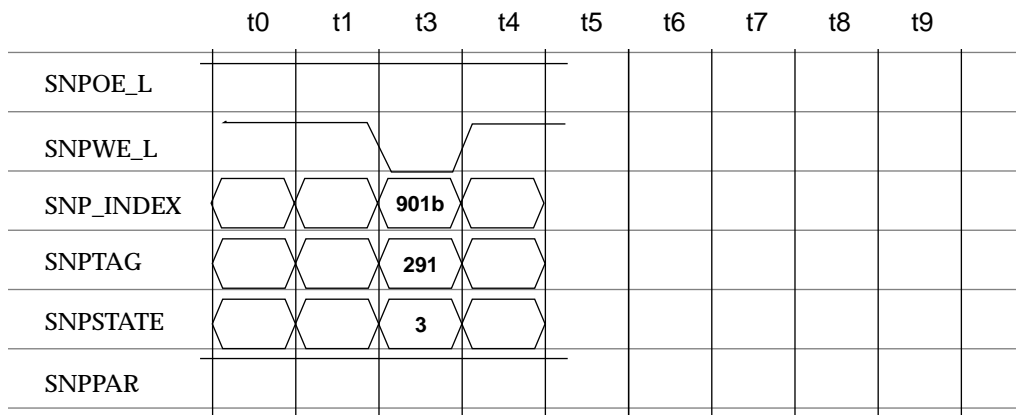
The DTAG is running at the same speed as the DSC clock, i.e. UPA clock. Its' clock input (SNP CLK) is generated by DSC. Some buffers have been inserted inside the Coherence Controller to position SNP CLK relative to DSC CLK to match required timing of DTAG SRAM. The SNP CLK should be ahead of the internal DSC CLK at least 150 ps but not more than 800 ps.

Figure 51. DTAG Read



- The MSB of SNP_INDEX imply Processor (0 => Proc 0, 1=> Proc 1)
- Values for SNP_INDEX from cycles t0/t1 is received in cycles t3/t4

Figure 52. DTAG Write



- Data on SNP_INDEX, SNPTAG, SNPSTATE, SNPPAR during active SNPWE_L are written into DTAG

Figure 53. Coherent Read Request

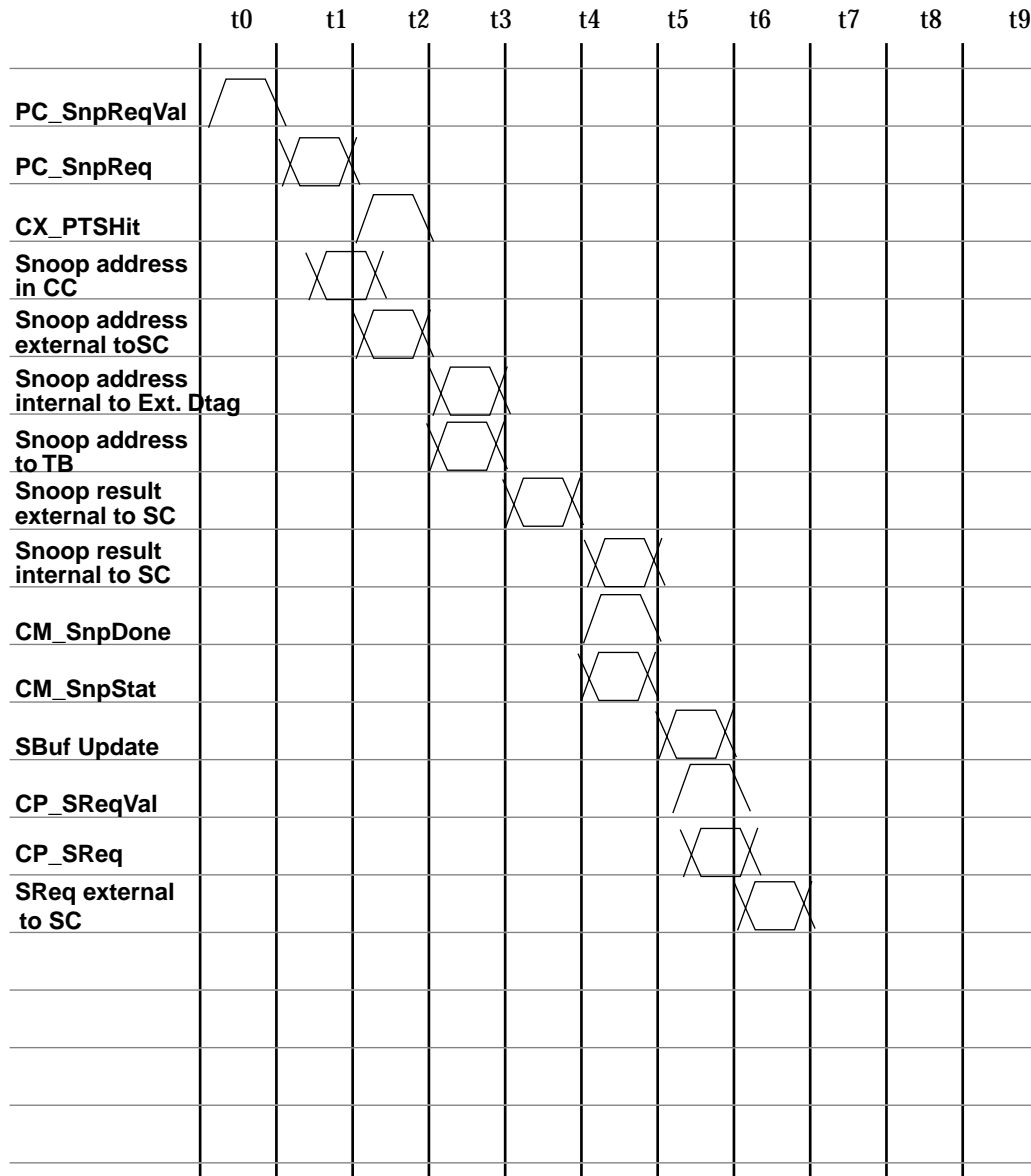


Figure 54. Update for Coherent Request

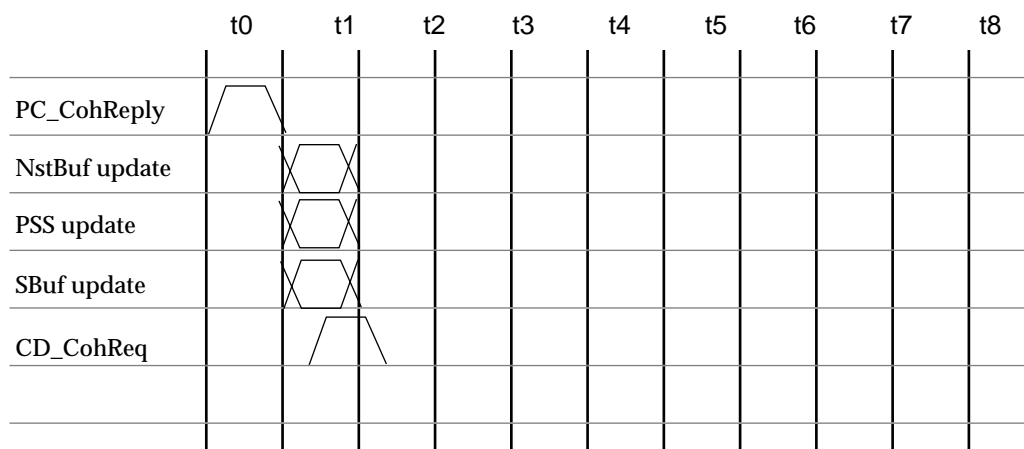


Figure 55. Updating DTAG

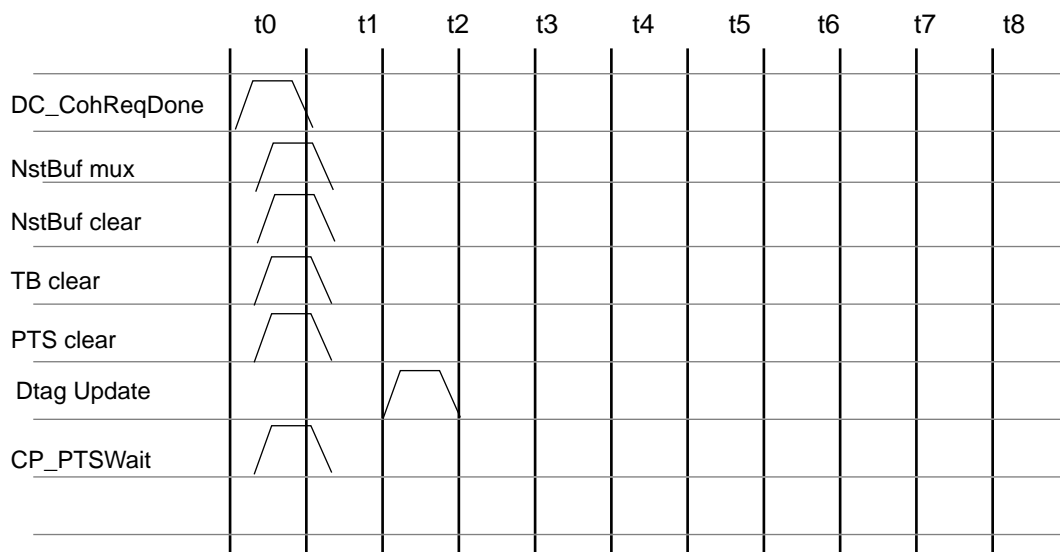


Figure 56. DTAG Parity Error

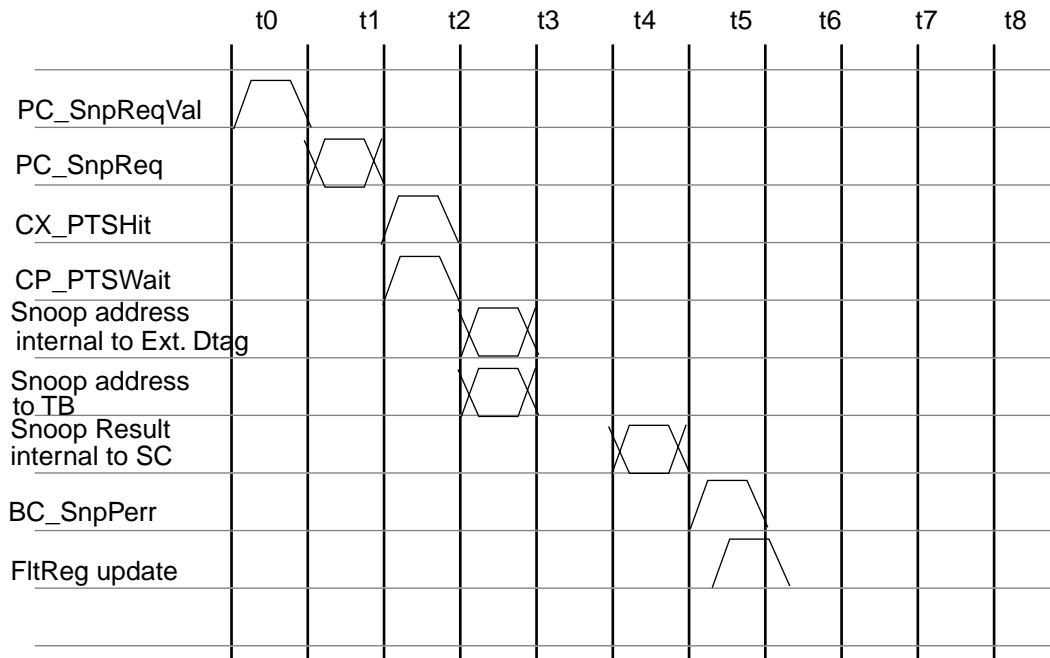


Figure 57. Four Consecutive RDS from P0 with DTAGs in I, S, O and M States

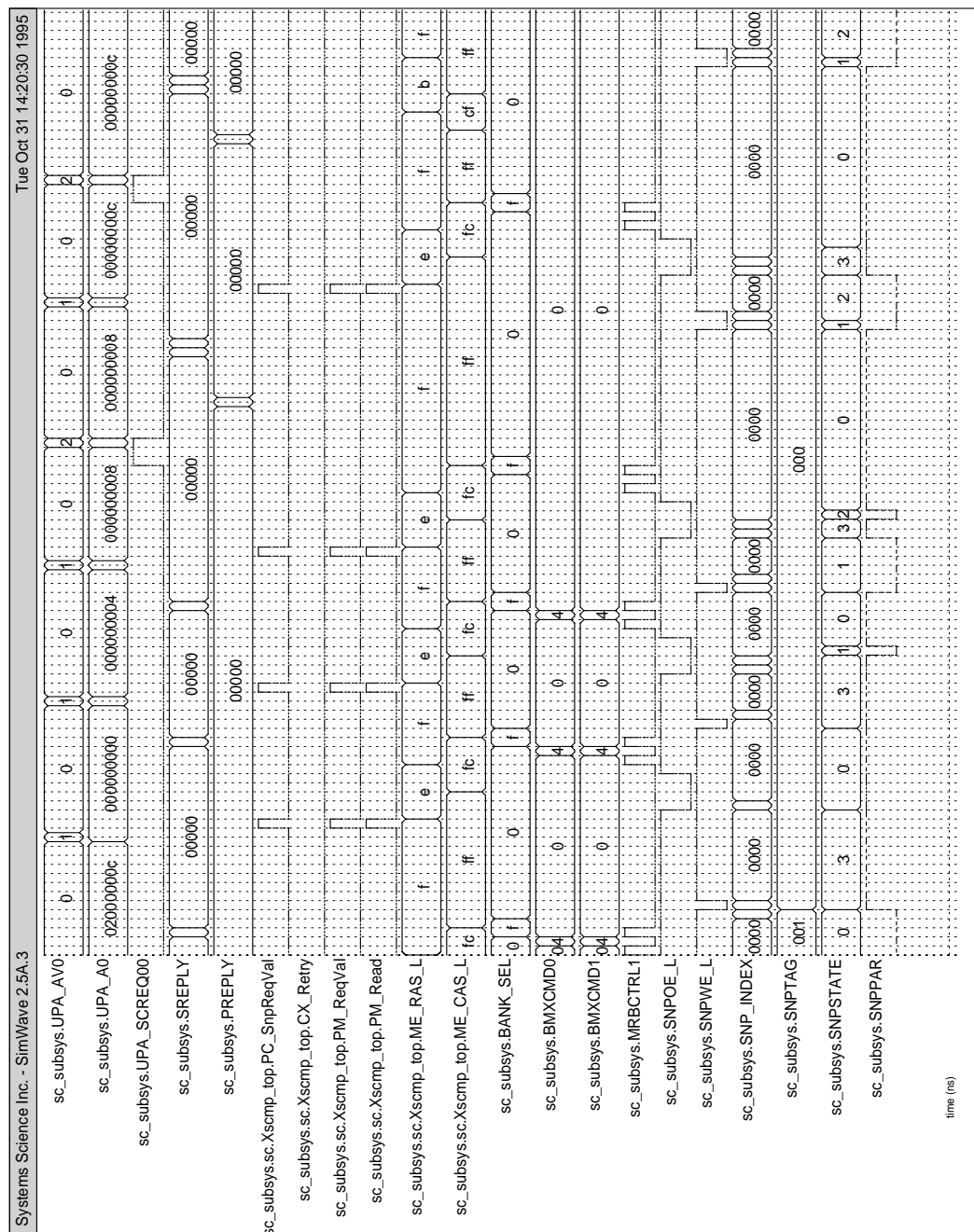


Figure 58. P0: RDS with Cancelled Memory Read; Data from P1 with CPB

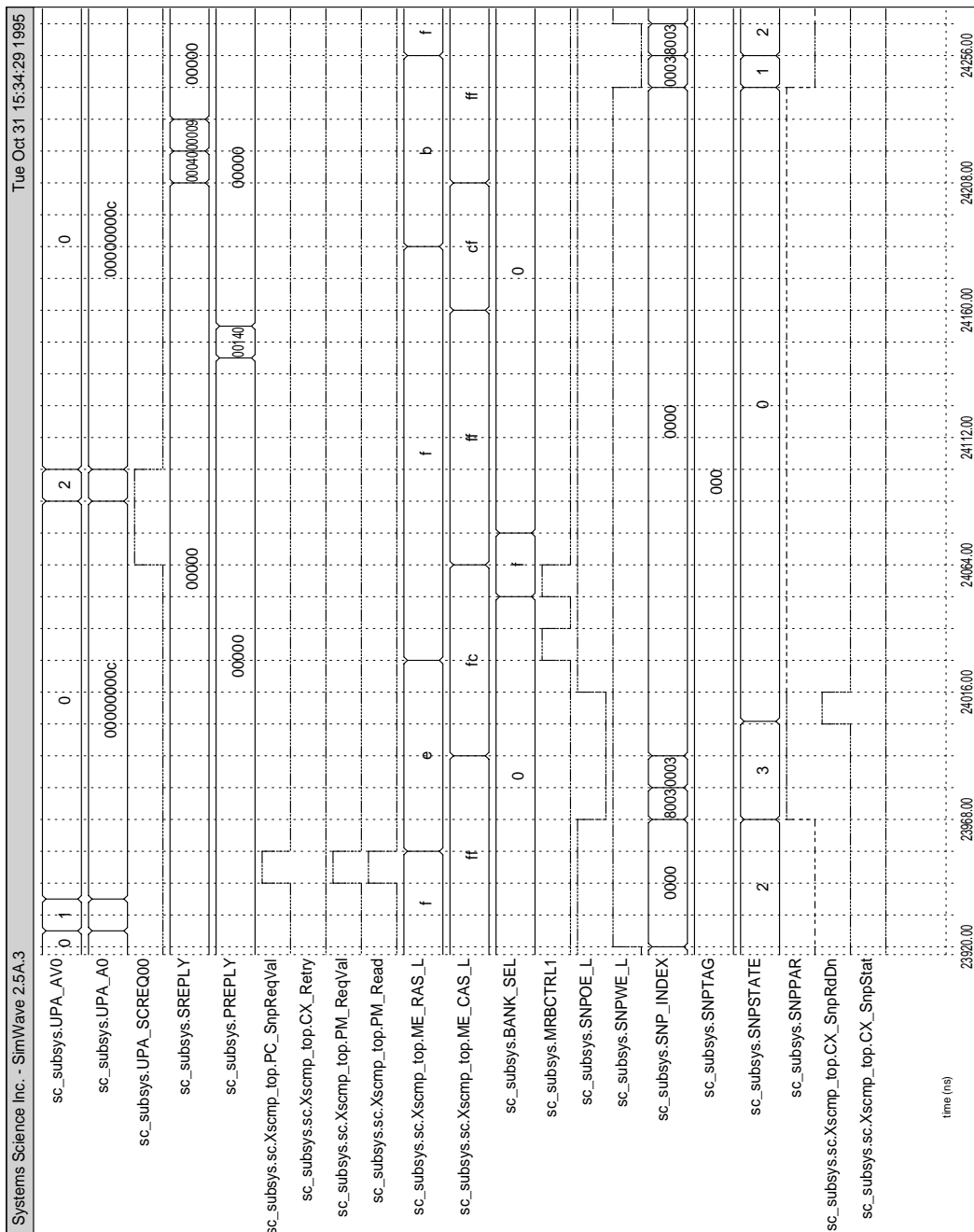


Figure 59. P0: 8x WRI; P1: 8x WRI, First 4 Addresses S in P0, Last 4 Addresses S in P1

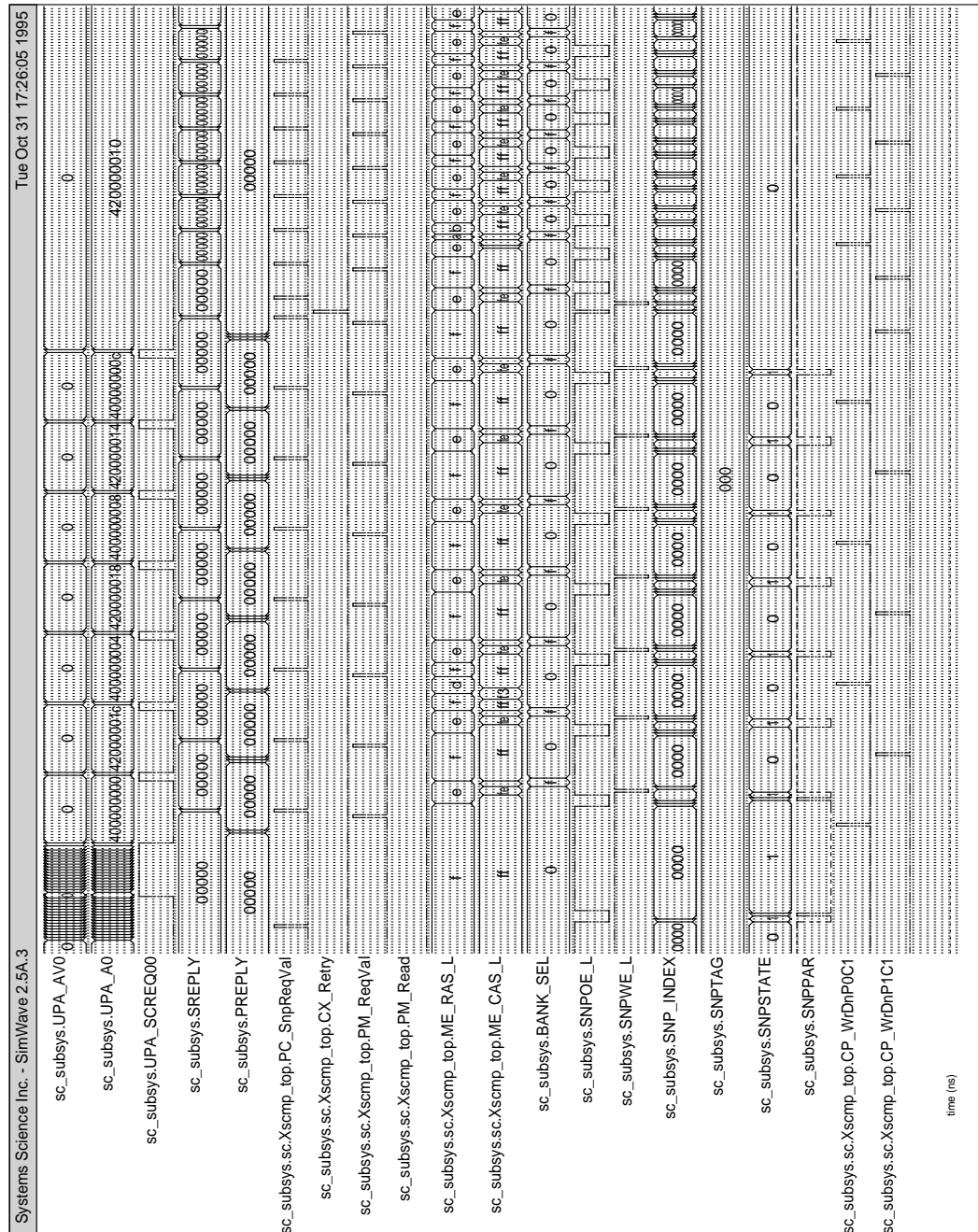


Figure 60. Coherence Error (Block is in M for Both CPUs) Creates Fatal Error - RESET

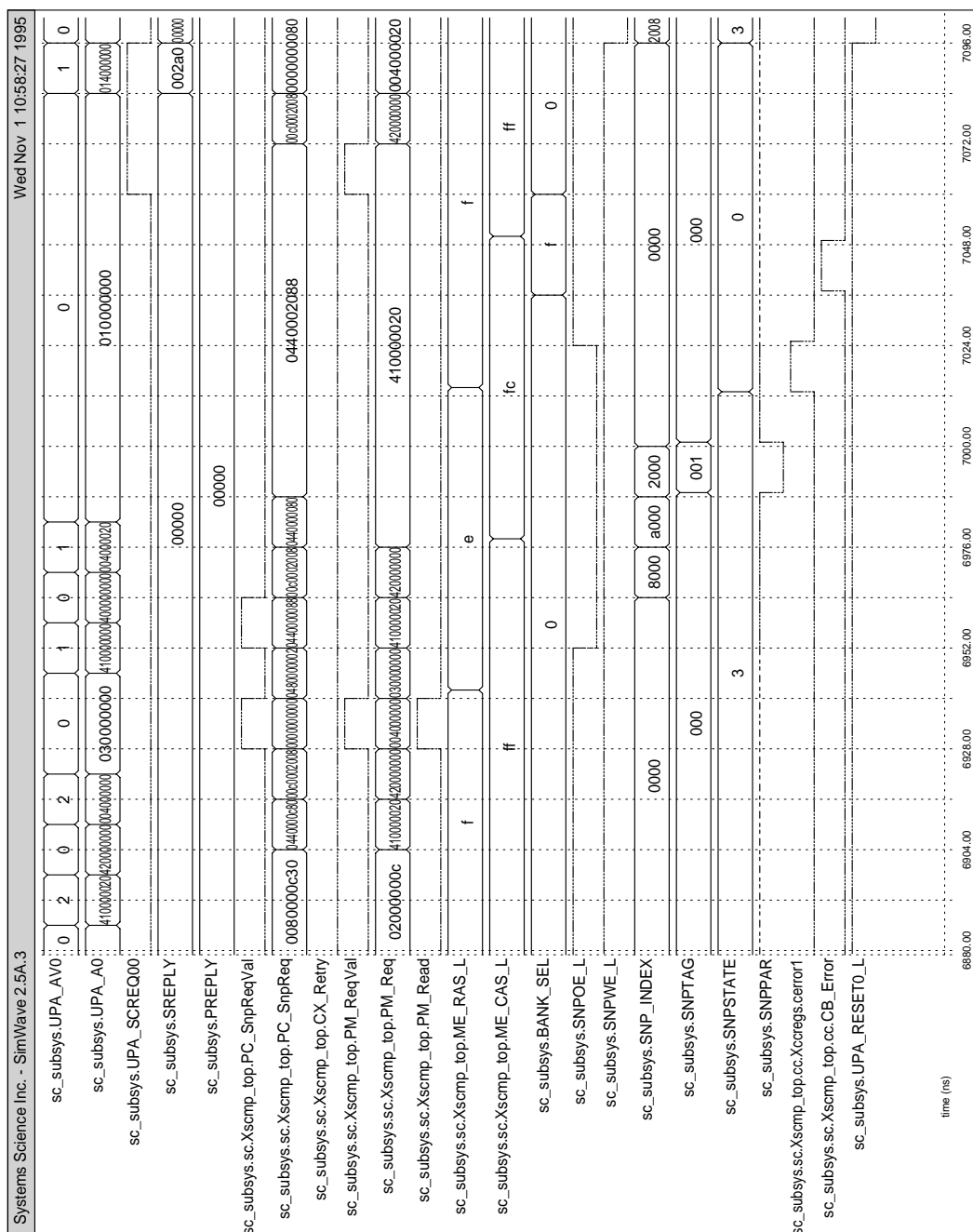


Figure 61. New Transaction Hits on Valid Entry in PTS (Same Index) and Gets CX_Retry

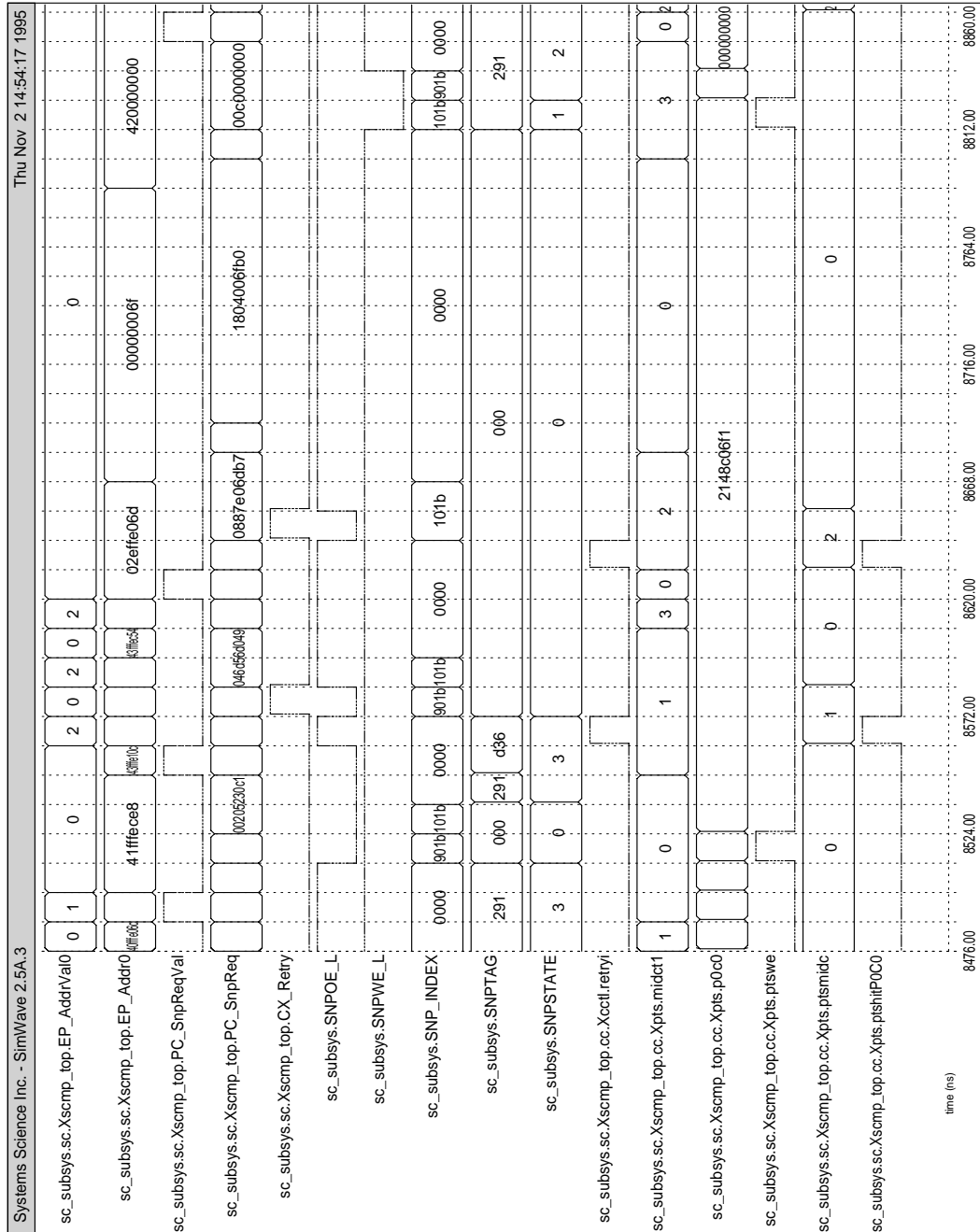
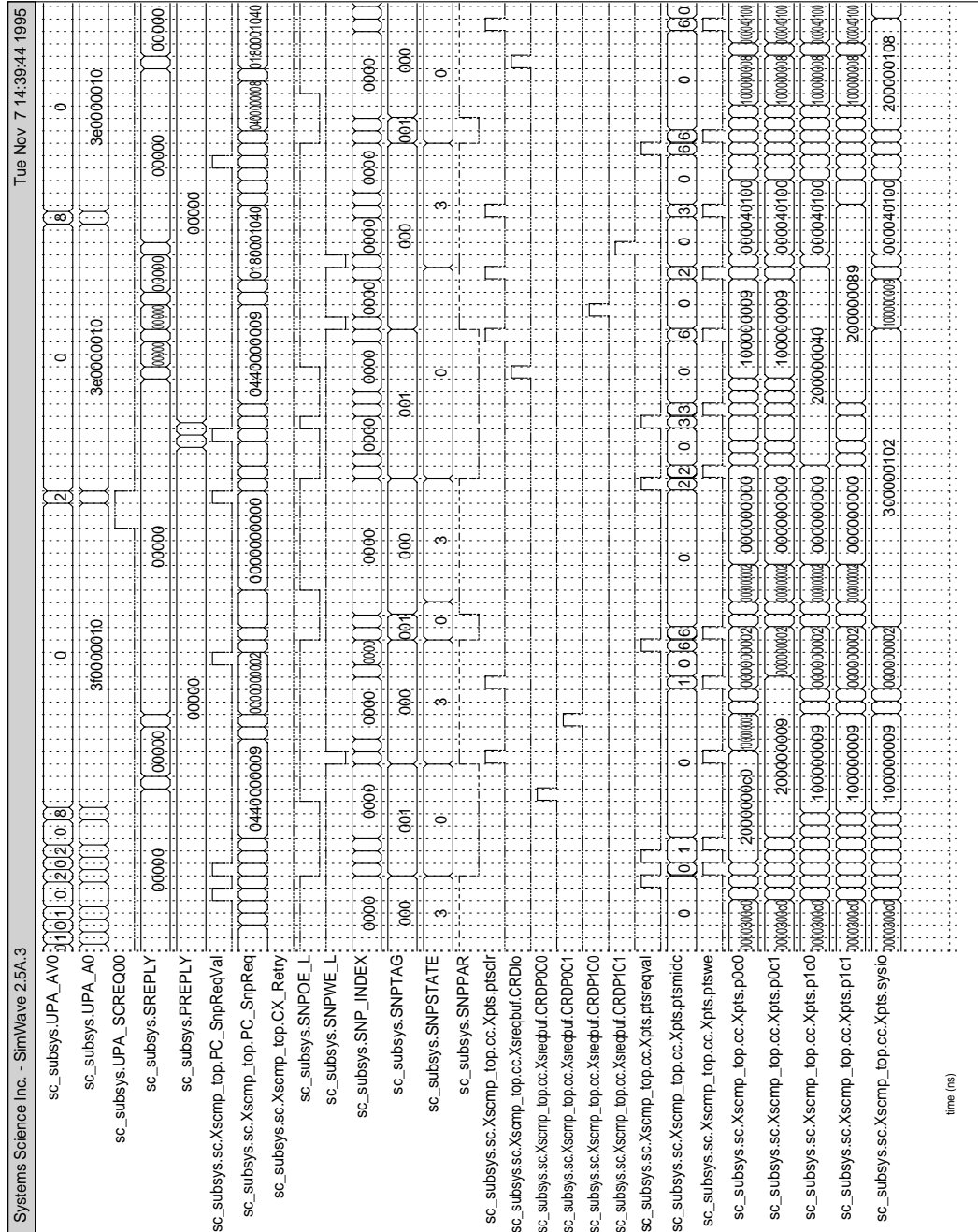


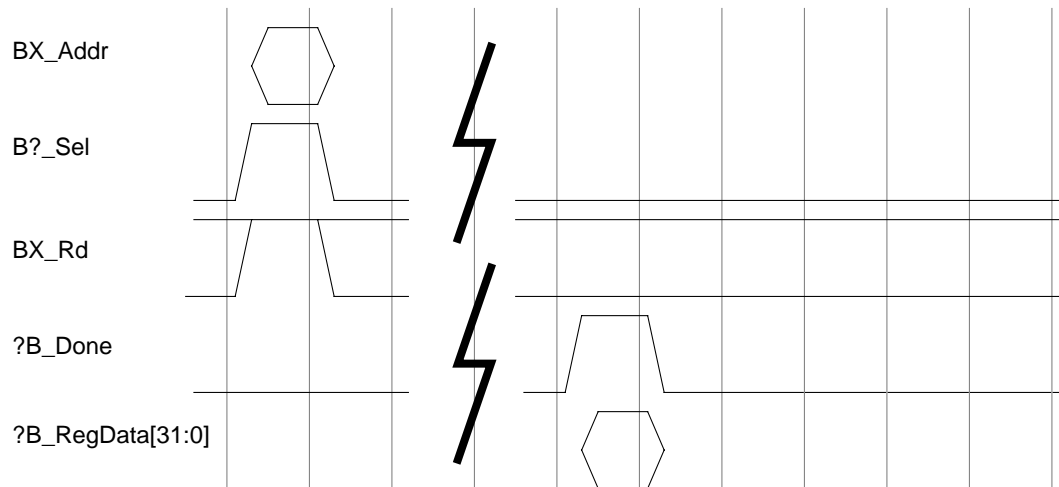
Figure 62. Exercise Pending Transaction Buffer with 5 Different Entries



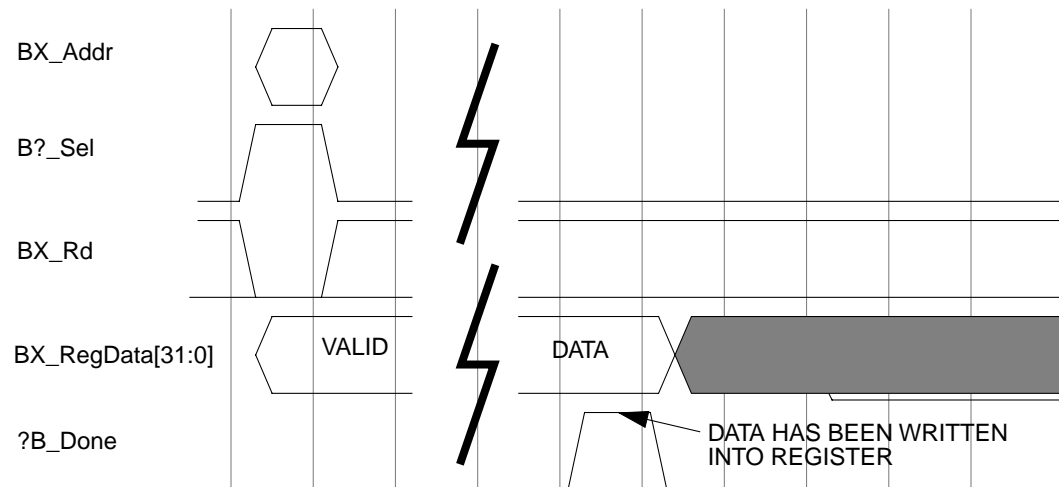
EBus Timing Diagrams

The timing diagrams below show both internal timing and external timing for EBus accesses.

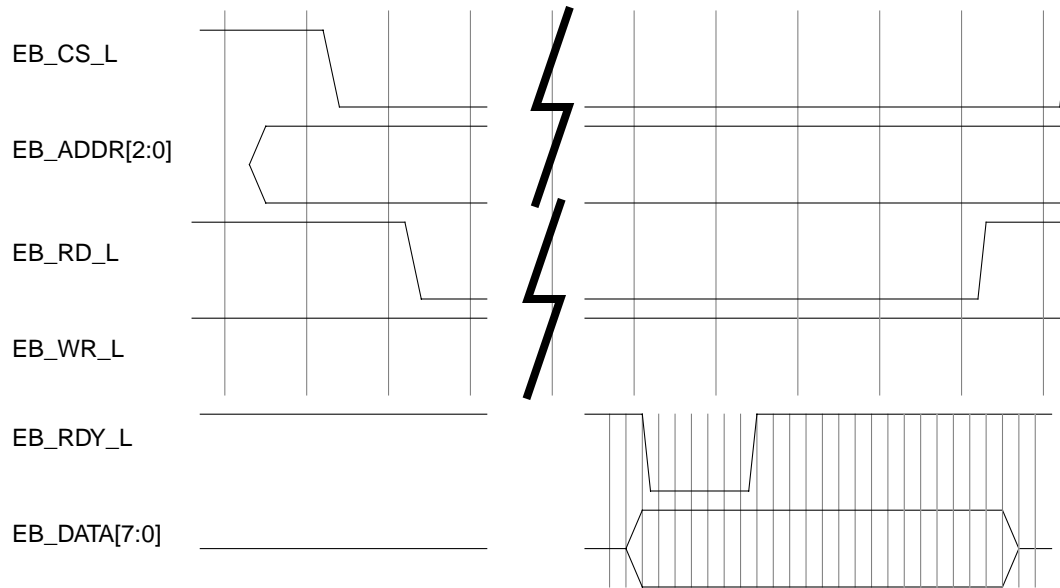
Internal Read Timing



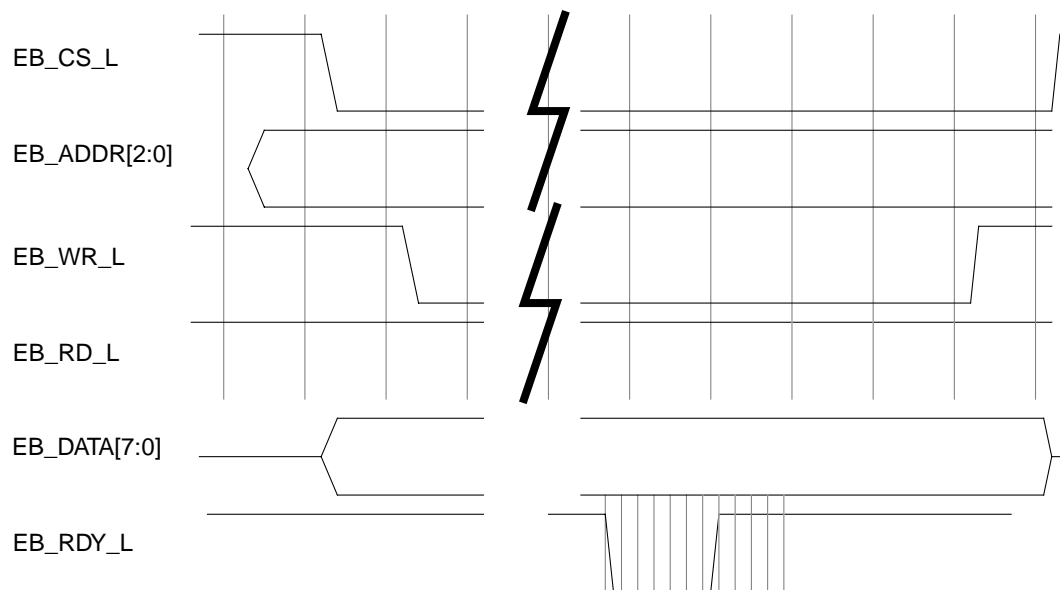
EBus Internal Write Timing



External EBus Read Timing



External EBus Write Timing



ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings

Parameter	Symbol	Limit	Unit
DC Supply Voltage	VDD	4.1	V
Input Voltage	Vin	(Vss - 0.3) to (Vdd + 0.3)	V
Storage Temp Range	Tstg	-40 to +125	°C
Clock Frequency	Tclk	45 to 100	MHz

Recommended Operating Conditions

Parameter	Symbol	Limit	Unit
DC Supply Voltage	VDD	3.3 ± 5%	V
Input Voltage	Vin	(Vss - 0.3) to (Vdd + 0.3)	V
Maximum Junction Temperature	Tj	105	°C
Maximum Operating Ambient Temperature	Ta	70	°C
DC Supply Voltage	VCC	5.0 ± 10%*	V

* Note: For 5V tolerant signals.

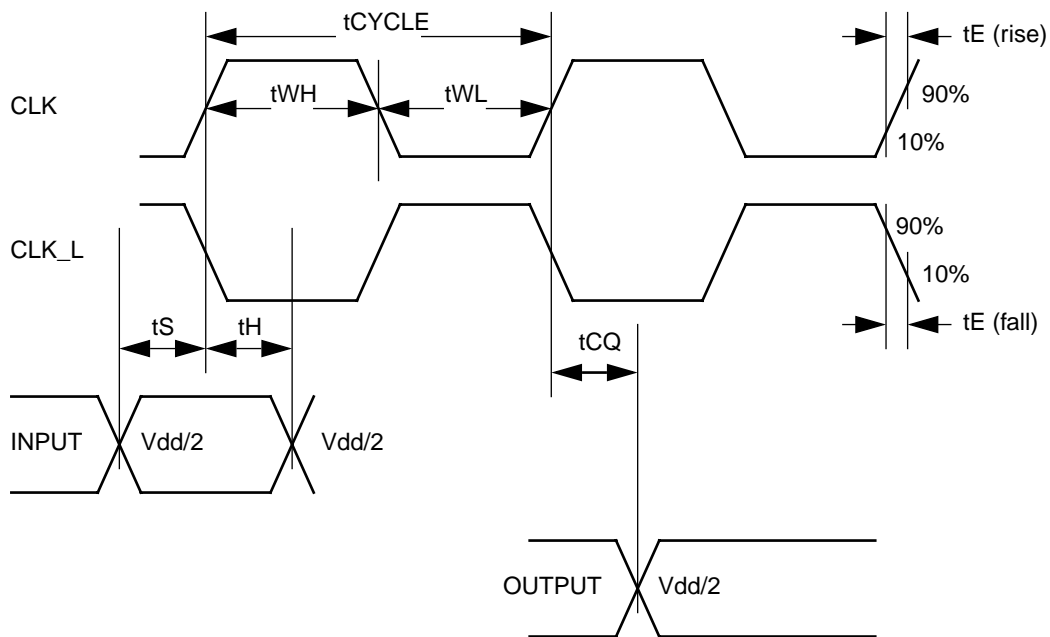
DC Characteristics

Symbol	Parameter	Condition	Min	Typ	Max	Unit
V _{IL}	Input Low Voltage (TTL inputs)				0.8	V
V _{IH}	Input High Voltage (TTL inputs)		2.0			V
V _{IL}	Input Low Voltage (PECL inputs)		Vdd - 1.81		Vdd - 1.475	V
V _{IH}	Input High Voltage (PECL inputs)		Vdd - 1.165		Vdd - 0.88	V
I _{IN}	Input Leakage Current				10	µA
V _{OL}	Output Low Voltage				0.4	V
V _{OH}	Output High Voltage		2.4			V
I _{OZ}	High Z Leakage Current				10	µA

DC Characteristics

Symbol	Parameter	Condition	Min	Typ	Max	Unit
I_{OS}	Short Circuit Current				20	mA
C_{IN}	Input Capacitance	any input			10	pF
C_{OUT}	Output Capacitance	any output			10	pF
I_{DD}	Supply Current				758	mA

Signal Timing Definition



AC Characteristics

Nearly all inputs and outputs are registered and are referenced to the PECL differential input clock (CLK and CLK_L). This clock input is also deskewed by the on-board PLL. All signals that are clocked by CLK/CLK_L are always referenced to the rising edge of CLK.

The only exceptions are the JTAG signals, which are referenced to JTAG_TCK, which does not have any PLL deskewing, and signals which are asynchronous with respect to DSC CLK/CLK_L or JTAG_TCK. These signals are:

1. EBUS_ADDR[2:0]
2. EBUS_CS_L
3. EBUS_RD_L

4. EBUS_WR_L
5. EBUS_DATA[7:0]
6. P_RESET_L
7. X_RESET_L
8. SYS_RESET_L
9. JTAG_TRST_L

For signals referenced to CLK/CLK_L, 500 ps has been added to setup, hold, and clock to output times to account for clock uncertainty introduced by the PLL and on-board clock skew within DSC.

All signals are referenced to the crossover between CLK and CLK_L (where both signals are at the same voltage). All inputs are applied with a rise and fall time of 1.0 ns.

AC Characteristics, Signals referenced to Rising Edge of CLK

Signal Name	Parameter	Condition	Min	Typ	Max	Unit
CLK/CLK_L	tCYCLE		45		100	MHz
CLK/CLK_L	tWH		5.4			ns
CLK/CLK_L	tWL		5.4			ns
CLK	tE	rising			200	ps
CLK_L	tE	falling			200	ps
CLK	tE	falling			600	ps
CLK_L	tE	rising			600	ps
CLK/CLK_L	tSKEW				50	ps
UPA_ADDRBUS0[34:0]	tSU		2.5			ns
UPA_ADDRBUS0[34:0]	tH		0.5			ns
UPA_ADDRBUS0[34:0]	tCQ	40 pF	0.5		6.1	ns
UPA_ADDRPAR0	tSU		2.5			ns
UPA_ADDRPAR0	tH		0.5			ns
UPA_ADDRPAR0	tCQ	40 pF	0.5		6.1	ns
UPA_ADDRVAL0[1:0]	tSU		2.5			ns
UPA_ADDRVAL0[1:0]	tH		0.5			ns
UPA_ADDRVAL0[1:0]	tCQ	40 pF	0.5		6.1	ns
UPA_PREPLY0[4:0]	tSU		2.5			ns
UPA_PREPLY0[4:0]	tH		0.5			ns
UPA_PREPLY1[4:0]	tSU		2.5			ns
UPA_PREPLY1[4:0]	tH		0.5			ns
UPA_PREPLY2[1:0]	tSU		2.5			ns

AC Characteristics, Signals referenced to Rising Edge of CLK (Continued)

Signal Name	Parameter	Condition	Min	Typ	Max	Unit
UPA_PREPLY2[1:0]	tH		0.5			ns
UPA_REQIN0[1:0]	tSU		2.5			ns
UPA_REQIN0[1:0]	tH		0.5			ns
UPA_ADDRVAL	tCQ	40 pF	0.5		6.1	ns
UPA_ADDRBUS1[28:0]	tCQ	40 pF	0.5		6.1	ns
UPA_DATASTALL0	tCQ	40 pF	0.5		6.1	ns
UPA_DATASTALL1	tCQ	40 pF	0.5		6.1	ns
UPA_ECCVALID0	tCQ	40 pF	0.5		6.1	ns
UPA_ECCVALID1	tCQ	40 pF	0.5		6.1	ns
UPA_RESET0_L	tCQ	40 pF	0.5		6.1	ns
UPA_RESET1_L	tCQ	40 pF	0.5		6.1	ns
UPA_SCREQ0	tCQ	40 pF	0.5		6.1	ns
UPA_SREPLY0[4:0]	tCQ	40 pF	0.5		6.1	ns
UPA_SREPLY1[4:0]	tCQ	40 pF	0.5		6.1	ns
UPA_SREPLY2[2:0]	tCQ	40 pF	0.5		6.1	ns
UPA_XIR_L	tCQ	40 pF	0.5		6.1	ns
BMXCMD0[3:0]	tCQ	70 pF			6.1	ns
BMXCMD1[3:0]	tCQ	70 pF			6.1	ns
MRBCTRL0	tCQ	70 pF			6.1	ns
MRBCTRL1	tCQ	70 pF			6.1	ns
MWBCTRL0	tCQ	70 pF			6.1	ns
MWBCTRL1	tCQ	70 pF			6.1	ns
MEMADDR[12:0]	tCQ	70 pF			6.1	ns
RAS_L[3:0]	tCQ	70 pF			6.1	ns
CAS_L[7:0]	tCQ	70 pF			6.1	ns
WE_L[3:0]	tCQ	70 pF			6.1	ns
SNP_INDEX[15:0]	tCQ				6.1	ns
SNPWE_L	tCQ				6.1	ns
SNPOE_L	tCQ				6.1	ns
SNPTAG[11:0]	tSU		2.5			ns
SNPTAG[11:0]	tH		0.5			ns
SNPTAG[11:0]	tCO	70 pF			6.1	ns

AC Characteristics, Signals referenced to Rising Edge of CLK (Continued)

Signal Name	Parameter	Condition	Min	Typ	Max	Unit
SNPSTATE[1:0]	tSU		2.5			ns
SNPSTATE[1:0]	tH		0.5			ns
SNPSTATE[1:0]	tCQ	70 pF			6.1	ns
SNPPAR	tSU		2.5			ns
SNPPAR	tH		0.5			ns
SNPPAR	tCQ	70 pF			6.1	ns
SNPCLK	tCQ				6.1	ns

AC Characteristics, Signals referenced to JTAG_TCK

Signal Name	Parameter	Condition	Min	Typ	Max	Unit
JTAG_TCK	tCYCLE				10.0	MHz
JTAG_TCK	tWH		30.0		70.0	ns
JTAG_TCK	tWL		30.0		70.0	ns
JTAG_TCK	tE	rising			20.0	ns
JTAG_TCK	tE	falling			20.0	ns
JTAG_TDI	tSU	wrt rising edge of JTAG_TCK	10			ns
JTAG_TDI	tH	wrt rising edge of JTAG_TCK	10			ns
JTAG_TMS	tSU	wrt rising edge of JTAG_TCK	10			ns
JTAG_TMS	tH	wrt rising edge of JTAG_TCK	10			ns
JTAG_TDO	tCQ	70 pF; wrt falling edge of JTAG_TCK			16.0	ns

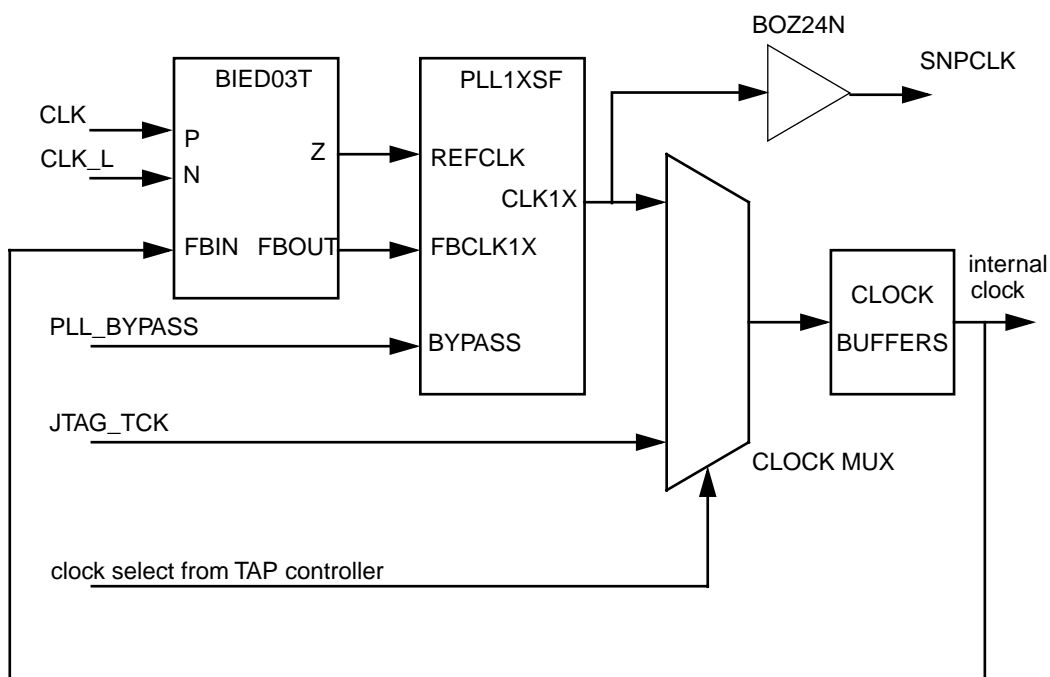
Power Dissipation

The power dissipation of DSC is 3.0 watts maximum.

PLL Specifications

PLL and Clock Distribution Circuitry

The schematic below shows the PLL and clock distribution scheme inside DSC.



PLL Recommended Operating Conditions

Parameter	Symbol	Limit	Unit
DC Supply Voltage	Vdd	3.3 ± 5%	V
Operating Junction Temperature Range	Tj	0 to 105	°C
Operating Frequency Range (nominal freq = 83.3 & 100MHz)	Fo	55 to 100	MHz

PLL DC Characteristics

Symbol	Parameter	Min	Typ	Max	Unit
VIL	LVTTL low - BYPASS			0.8	V
VIH	LVTTL high- BYPASS	2.0			V
VIL	LVPECL low - PECL CLK IN	Vdd - 1.810		Vdd - 1.475	V
VIH	LVPECL high - PECL CLK IN	Vdd - 1.165		Vdd - 0.88	V
PECL	LVPECL rise and fall times	0.2		0.6	ns

PLL AC Characteristics

Parameter	Min	Typ	Max	Unit
Total jitter and clock skew over operation range.	-500		+500	ps
Prop delay during BYPASS mode	tbd		tbd	ns
Initial Startup time			250	us
Transition Startup time (from bypass to normal mode)			250	us
Output Duty Cycle	45		55	%
Output loading			300	pf

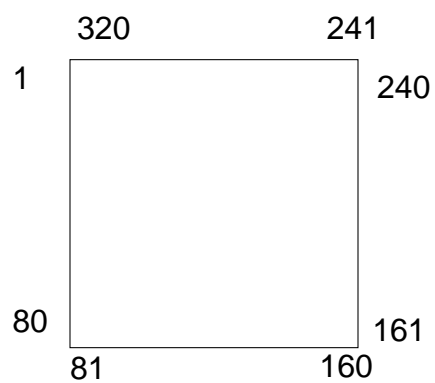
Mechanical Information

Pad Ring Assignments

Pad ring numbers and their associated ball numbers are shown below.

STP2202ABGA

DSC
Dual Processor System Controller



Pad Ring Numbering (AT&T Style)

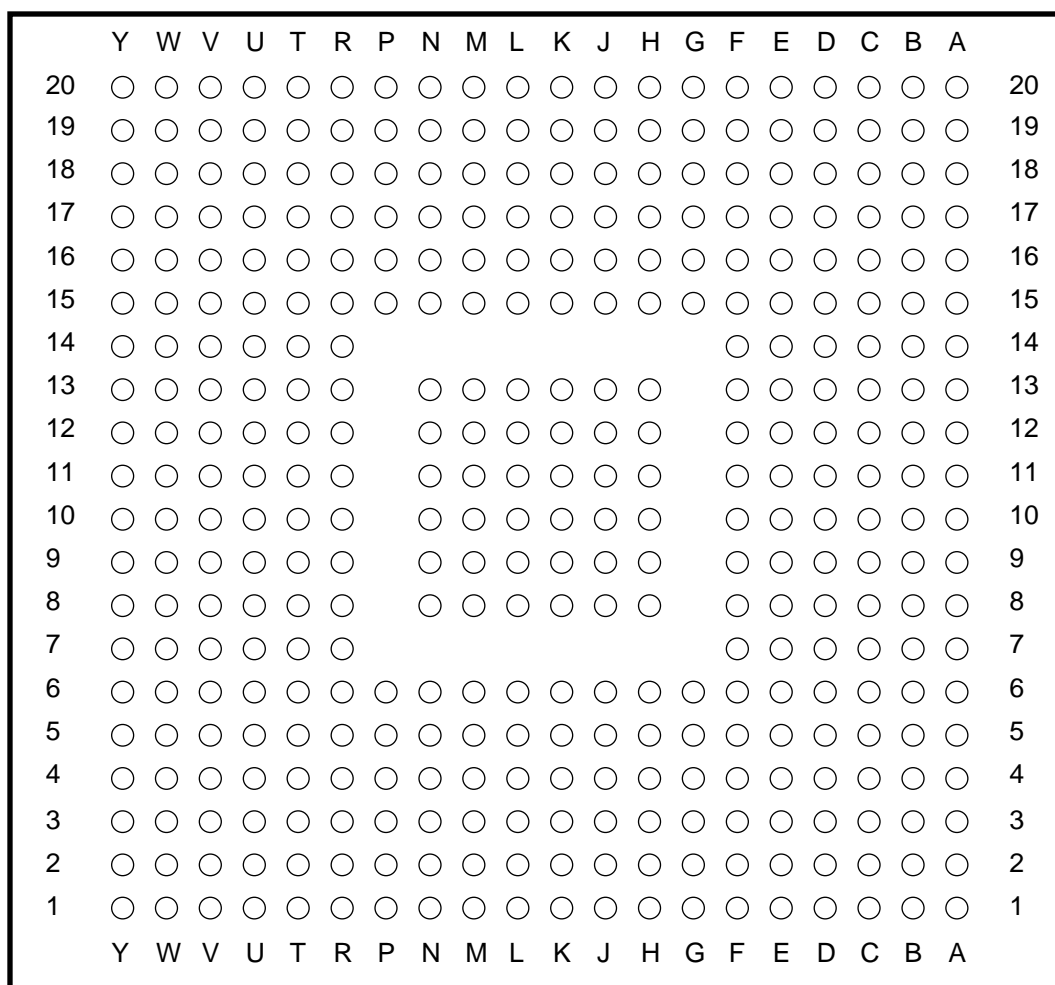
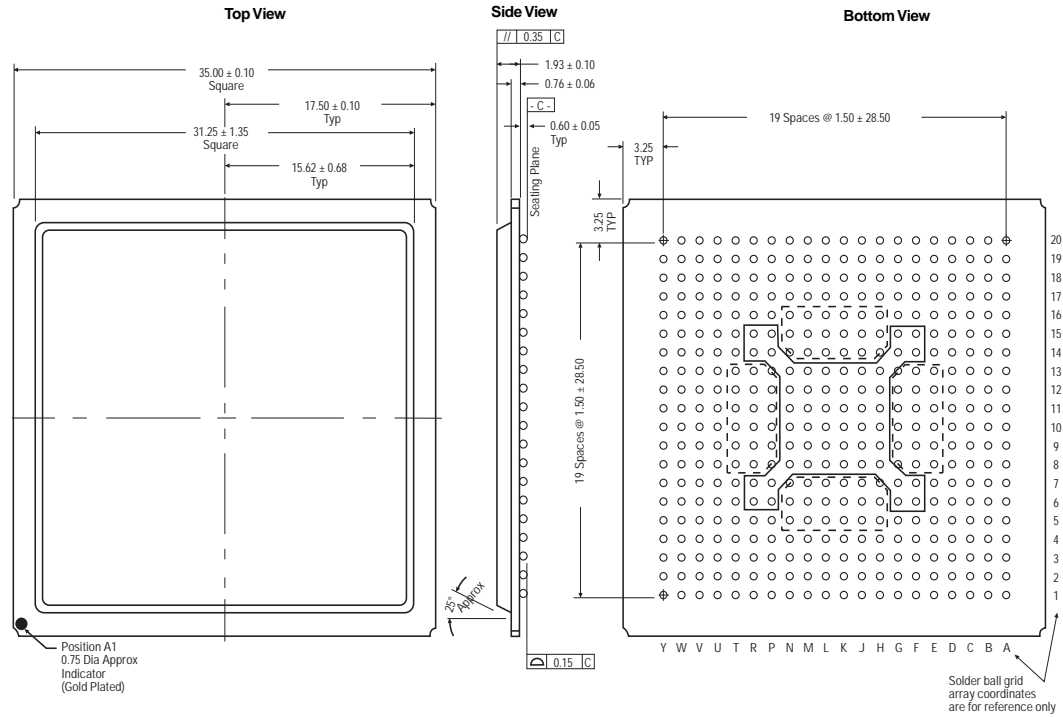


Figure 63. Footprint (Bottom View)

Dimensions



I/O Buffer Specifications

I/O buffers used in the DSC

Driver Type	I/O	drive (mA)	5V tolerant	Description
B5IN03Y	I	---	Y	LVTTTL Input
BIED03Y	I	---	N	PECL Input buffer (for clock)
BIN02Y	I	---	N	LVTTTL Input
BIN06N	I	---	N	LVTTTL Input
PINA02N/Y	I	---	N	LVTTTL Input w/50K Ω pullup
PINX06Y	I	---	N	LVTTTL Input w/50K Ω pulldown
B5OZ10N/L	O	8	Y	Output

I/O buffers used in the DSC

Driver Type	I/O	drive (mA)	5V tolerant	Description
BON10Y	O	10	N	Output
BOZ24N/L/Y	O	24	N	Output
BN02Z24N/L/Y	I/O	24/24	N	Bidirectional, no bus-hold
B5N3Z10Y	I/O	10/8	Y	Bidirectional, no bus-hold
P4OZ24N/Y	I/O	24/24	N	Bidirectional, no bus-hold. Tuned for driving transmission line load

Note that buffers with the suffix N, L or Y in the driver type will have identical function, but the die layout will be slightly different.

PINOUT TABLE

TABLE 3: Pinout Table

Bond pad	Ball pad	Signal Name	Type	I/O buffer
1	VDD	VDD	VDD	*****
2	D18	UPA_SREPLY3[2]	OUT	BOZ24N
3	A20	UPA_SREPLY3[1]	OUT	BOZ24L
4	C18	UPA_SREPLY3[0]	OUT	BOZ24Y
5	D17	UPA_SREPLY2[4]	OUT	BOZ24Y
6	VSS	VSS	VSS	*****
7	A19	UPA_SREPLY2[3]	OUT	BOZ24Y
8	C17	UPA_SREPLY2[2]	OUT	BOZ24Y
9	B18	UPA_SREPLY2[1]	OUT	BOZ24Y
10	VDD	VDD	VDD	*****
11	E15	UPA_SREPLY2[0]	OUT	BOZ24Y
12	B17	UPA_SREPLY1[4]	OUT	BOZ24Y
13	D16	UPA_SREPLY1[3]	OUT	BOZ24Y
14	A17	UPA_SREPLY1[2]	OUT	BOZ24Y
15	VSS	VSS	VSS	*****
16	D15	UPA_SREPLY1[1]	OUT	BOZ24Y
17	C16	UPA_SREPLY1[0]	OUT	BOZ24Y
18	C15	UPA_SREPLY0[4]	OUT	BOZ24Y
19	VDD	VDD	VDD	*****
20	B16	UPA_SREPLY0[3]	OUT	BOZ24Y
21	E14	UPA_SREPLY0[2]	OUT	BOZ24Y
22	B15	UPA_SREPLY0[1]	OUT	BOZ24Y
23	D14	UPA_SREPLY0[0]	OUT	BOZ24Y
24	VSS	VSS	VSS	*****
25	A15	UPA_SCREQ00	OUT	BOZ24Y
26	C14	UPA_REQIN0[2]	IN	BIN02Y
27	D13	UPA_REQIN0[1]	IN	BIN02Y
28	VDD	VDD	VDD	*****
29	C13	UPA_REQIN0[0]	IN	BIN02Y
30	B14	UPA_ADDRVAL0[2]	IO	BB02Z24Y
31	B13	UPA_ADDRVAL0[1]	IO	BB02Z24Y
32	A13	UPA_ADDRVAL0[0]	IO	BB02Z24Y
33	VSS	VSS	VSS	*****
34	D11	UPA_ADDRPAR0	IO	BB02Z24Y
35	D12	UPA_ADDRBUS0[34]	IO	BB02Z24Y

TABLE 3: Pinout Table (Continued)

Bond pad	Ball pad	Signal Name	Type	I/O buffer
36	C12	UPA_ADDRBUS0[33]	IO	BB02Z24Y
37	VDD	VDD	VDD	*****
38	B12	UPA_ADDRBUS0[32]	IO	BB02Z24Y
39	A11	UPA_ADDRBUS0[31]	IO	BB02Z24Y
40	VSS	VSS	VSS	*****
41	D10	UPA_ADDRBUS0[30]	IO	BB02Z24Y
42	C11	UPA_ADDRBUS0[29]	IO	BB02Z24Y
43	B11	UPA_ADDRBUS0[28]	IO	BB02Z24Y
44	VDD	VDD	VDD	*****
45	A10	UPA_ADDRBUS0[27]	IO	BB02Z24Y
46	B10	UPA_ADDRBUS0[26]	IO	BB02Z24Y
47	D9	UPA_ADDRBUS0[25]	IO	BB02Z24Y
48	VSS	VSS	VSS	*****
49	C10	UPA_ADDRBUS0[24]	IO	BB02Z24Y
50	B9	UPA_ADDRBUS0[23]	IO	BB02Z24Y
51	C9	UPA_ADDRBUS0[22]	IO	BB02Z24Y
52	C8	UPA_ADDRBUS0[21]	IO	BB02Z24Y
53	VDD	VDD	VDD	*****
54	D8	UPA_ADDRBUS0[20]	IO	BB02Z24Y
55	A8	UPA_ADDRBUS0[19]	IO	BB02Z24Y
56	B8	UPA_ADDRBUS0[18]	IO	BB02Z24Y
57	VSS	VSS	VSS	*****
58	D7	UPA_ADDRBUS0[17]	IO	BB02Z24Y
59	B7	UPA_ADDRBUS0[16]	IO	BB02Z24Y
60	E7	UPA_ADDRBUS0[15]	IO	BB02Z24Y
61	C7	UPA_ADDRBUS0[14]	IO	BB02Z24Y
62	VDD	VDD	VDD	*****
63	C6	UPA_ADDRBUS0[13]	IO	BB02Z24Y
64	A6	UPA_ADDRBUS0[12]	IO	BB02Z24Y
65	D6	UPA_ADDRBUS0[11]	IO	BB02Z24Y
66	VSS	VSS	VSS	*****
67	B6	UPA_ADDRBUS0[10]	IO	BB02Z24Y
68	B5	UPA_ADDRBUS0[9]	IO	BB02Z24Y
69	A4	UPA_ADDRBUS0[8]	IO	BB02Z24Y
70	C5	UPA_ADDRBUS0[7]	IO	BB02Z24Y
71	VDD	VDD	VDD	*****

TABLE 3: Pinout Table (Continued)

Bond pad	Ball pad	Signal Name	Type	I/O buffer
72	B4	UPA_ADDRBUS0[6]	IO	BB0Z24Y
73	C4	UPA_ADDRBUS0[5]	IO	BB0Z24Y
74	A2	UPA_ADDRBUS0[4]	IO	BB0Z24Y
75	VSS	VSS	VSS	*****
76	D5	UPA_ADDRBUS0[3]	IO	BB0Z24Y
77	B3	UPA_ADDRBUS0[2]	IO	BB0Z24Y
78	C3	UPA_ADDRBUS0[1]	IO	BB0Z24L
79	E6	UPA_ADDRBUS0[0]	IO	BB0Z24N
80	VDD	VDD	VDD	*****
81	VSS	VSS	VSS	*****
82	D4	SPARE[1]	***	*****
83	A1	SPARE[0]	***	*****
84	B2	MWBCTRL1	OUT	BOZ24Y
85	E5	MWBCTRL0	OUT	BOZ24Y
86	VDD	VDD	VDD	*****
87	B1	MRBCTRL1	OUT	BOZ24Y
88	D3	MRBCTRL0	OUT	BOZ24Y
89	C2	MEMADDR1[12]	OUT	P4OZ24Y
90	VSS	VSS	VSS	*****
91	E4	MEMADDR1[11]	OUT	P4OZ24Y
92	D2	MEMADDR1[10]	OUT	P4OZ24Y
93	E3	MEMADDR1[9]	OUT	P4OZ24Y
94	D1	MEMADDR1[8]	OUT	P4OZ24Y
95	VDD	VDD	VDD	*****
96	F5	MEMADDR1[7]	OUT	P4OZ24Y
97	E2	MEMADDR1[6]	OUT	P4OZ24Y
98	F4	MEMADDR1[5]	OUT	P4OZ24Y
99	VSS	VSS	VSS	*****
100	F1	MEMADDR1[4]	OUT	P4OZ24Y
101	G5	MEMADDR1[3]	OUT	P4OZ24Y
102	F3	MEMADDR1[2]	OUT	P4OZ24Y
103	G4	MEMADDR1[1]	OUT	P4OZ24Y
104	VDD	VDD	VDD	*****
105	F2	MEMADDR1[0]	OUT	P4OZ24Y
106	G3	MEMADDR0[12]	OUT	P4OZ24Y
107	H4	MEMADDR0[11]	OUT	P4OZ24Y

TABLE 3: Pinout Table (Continued)

Bond pad	Ball pad	Signal Name	Type	I/O buffer
108	VSS	VSS	VSS	*****
109	H3	MEMADDR0[10]	OUT	P4OZ24Y
110	G2	MEMADDR0[9]	OUT	P4OZ24Y
111	H2	MEMADDR0[8]	OUT	P4OZ24Y
112	H1	MEMADDR0[7]	OUT	P4OZ24Y
113	VDD	VDD	VDD	*****
114	K4	MEMADDR0[6]	OUT	P4OZ24Y
115	J4	MEMADDR0[5]	OUT	P4OZ24Y
116	J3	MEMADDR0[4]	OUT	P4OZ24Y
117	VSS	VSS	VSS	*****
118	J2	MEMADDR0[3]	OUT	P4OZ24Y
119	K1	MEMADDR0[2]	OUT	P4OZ24Y
120	VDD	VDD	VDD	*****
121	L4	MEMADDR0[1]	OUT	P4OZ24Y
122	K3	MEMADDR0[0]	OUT	P4OZ24Y
123	K2	BANK_SEL[3]	OUT	BOZ24Y
124	VSS	VSS	VSS	*****
125	L1	BANK_SEL[2]	OUT	BOZ24Y
126	L2	BANK_SEL[1]	OUT	BOZ24Y
127	M4	BANK_SEL[0]	OUT	BOZ24Y
128	VDD	VDD	VDD	*****
129	L3	WE_L[3]	OUT	BOZ24Y
130	M2	WE_L[2]	OUT	BOZ24Y
131	M3	WE_L[1]	OUT	BOZ24Y
132	N3	WE_L[0]	OUT	BOZ24Y
133	VSS	VSS	VSS	*****
134	N4	CAS_L[7]	OUT	BOZ24Y
135	N1	CAS_L[6]	OUT	BOZ24Y
136	N2	CAS_L[5]	OUT	BOZ24Y
137	VDD	VDD	VDD	*****
138	P4	CAS_L[4]	OUT	BOZ24Y
139	P2	CAS_L[3]	OUT	BOZ24Y
140	P5	CAS_L[2]	OUT	BOZ24Y
141	P3	CAS_L[1]	OUT	BOZ24Y
142	VSS	VSS	VSS	*****
143	R3	CAS_L[0]	OUT	BOZ24Y

TABLE 3: Pinout Table (Continued)

Bond pad	Ball pad	Signal Name	Type	I/O buffer
144	R1	DEBUG[3]	OUT	BOZ24Y
145	R5	DEBUG[2]	OUT	BOZ24Y
146	VDD	VDD	VDD	*****
147	R2	DEBUG[1]	OUT	BOZ24Y
148	T2	DEBUG[0]	OUT	BOZ24Y
149	U1	RAS_L[3]	OUT	BOZ24Y
150	R4	RAS_L[2]	OUT	BOZ24Y
151	VSS	VSS	VSS	*****
152	V2	RAS_L[1]	OUT	BOZ24Y
153	T3	RAS_L[0]	OUT	BOZ24Y
154	W1	JTAG_TRST_L	IN	PINA02Y
155	VDD	VDD	VDD	*****
156	T4	JTAG_TDI	IN	PINA02Y
157	U2	JTAG_TCK	IN	BIN02Y
158	W2	JTAG_TDO	OUT	B5OZ10L
159	U4	JTAG_TMS	IN	PINA02N
160	VSS	VSS	VSS	*****
161	VDD	VDD	VDD	*****
162	U3	X_RESET_L	IN	BIN06N
163	Y1	UPA_XIR_L	OUT	BOZ24L
164	V3	SYS_RESET_L	IN	PINX06Y
165	T5	UPA_RESET1_L	OUT	BOZ24Y
166	VSS	VSS	VSS	*****
167	Y2	P_RESET_L	IN	BIN06Y
168	V4	PLL_BYPASS	IN	BIN06Y
169	W3	REF_5V	IN	*****
170	VDD	VDD	VDD	*****
171	U5	PLL_VDD	IN	*****
172	W4	CLK	IN	BIED03Y
173	U6	CLK_L	IN	BIED03Y
174	Y4	PLL_VSS	IN	*****
175	VSS	VSS	VSS	*****
176	T6	UPA_RESET0_L	OUT	BOZ24Y
177	V5	EBUS_RD_L	IN	B5IN03Y
178	V6	EBUS_WR_L	IN	B5IN03Y
179	VDD	VDD	VDD	*****

TABLE 3: Pinout Table (Continued)

Bond pad	Ball pad	Signal Name	Type	I/O buffer
180	W5	SNPCLK	OUT	BOZ24Y
181	T7	EBUS_ADDR[2]	IN	B5IN03Y
182	W6	EBUS_ADDR[1]	IN	B5IN03Y
183	U7	EBUS_ADDR[0]	IN	B5IN03Y
184	VSS	VSS	VSS	*****
185	Y6	EBUS_CS_L	IN	B5IN03Y
186	V7	EBUS_DATA[7]	IO	B5N3Z10Y
187	U8	EBUS_DATA[6]	IO	B5N3Z10Y
188	VDD	VDD	VDD	*****
189	V8	EBUS_DATA[5]	IO	B5N3Z10Y
190	W7	EBUS_DATA[4]	IO	B5N3Z10Y
191	W8	EBUS_DATA[3]	IO	B5N3Z10Y
192	Y8	EBUS_DATA[2]	IO	B5N3Z10Y
193	VSS	VSS	VSS	*****
194	U10	EBUS_DATA[1]	IO	B5N3Z10Y
195	U9	EBUS_DATA[0]	IO	B5N3Z10Y
196	V9	SNPPAR	IO	BB02Z24Y
197	VDD	VDD	VDD	*****
198	W9	SNPSTATE[1]	IO	BB02Z24Y
199	Y10	SNPSTATE[0]	IO	BB02Z24Y
200	VSS	VSS	VSS	*****
201	U11	SPARE[3]	***	*****
202	V10	SPARE[2]	***	*****
203	W10	PM_OUT	OUT	BON10Y
204	VDD	VDD	VDD	*****
205	Y11	SNPTAG[11]	IO	BB02Z24Y
206	W11	SNPTAG[10]	IO	BB02Z24Y
207	U12	SNPTAG[9]	IO	BB02Z24Y
208	VSS	VSS	VSS	*****
209	V11	SNPTAG[8]	IO	BB02Z24Y
210	W12	SNPTAG[7]	IO	BB02Z24Y
211	V12	SNPTAG[6]	IO	BB02Z24Y
212	V13	SNPTAG[5]	IO	BB02Z24Y
213	VDD	VDD	VDD	*****
214	U13	SNPTAG[4]	IO	BB02Z24Y
215	Y13	SNPTAG[3]	IO	BB02Z24Y

TABLE 3: Pinout Table (Continued)

Bond pad	Ball pad	Signal Name	Type	I/O buffer
216	W13	SNPTAG[2]	IO	BB0Z24Y
217	VSS	VSS	VSS	*****
218	V14	SNPTAG[1]	IO	BB0Z24Y
219	W14	SNPTAG[0]	IO	BB0Z24Y
220	T14	SNPOE_L	OUT	BOZ24Y
221	W15	SNPWE_L	OUT	BOZ24Y
222	VDD	VDD	VDD	*****
223	V15	SNP_INDEX[15]	OUT	BOZ24Y
224	Y15	SNP_INDEX[14]	OUT	BOZ24Y
225	U14	SNP_INDEX[13]	OUT	BOZ24Y
226	VSS	VSS	VSS	*****
227	W16	SNP_INDEX[12]	OUT	BOZ24Y
228	V16	SNP_INDEX[11]	OUT	BOZ24Y
229	Y17	SNP_INDEX[10]	OUT	BOZ24Y
230	U15	SNP_INDEX[9]	OUT	BOZ24Y
231	VDD	VDD	VDD	*****
232	W18	SNP_INDEX[8]	OUT	BOZ24Y
233	V17	SNP_INDEX[7]	OUT	BOZ24Y
234	Y19	SNP_INDEX[6]	OUT	BOZ24Y
235	VSS	VSS	VSS	*****
236	U16	SNP_INDEX[5]	OUT	BOZ24Y
237	W17	SNP_INDEX[4]	OUT	BOZ24Y
238	W19	SNP_INDEX[3]	OUT	BOZ24L
239	T15	SNP_INDEX[2]	OUT	BOZ24N
240	VDD	VDD	VDD	*****
241	VSS	VSS	VSS	*****
242	V18	SNP_INDEX[1]	OUT	BOZ24N
243	Y20	SNP_INDEX[0]	OUT	BOZ24L
244	V19	UPA_ADDRVAL1	OUT	BOZ24Y
245	U17	UPA_ADDRBUS1[28]	OUT	BBOZ24Y
246	VDD	VDD	VDD	*****
247	W20	UPA_ADDRBUS1[27]	OUT	BBOZ24Y
248	T18	UPA_ADDRBUS1[26]	OUT	BBOZ24Y
249	U18	UPA_ADDRBUS1[25]	OUT	BBOZ24Y
250	VSS	VSS	VSS	*****
251	T16	UPA_ADDRBUS1[24]	OUT	BBOZ24Y

TABLE 3: Pinout Table (Continued)

Bond pad	Ball pad	Signal Name	Type	I/O buffer
252	U19	UPA_ADDRBUS1[23]	OUT	BBOZ24Y
253	T17	UPA_ADDRBUS1[22]	OUT	BBOZ24Y
254	U20	UPA_ADDRBUS1[21]	OUT	BBOZ24Y
255	VDD	VDD	VDD	*****
256	R16	UPA_ADDRBUS1[20]	OUT	BBOZ24Y
257	T19	UPA_ADDRBUS1[19]	OUT	BBOZ24Y
258	R17	UPA_ADDRBUS1[18]	OUT	BBOZ24Y
259	VSS	VSS	VSS	*****
260	R19	UPA_ADDRBUS1[17]	OUT	BBOZ24Y
261	P16	UPA_ADDRBUS1[16]	OUT	BBOZ24Y
262	R18	UPA_ADDRBUS1[15]	OUT	BBOZ24Y
263	P17	UPA_ADDRBUS1[14]	OUT	BBOZ24Y
264	VDD	VDD	VDD	*****
265	R20	UPA_ADDRBUS1[13]	OUT	BBOZ24Y
266	P18	UPA_ADDRBUS1[12]	OUT	BBOZ24Y
267	N17	UPA_ADDRBUS1[11]	OUT	BBOZ24Y
268	VSS	VSS	VSS	*****
269	N18	UPA_ADDRBUS1[10]	OUT	BBOZ24Y
270	P19	UPA_ADDRBUS1[9]	OUT	BBOZ24Y
271	N19	UPA_ADDRBUS1[8]	OUT	BBOZ24Y
272	N20	UPA_ADDRBUS1[7]	OUT	BBOZ24Y
273	VDD	VDD	VDD	*****
274	M17	UPA_ADDRBUS1[6]	OUT	BBOZ24Y
275	M18	UPA_ADDRBUS1[5]	OUT	BBOZ24Y
276	L18	UPA_ADDRBUS1[4]	OUT	BBOZ24Y
277	VSS	VSS	VSS	*****
278	M19	UPA_ADDRBUS1[3]	OUT	BBOZ24Y
279	L20	UPA_ADDRBUS1[2]	OUT	BBOZ24Y
280	VDD	VDD	VDD	*****
281	L17	UPA_ADDRBUS1[1]	OUT	BBOZ24Y
282	K17	UPA_ADDRBUS1[0]	OUT	BBOZ24Y
283	L19	UPA_PREPLY3[1]	IN	PINA02Y
284	VSS	VSS	VSS	*****
285	K20	UPA_PREPLY3[0]	IN	PINA02Y
286	K19	UPA_PREPLY2[4]	IN	PINA02Y
287	J17	UPA_PREPLY2[3]	IN	PINA02Y

TABLE 3: Pinout Table (Continued)

Bond pad	Ball pad	Signal Name	Type	I/O buffer
288	VDD	VDD	VDD	*****
289	K18	UPA_PREPLY2[2]	IN	PINA02Y
290	H19	UPA_PREPLY2[1]	IN	PINA02Y
291	J19	UPA_PREPLY2[0]	IN	PINA02Y
292	J18	UPA_PREPLY1[4]	IN	PINA02Y
293	VSS	VSS	VSS	*****
294	H17	UPA_PREPLY1[3]	IN	PINA02Y
295	H20	UPA_PREPLY1[2]	IN	PINA02Y
296	H18	UPA_PREPLY1[1]	IN	PINA02Y
297	VDD	VDD	VDD	*****
298	G17	UPA_PREPLY1[0]	IN	PINA02Y
299	G19	UPA_PREPLY0[4]	IN	PINA02Y
300	G16	UPA_PREPLY0[3]	IN	PINA02Y
301	F18	UPA_PREPLY0[2]	IN	PINA02Y
302	VSS	VSS	VSS	*****
303	G18	UPA_PREPLY0[1]	IN	PINA02Y
304	F20	UPA_PREPLY0[0]	IN	PINA02Y
305	F16	BMXCMD1[3]	OUT	BOZ24Y
306	VDD	VDD	VDD	*****
307	F19	BMXCMD0[3]	OUT	BOZ24Y
308	E18	BMXCMD1[2]	OUT	BOZ24Y
309	D19	BMXCMD0[2]	OUT	BOZ24Y
310	F17	BMXCMD1[1]	OUT	BOZ24Y
311	VSS	VSS	VSS	*****
312	D20	BMXCMD0[1]	OUT	BOZ24Y
313	E19	BMXCMD1[0]	OUT	BOZ24Y
314	B20	BMXCMD0[0]	OUT	BOZ24Y
315	VDD	VDD	VDD	*****
316	E17	UPA_DATASTALL1	OUT	BOZ24Y
317	C19	UPA_DATASTALL0	OUT	BOZ24Y
318	B19	UPA_ECCVALID1	OUT	BOZ24L
319	E16	UPA_ECCVALID0	OUT	BOZ24N
320	VSS	VSS	VSS	*****

The following tables specify the coordinates for the 64 VDD ball numbers and the 64 VSS ball numbers. See *Figure 63* to determine the figurative representation of the coordinates herein listed in the VDD Ball Numbers table and the VSS Ball Numbers table.

VDD Ball Numbers

A5	A9	A14	A18	C1	E8	E9	E10
E11	E12	E13	E20	F8	F9	F10	F11
F12	F13	G1	H5	H6	H15	H16	J5
J6	J15	J16	J20	K5	K6	K15	K16
L5	L6	L15	L16	M1	M5	M6	M15
M16	N5	N6	N15	N16	P20	R8	R9
R10	R11	R12	R13	T1	T8	T9	T10
T11	T12	T13	V20	Y3	Y7	Y12	Y16

VSS Ball Numbers

A3	A7	A12	A16	C20	E1	F6	F7
F14	F15	G6	G15	G20	H8	H9	H10
H11	H12	H13	J1	J8	J9	J10	J11
J12	J13	K8	K9	K10	K11	K12	K13
L8	L9	L10	L11	L12	L13	M8	M9
M10	M11	M12	M13	M20	N8	N9	N10
N11	N12	N13	P1	P6	P15	R6	R7
R14	R15	T20	V1	Y5	Y9	Y14	Y18

STP2202ABGA

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